PATENT ASSIGNMENT COVER SHEET

Electronic Version v1.1
Stylesheet Version v1.2

EPAS ID: PAT4027325

SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT

CONVEYING PARTY DATA

Name	Execution Date
NATIONAL STARCH AND CHEMICAL INVESTMENT HOLDING CORPORATION	04/01/2008

RECEIVING PARTY DATA

Name:	HENKEL KGAA
Street Address:	HENKELSTRASSE 67
City:	DUESSELDORF
State/Country:	GERMANY
Postal Code:	40589

PROPERTY NUMBERS Total: 1

Property Type	Number
Application Number:	12105838

CORRESPONDENCE DATA

Fax Number: (860)571-5028

Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent using a fax number, if provided; if that is unsuccessful, it will be sent via US Mail.

Phone: (908) 243-2874
Email: PATENTS.MAILBOX@HENKEL.COM
Correspondent Name: HENKEL CORPORATION
Address Line 1: ONE HENKEL WAY
Address Line 4: ROCKY HILL, CONNECTICUT 06067

ATTORNEY DOCKET NUMBER:	N-2061D2.PSA-US
NAME OF SUBMITTER:	JOANNE GUTIERREZ
SIGNATURE:	/JOANNE GUTIERREZ/
DATE SIGNED:	08/29/2016

Total Attachments: 114
source=NSC to Henkel KGaA Assignment with Schedule 1 and TM Sched 2#page1.tif
source=NSC to Henkel KGaA Assignment with Schedule 1 and TM Sched 2#page2.tif
source=NSC to Henkel KGaA Assignment with Schedule 1 and TM Sched 2#page3.tif
source=NSC to Henkel KGaA Assignment with Schedule 1 and TM Sched 2#page4.tif
source=NSC to Henkel KGaA Assignment with Schedule 1 and TM Sched 2#page5.tif
source=NSC to Henkel KGaA Assignment with Schedule 1 and TM Sched 2#page6.tif

source=NSC to Henkel KGaA Assignment with Schedule 1 and TM Sched 2#page7.tif
source=NSC to Henkel KGaA Assignment with Schedule 1 and TM Sched 2#page8.tif
source=NSC to Henkel KGaA Assignment with Schedule 1 and TM Sched 2#page9.tif
source=NSC to Henkel KGaA Assignment with Schedule 1 and TM Sched 2#page10.tif
source=NSC to Henkel KGaA Assignment with Schedule 1 and TM Sched 2#page11.tif
source=NSC to Henkel KGaA Assignment with Schedule 1 and TM Sched 2#page12.tif
source=NSC to Henkel KGaA Assignment with Schedule 1 and TM Sched 2#page13.tif
source=NSC to Henkel KGaA Assignment with Schedule 1 and TM Sched 2#page14.tif
source=NSC to Henkel KGaA Assignment with Schedule 1 and TM Sched 2#page15.tif
source=NSC to Henkel KGaA Assignment with Schedule 1 and TM Sched 2#page16.tif
source=NSC to Henkel KGaA Assignment with Schedule 1 and TM Sched 2#page17.tif
source=NSC to Henkel KGaA Assignment with Schedule 1 and TM Sched 2#page18.tif
source=NSC to Henkel KGaA Assignment with Schedule 1 and TM Sched 2#page19.tif
source=NSC to Henkel KGaA Assignment with Schedule 1 and TM Sched 2#page20.tif
source=NSC to Henkel KGaA Assignment with Schedule 1 and TM Sched 2#page21.tif
source=NSC to Henkel KGaA Assignment with Schedule 1 and TM Sched 2#page22.tif
source=NSC to Henkel KGaA Assignment with Schedule 1 and TM Sched 2#page23.tif
source=NSC to Henkel KGaA Assignment with Schedule 1 and TM Sched 2#page24.tif
source=NSC to Henkel KGaA Assignment with Schedule 1 and TM Sched 2#page25.tif
source=NSC to Henkel KGaA Assignment with Schedule 1 and TM Sched 2#page26.tif
source=NSC to Henkel KGaA Assignment with Schedule 1 and TM Sched 2#page27.tif
source=NSC to Henkel KGaA Assignment with Schedule 1 and TM Sched 2#page28.tif
source=NSC to Henkel KGaA Assignment with Schedule 1 and TM Sched 2#page29.tif
source=NSC to Henkel KGaA Assignment with Schedule 1 and TM Sched 2#page30.tif
source=NSC to Henkel KGaA Assignment with Schedule 1 and TM Sched 2#page31.tif
source=NSC to Henkel KGaA Assignment with Schedule 1 and TM Sched 2#page32.tif
source=NSC to Henkel KGaA Assignment with Schedule 1 and TM Sched 2#page33.tif
source=NSC to Henkel KGaA Assignment with Schedule 1 and TM Sched 2#page34.tif
source=NSC to Henkel KGaA Assignment with Schedule 1 and TM Sched 2#page35.tif
source=NSC to Henkel KGaA Assignment with Schedule 1 and TM Sched 2#page36.tif
source=NSC to Henkel KGaA Assignment with Schedule 1 and TM Sched 2#page37.tif
source=NSC to Henkel KGaA Assignment with Schedule 1 and TM Sched 2#page38.tif
source=NSC to Henkel KGaA Assignment with Schedule 1 and TM Sched 2#page39.tif
source=NSC to Henkel KGaA Assignment with Schedule 1 and TM Sched 2#page40.tif
source=NSC to Henkel KGaA Assignment with Schedule 1 and TM Sched 2#page41.tif
source=NSC to Henkel KGaA Assignment with Schedule 1 and TM Sched 2#page42.tif
source=NSC to Henkel KGaA Assignment with Schedule 1 and TM Sched 2#page43.tif
source=NSC to Henkel KGaA Assignment with Schedule 1 and TM Sched 2#page44.tif
source=NSC to Henkel KGaA Assignment with Schedule 1 and TM Sched 2#page45.tif
source=NSC to Henkel KGaA Assignment with Schedule 1 and TM Sched 2#page46.tif
source=NSC to Henkel KGaA Assignment with Schedule 1 and TM Sched 2#page47.tif
source=NSC to Henkel KGaA Assignment with Schedule 1 and TM Sched 2#page48.tif
source=NSC to Henkel KGaA Assignment with Schedule 1 and TM Sched 2#page49.tif
source=NSC to Henkel KGaA Assignment with Schedule 1 and TM Sched 2#page50.tif
source=NSC to Henkel KGaA Assignment with Schedule 1 and TM Sched 2#page51.tif
source=NSC to Henkel KGaA Assignment with Schedule 1 and TM Sched 2#page52.tif
source=NSC to Henkel KGaA Assignment with Schedule 1 and TM Sched 2#page53.tif
source=NSC to Henkel KGaA Assignment with Schedule 1 and TM Sched 2#page54.tif

source=NSC to Henkel KGaA Assignment with Schedule 1 and TM Sched 2#page55.tif
source=NSC to Henkel KGaA Assignment with Schedule 1 and TM Sched 2#page56.tif
source=NSC to Henkel KGaA Assignment with Schedule 1 and TM Sched 2#page57.tif
source=NSC to Henkel KGaA Assignment with Schedule 1 and TM Sched 2#page58.tif
source=NSC to Henkel KGaA Assignment with Schedule 1 and TM Sched 2#page59.tif
source=NSC to Henkel KGaA Assignment with Schedule 1 and TM Sched 2#page60.tif
source=NSC to Henkel KGaA Assignment with Schedule 1 and TM Sched 2#page61.tif
source=NSC to Henkel KGaA Assignment with Schedule 1 and TM Sched 2#page62.tif
source=NSC to Henkel KGaA Assignment with Schedule 1 and TM Sched 2#page63.tif
source=NSC to Henkel KGaA Assignment with Schedule 1 and TM Sched 2#page64.tif
source=NSC to Henkel KGaA Assignment with Schedule 1 and TM Sched 2#page65.tif
source=NSC to Henkel KGaA Assignment with Schedule 1 and TM Sched 2#page66.tif
source=NSC to Henkel KGaA Assignment with Schedule 1 and TM Sched 2#page67.tif
source=NSC to Henkel KGaA Assignment with Schedule 1 and TM Sched 2#page68.tif
source=NSC to Henkel KGaA Assignment with Schedule 1 and TM Sched 2#page69.tif
source=NSC to Henkel KGaA Assignment with Schedule 1 and TM Sched 2#page70.tif
source=NSC to Henkel KGaA Assignment with Schedule 1 and TM Sched 2#page71.tif
source=NSC to Henkel KGaA Assignment with Schedule 1 and TM Sched 2#page72.tif
source=NSC to Henkel KGaA Assignment with Schedule 1 and TM Sched 2#page73.tif
source=NSC to Henkel KGaA Assignment with Schedule 1 and TM Sched 2#page74.tif
source=NSC to Henkel KGaA Assignment with Schedule 1 and TM Sched 2#page75.tif
source=NSC to Henkel KGaA Assignment with Schedule 1 and TM Sched 2#page76.tif
source=NSC to Henkel KGaA Assignment with Schedule 1 and TM Sched 2#page77.tif
source=NSC to Henkel KGaA Assignment with Schedule 1 and TM Sched 2#page78.tif
source=NSC to Henkel KGaA Assignment with Schedule 1 and TM Sched 2#page79.tif
source=NSC to Henkel KGaA Assignment with Schedule 1 and TM Sched 2#page80.tif
source=NSC to Henkel KGaA Assignment with Schedule 1 and TM Sched 2#page81.tif
source=NSC to Henkel KGaA Assignment with Schedule 1 and TM Sched 2#page82.tif
source=NSC to Henkel KGaA Assignment with Schedule 1 and TM Sched 2#page83.tif
source=NSC to Henkel KGaA Assignment with Schedule 1 and TM Sched 2#page84.tif
source=NSC to Henkel KGaA Assignment with Schedule 1 and TM Sched 2#page85.tif
source=NSC to Henkel KGaA Assignment with Schedule 1 and TM Sched 2#page86.tif
source=NSC to Henkel KGaA Assignment with Schedule 1 and TM Sched 2#page87.tif
source=NSC to Henkel KGaA Assignment with Schedule 1 and TM Sched 2#page88.tif
source=NSC to Henkel KGaA Assignment with Schedule 1 and TM Sched 2#page89.tif
source=NSC to Henkel KGaA Assignment with Schedule 1 and TM Sched 2#page90.tif
source=NSC to Henkel KGaA Assignment with Schedule 1 and TM Sched 2#page91.tif
source=NSC to Henkel KGaA Assignment with Schedule 1 and TM Sched 2#page92.tif
source=NSC to Henkel KGaA Assignment with Schedule 1 and TM Sched 2#page93.tif
source=NSC to Henkel KGaA Assignment with Schedule 1 and TM Sched 2#page94.tif
source=NSC to Henkel KGaA Assignment with Schedule 1 and TM Sched 2#page95.tif
source=NSC to Henkel KGaA Assignment with Schedule 1 and TM Sched 2#page96.tif
source=NSC to Henkel KGaA Assignment with Schedule 1 and TM Sched 2#page97.tif
source=NSC to Henkel KGaA Assignment with Schedule 1 and TM Sched 2#page98.tif
source=NSC to Henkel KGaA Assignment with Schedule 1 and TM Sched 2#page99.tif
source=NSC to Henkel KGaA Assignment with Schedule 1 and TM Sched 2#page100.tif
source=NSC to Henkel KGaA Assignment with Schedule 1 and TM Sched 2#page101.tif
source=NSC to Henkel KGaA Assignment with Schedule 1 and TM Sched 2#page102.tif

source=NSC to Henkel KGaA Assignment with Schedule 1 and TM Sched 2#page103.tif
source=NSC to Henkel KGaA Assignment with Schedule 1 and TM Sched 2#page104.tif
source=NSC to Henkel KGaA Assignment with Schedule 1 and TM Sched 2#page105.tif
source=NSC to Henkel KGaA Assignment with Schedule 1 and TM Sched 2#page106.tif
source=NSC to Henkel KGaA Assignment with Schedule 1 and TM Sched 2#page107.tif
source=NSC to Henkel KGaA Assignment with Schedule 1 and TM Sched 2#page108.tif
source=NSC to Henkel KGaA Assignment with Schedule 1 and TM Sched 2#page109.tif
source=NSC to Henkel KGaA Assignment with Schedule 1 and TM Sched 2#page110.tif
source=NSC to Henkel KGaA Assignment with Schedule 1 and TM Sched 2#page111.tif
source=NSC to Henkel KGaA Assignment with Schedule 1 and TM Sched 2#page112.tif
source=NSC to Henkel KGaA Assignment with Schedule 1 and TM Sched 2#page113.tif
source=NSC to Henkel KGaA Assignment with Schedule 1 and TM Sched 2#page114.tif

Dated 1 April 2008

(1) NATIONAL STARCH AND CHEMICAL INVESTMENT HOLDING CORPORATION

(2) INDOPCO, INC.

as Assignors

(3) HENKEL KGaA as Assignee

ASSIGNMENT OF CERTAIN PATENTS AND TRADE MARKS

MAYER • BROWN

LONDON

CONTENTS

Clause Page

Schedule

THIS AGREEMENT is dated 1 April 2008 and made between:

(1) **NATIONAL STARCH AND CHEMICAL INVESTMENT HOLDING CORPORATION**, a corporation incorporated under the laws of Delaware, USA whose principal place of business is at 1000 Uniqema Blvd., New Castle, DE 19720, USA ("**NSCIH**");

(2) **INDOPCO, INC.**, a Delaware corporation, ("**Indopco**") (including Indopco, Inc. d/b/a National Starch and Chemical Company);

NSCIH and Indopco each being an "**Assignor**" and together the "**Assignors**"; and

(3) **HENKEL KGaA** whose registered office is at Henkelstraße 67, 40589 Düsseldorf with number HRB 4724) (the "**Assignee**"),

BACKGROUND:

In connection with a sale and purchase agreement dated 13 August 2007 between Akzo Nobel N.V. and the Assignee (the "**Principal Agreement**"), the Assignors have agreed to assign certain Patents and Trade Marks owned by them to the Assignee on the terms set out below.

IT IS AGREED that:

1. DEFINITIONS AND INTERPRETATION

1.1 Defined terms

In this Agreement:

"**Patents**" means those patents and patent applications specified in Schedule 1 (*Patents*) (and shall include (i) any patents issuing from such patent applications, and (ii) any patents or patent applications claiming priority to them, in each case throughout the world); and

"**Trade Marks**" means those trade marks and trade mark applications specified in Schedule 2 (*Trade Marks*) (and shall include registered trade marks issuing from such applications, throughout the world).

1.2 Meaning of references

In this Agreement, unless the context requires otherwise, any reference to:

(a) this Agreement includes the Schedules, which form part of this Agreement for all purposes;

(b) any English statutory provision or English legal term for any action, remedy, method of judicial proceeding, document, legal status, court, official or other legal concept or thing shall in respect of any jurisdiction other than England be deemed to include what most nearly approximates in that jurisdiction to the English statutory provision or English legal term;

(c) £ or sterling is to the lawful currency from time to time of the United Kingdom; and

(d) $ or dollars is the lawful currency from time to time of the United States of America.

1.3 Headings and table of contents

In this Agreement, the table of contents and headings are included for convenience only and shall not affect the interpretation or construction of this Agreement.

1.4 No restrictive interpretations

In this Agreement, general words shall not be given a restrictive interpretation by reason of their being preceded or followed by words indicating a particular class of acts, matters or things.

2. ASSIGNMENT

2.1 Assignment of Patents and Trade Marks

$50 ~~£25,767,428.63~~

In consideration of the sum of ~~$50~~ million paid by the Assignee to NSCIH and the sum of £1 paid by the Assignee to Indopco, in each case paid in accordance with Clause 2.2 (*Payment details*), the receipt and adequacy of which the Assignors now acknowledge, each Assignor hereby assigns to the Assignee, effective as of 1 April 2008 New York time:

(a) all its right, title and interest in and to the Patents listed against its name (in the case of NSCIH, its name being indicated by the code "NIHC" and in the case of Indopco, its name being indicated by the code "INNS"), in Schedule 1 (*Patents*); and

(b) all its right, title and interest in and to the Trade Marks listed against its name (using the codes mentioned in sub-clause (a)), in Schedule 2 (*Trade Marks*) together with all goodwill inherent in such Trade Marks but no other or greater goodwill,

to hold unto the Assignee absolutely. The rights agreed to be so assigned include the right to sue for, and to recover any damages and other remedies in respect of, any past, present or future infringement of the Patents and/or of the Trade Marks and to fully stand in place of each Assignor in all matters relating to the Patents and Trade Marks. The Assignee grants to the Assignors an exclusive licence of the Patents and Trade Marks assigned to it, for itself and for Akzo Nobel N.V. and its other subsidiaries and subsidiary undertakings, to use the same for all purposes. This licence shall be irrevocable and shall remain in effect until Completion (as defined in Clause 2.3 (*Obligation to re-transfer*)) occurs, or until the re-assignment provided for in Clause 2.3 takes place, as the case may be.

2.2 Payment details

Payment of the consideration shall be made in accordance with the instructions already provided to the Assignee.

2.3 Obligation to re-transfer

If Completion (as defined in the Principal Agreement, but other than in relation to any business in respect of which the parties to the Principal Agreement agree that Completion is to be deferred) has not occurred on or before 16 April 2008, the Assignee shall promptly re-assign to each of the Assignors (or as they shall direct) the Patents and Trade Marks respectively assigned by each of them hereunder and the Assignors shall repay to the Assignee all consideration received by them under this Agreement. The Assignee therefore undertakes not to transfer any interest in or title to, or encumber, or grant any licence or right in respect of, any of the Patents and Trade Marks to any third party until Completion has occurred.

they promptly

3. FURTHER ASSURANCE

The Assignors will, at the Assignee's request and expense, promptly execute all documents and deeds which the Assignee considers are necessary or desirable for giving full effect to and the proper recordation of any assignment executed in accordance with Clause 2 (*Assignment*).

4. GOVERNING LAW AND JURISDICTION

4.1 Governing law

This Agreement shall be governed by and construed in accordance with English law.

4.2 Jurisdiction

Each party irrevocably submits to the exclusive jurisdiction of the English courts to settle any dispute which may arise under or in connection with this Agreement or the legal relationships established by this Agreement.

EXECUTION:

The parties have shown their acceptance of the terms of this Agreement by executing it after the Schedules.

SCHEDULE 1

PATENTS

WORLDWIDE PATENTS, FILED ON OR AFTER JULY 10, 2001

Docket No.	Ctry	Division	App Date	App No	Grant Dt	Pat No.	Exp Dt	Current Owner
1734A	HONG	EEM	18OC2006	02103421.1	08DE2006	1041712	10AP2021	NIHC
DIE ATTACH ADHESIVES FOR USE IN MICROELECTRONIC DEVICES								
1734RX	USA	EEM	16JE2004	90/007,084	27SE2005	B-6,265,530	02JL2018	NIHC
DIE ATTACH ADHESIVES FOR USE IN MICROELECTRONIC DEVICES								
1736D	HONG	EEM	11JA2007	04108689.5	09MR2007	HK1065814	30JE2019	NIHC
PACKAGE ENCAPSULANT COMPOSITIONS FOR USE IN ELECTRONIC DEVICES								
1736D1	KORS	EEM	20FE2006	10-2006-0016236	09AU2006	0613214	02JL2019	NIHC
PACKAGE ENCAPSULANT COMPOSITIONS FOR USE IN ELECTRONIC DEVICES								
1736D2	KORS	EEM	20FE2006	10-2006-0016237	09AU2006	0613215	02JL2019	NIHC
PACKAGE ENCAPSULANT COMPOSITIONS FOR USE IN ELECTRONIC DEVICES								
1749A	USA	A	21DE2001	10/026,017	23OC2007	7,285,600	02FE2019	NIHC
NOVEL REAGENTS FOR HEAT ACTIVATED POLYMER CROSSLINKING								
1779B	USA	A	08AU2005	11/199,324				NIHC
USE OF FOAMED ADHESIVES TO MAKE PAPER CORES OR TUBES								
1805A	JAPA	EEM	08FE2002	2002-32530				NIHC
CONDUCTIVE AND RESISTIVE MATERIALS WITH ELECTICAL STABILITY FOR USE IN ELECTRONICS DEVICES								
1805A	KORS	EEM	08FE2002	2002-0007383				NIHC
CONDUCTIVE AND RESISTIVE MATERIALS WITH ELECTICAL STABILITY								

```
FOR USE IN ELECTRONICS DEVICES

1805A         MAYS  EEM        08FE2002   PI 20020450        31MY2006   MY-122956-A  08FE2022     NIHC
CONDUCTIVE AND RESISTIVE MATERIALS WITH ELECTICAL STABILITY
FOR USE IN ELECTRONICS DEVICES

1805A         PHIL  EEM        08FE2002   1-2002-00092       22NO2005   1-2002-00092 08FE2022     NIHC
CONDUCTIVE AND RESISTIVE MATERIALS WITH ELECTICAL STABILITY
FOR USE IN ELECTRONICS DEVICES

1805A         TAIW  EEM        08FE2002   91102863           01OC2005   240747       07FE2022     NIHC
CONDUCTIVE AND RESISTIVE MATERIALS WITH ELECTICAL STABILITY
FOR USE IN ELECTRONICS DEVICES

1805A         THAI  EEM        08FE2002   071661                                                  NIHC
CONDUCTIVE AND RESISTIVE MATERIALS WITH ELECTICAL STABILITY
FOR USE IN ELECTRONICS DEVICES

1824          HONG  EEM        24MY2002   02103909.2         08SE2006   HK1042107    16MY2021     NIHC
CURABLE ELECTRON DONOR COMPOUNDS

1824A         USA   EEM        03AU2001   09/922,187         21JE2005   6,908,957    18DE2021     NIHC
CURABLE ELECTRON DONOR COMPOUNDS

1824A/D       USA   EEM        18OC2004   10/967,493         05FE2008   7,326,746    27JE2021     NIHC
CURABLE ELECTRON DONOR COMPOUNDS

1828D         ASTL  A          03MR2005   2005200967                                              NIHC
HIGH GREEN STRENGTH REACTIVE HOT MELT BY A PREPOLYMERIZATION
STEP IN THE MAIN REACTOR

1849          HONG  EEM        04JE2002   02104240.8                                              NIHC
CURABLE HYBRID ELECTRON DONOR COMPOUNDS CONTAINING VINYL
ETHER

1849D         CHIN  EEM        22NO2007   200710169325.2                                          NIHC
CURABLE HYBRID ELECTRON DONOR COMPOUNDS CONTAINING VINYL
```

```
ETHER


1852          HONG  EEM        17AU2005   02104280.9        07OC2005   HK1042492    17MY2021     NIHC
COMPOUNDS WITH ELECTRON DONOR AND ELECTRON ACCEPTOR
FUNCTIONALITY


1853A.TDM     USA   A          17JL2001   09/907,413        30NO2004   6,824,792    11FE2020     NIHC
BIOADHESIVE COMPOSITION


1861          HONG  EEM        28MY2002   02103967.1        22JL2005   HK1042316    16MY2021     NIHC
DIE ATTACH ADHESIVES WITH VINYL ETHER AND CARBAMATE OR UREA
FUNCTIONALITY


1861A         USA   EEM        10AU2001   09/927,242        02MR2004   6,699,929    04MY2021     NIHC
DIE ATTACH ADHESIVES WITH VINYL ETHER AND CARBAMATE OR UREA
FUNCTIONALITY


1862          HONG  EEM        28MY2002   02103965.3        25AU2006   HK1042315    17MY2021     NIHC
ADHESION PROMOTERS CONTAINING SILANE, CARBAMATE OR UREA, AND
DONOR OR ACCEPTOR FUNCTIONALITY


1868          EPC   A          18MR2002   02 006 509.0      16MY2006   1347038      18MR2022     NIHC
CLEANING COMPOSITION FOR REMOVING ADHESIVES


1868          FRAN  A          18MR2002   02 006 509.0      16MY2006   1347038      18MR2022     NIHC
CLEANING COMPOSITION FOR REMOVING ADHESIVES


1868          GBRI  A          18MR2002   02 006 509.0      16MY2006   1347038      18MR2022     NIHC
CLEANING COMPOSITION FOR REMOVING ADHESIVES


1868          GERM  A          18MR2002   02 006 509.0      16MY2006   60220135.7-0818MR2022     NIHC
CLEANING COMPOSITION FOR REMOVING ADHESIVES


1869          HONG  EEM        10JL2005   02105140.6        04NO2005   HK1043382    05JL2021     NIHC
DIE ATTACH ADHESIVES WITH EPOXY RESIN HAVING ALLYL OR VINYL
GROUPS
```

```
1893           USA   A          18SE2001   09/955,644                                               NIHC
NON-REACTIVE ADHESIVE USEFUL IN TRANSDERMAL DRUG DELIVERY
SYSTEMS


1893           EPC   A          18SE2001   01 973 175.1                                             NIHC
NON-REACTIVE ADHESIVE USEFUL IN TRANSDERMAL DRUG DELIVERY
SYSTEMS


1893           JAPA  A          18SE2001   2002-528194                                              NIHC
NON-REACTIVE ADHESIVE USEFUL IN TRANSDERMAL DRUG DELIVERY
SYSTEMS


1893           KORS  A          18SE2001   2003-7003644                                             NIHC
NON-REACTIVE ADHESIVE USEFUL IN TRANSDERMAL DRUG DELIVERY
SYSTEMS


1893           TAIW  A          19SE2001   90124224                                                 NIHC
NON-REACTIVE ADHESIVE USEFUL IN TRANSDERMAL DRUG DELIVERY
SYSTEMS


1905           ASTL  A          31OC2001   2002249785       02AU2007   2002249785   31OC2021     NIHC
PACKAGING OF LOW APPLICATION HOT MELT ADHESIVE FORMULATIONS


1905           CANA  A          31OC2001   2,448,664                                                NIHC
PACKAGING OF LOW APPLICATION HOT MELT ADHESIVE FORMULATIONS


1905           CHIN  A          31OC2001   01821676.5                                               NIHC
PACKAGING OF LOW APPLICATION HOT MELT ADHESIVE FORMULATIONS


1905           EPC   A          31OC2001   01 998 023.4                                             NIHC
PACKAGING OF LOW APPLICATION HOT MELT ADHESIVE FORMULATIONS


1905           JAPA  A          31OC2001   2002-561570                                              NIHC
PACKAGING OF LOW APPLICATION HOT MELT ADHESIVE FORMULATIONS


1905           KORS  A          31OC2001   2003-7006110                                             NIHC
```

```
PACKAGING OF LOW APPLICATION HOT MELT ADHESIVE FORMULATIONS


1905D          USA   A          27FE2003   10/375,270                                            NIHC
PACKAGING OF LOW APPLICATION HOT MELT ADHESIVE FORMULATIONS



1906           CHIN  EEM        14NO2001   01138495.6         02AU2006   ZL01138495.6 14NO2021     NIHC
CONDUCTIVE INK COMPOSITION



1906           EPC   EEM        13NO2001   01 126 523.8                                          NIHC
CONDUCTIVE INK COMPOSITION



1906           JAPA  EEM        14NO2001   2001-348318                                           NIHC
CONDUCTIVE INK COMPOSITION



1906           KORS  EEM        13NO2001   2001-0070497                                          NIHC
CONDUCTIVE INK COMPOSITION



1906           MAYS  EEM        13NO2001   PI 20015218        30AU2004   MY-117791-A  13NO2021     NIHC
CONDUCTIVE INK COMPOSITION


1906           PHIL  EEM        13NO2001   1-2001-02480       07AP2006   1-2001-02480 13NO2021     NIHC
CONDUCTIVE INK COMPOSITION


1906           SING  EEM        13NO2001   200107088-7                                           NIHC
CONDUCTIVE INK COMPOSITION


1911           CHIN  EEM        11DE2001   01143158.X         06SE2006   ZL01143158.X 11DE2021     NIHC
NOVEL HIGH TEMPERATURE UNDERFILLING MATERIAL WITH LOW
EXOTHERM DURING USE


1911           MAYS  EEM        10DE2001   PI 20015599        31OC2006   MY-126833-A  10DE2021     NIHC
NOVEL HIGH TEMPERATURE UNDERFILLING MATERIAL WITH LOW
```

```
EXOTHERM DURING USE


Docket No.     Ctry  Division    App Date   App No              Grant Dt   Pat No.      Exp Dt       Current Owner
------ ---     ----  --------    --- ----   --- --              ----- --   --- ---      --- --       ------- -----
1911           SING  EEM         10DE2001   200107806-2         30SE2005    96671       10DE2021     NIHC
NOVEL HIGH TEMPERATURE UNDERFILLING MATERIAL WITH LOW
EXOTHERM DURING USE


1911           TAIW  EEM         10DE2001   90130731            21DE2004   225507       09DE2021     NIHC
NOVEL HIGH TEMPERATURE UNDERFILLING MATERIAL WITH LOW
EXOTHERM DURING USE


1912           EPC   A           20DE2001   01 991 376.3                                             NIHC
HOT MELT ADHESIVES FOR DERMAL APPLICATION


1912           JAPA  A           20DE2001   2002-554146                                              NIHC
HOT MELT ADHESIVES FOR DERMAL APPLICATION


1912           TAIW  A           24DE2001   90132119                                                 NIHC
HOT MELT ADHESIVES FOR DERMAL APPLICATION


1917.ADH       EPC   A           05FE2002   02 704 348.8                                             NIHC
HOT MELT ADHESIVE COMPOSITION


1922.PSA       ASTL  A           25MR2002   2002303289                                               NIHC
RUBBER-ACRYLIC ADHESIVE FORMULATION


1922.PSA       CHIN  A           25MR2002   02828619.7                                               NIHC
RUBBER-ACRYLIC ADHESIVE FORMULATION


1922.PSA       GBRI  A           25MR2002   0421207.2           07DE2005   2402394      25MR2022     NIHC
RUBBER-ACRYLIC ADHESIVE FORMULATION


1922.PSA       GERM  A           25MR2002   102 97 685.6                                             NIHC
RUBBER-ACRYLIC ADHESIVE FORMULATION
```

```
1922.PSA       JAPA  A          25MR2002   2003-580443                                                NIHC
RUBBER-ACRYLIC ADHESIVE FORMULATION


1922.PSA       KORS  A          25MR2002   10-2004-7015145                                            NIHC
RUBBER-ACRYLIC ADHESIVE FORMULATION


1922D.PSA      USA   A          13FE2003   10/366,029         30DE2003   6,670,417    16MR2021      NIHC
RUBBER-ACRYLIC ADHESIVE FORMULATION


1925.EEM       CHIN  EEM        22MR2002   02812751.X                                                 NIHC
CONDUCTIVE MATERIALS WITH ELECTRICAL STABILITY FOR USE IN
ELECTRONICS DEVICES


1925.EEM       GBRI  EEM        22MR2002   0329810.6          15JE2005   2,393,442    22MR2022      NIHC
CONDUCTIVE MATERIALS WITH ELECTRICAL STABILITY FOR USE IN
ELECTRONICS DEVICES


1925.EEM       JAPA  EEM        22MR2002   2002-586361                                                NIHC
CONDUCTIVE MATERIALS WITH ELECTRICAL STABILITY FOR USE IN
ELECTRONICS DEVICES


1925D.EEM      GBRI  EEM        16NO2004   0425236.7          15JE2005   2,407,578    22MR2022      NIHC
CONDUCTIVE MATERIALS WITH ELECTRICAL STABILITY FOR USE IN
ELECTRONICS DEVICES


1927.BKB       CANA  A          23AP2002   2,445,446                                                  NIHC
CURABLE HOT MELT ADHESIVES FOR CASEMAKING


1927.BKB       EPC   A          23AP2002   02 731 490.5                                               NIHC
CURABLE HOT MELT ADHESIVES FOR CASEMAKING


1927.BKB       JAPA  A          23AP2002   2002-585213                                                NIHC
CURABLE HOT MELT ADHESIVES FOR CASEMAKING


1929.EEM       CANA  EEM        17JE2002   2,390,804                                                  NIHC
CATHODE COATING DISPERSION
```

```
1929.EEM      EPC   EEM        17JE2002   02 013 501.8                                         NIHC
CATHODE COATING DISPERSION

1929.EEM      JAPA  EEM        20JE2002   2002-179918                                          NIHC
CATHODE COATING DISPERSION

1929.EEM      KORS  EEM        17JE2002   2002-0033676                                         NIHC
CATHODE COATING DISPERSION

1929.EEM      SING  EEM        20JE2002   200203762-0       30DE2005   106074       20JE2022   NIHC
CATHODE COATING DISPERSION

1929.EEM      TAIW  EEM        21JE2002   91113721                                             NIHC
CATHODE COATING DISPERSION

1930.EEM      ATRA  EEM        17JE2002   02 013 502.6      24AU2005   E 302 806    17JE2022   NIHC
SOLVENT-BASED PROCESS FOR MANUFACTURING LATENT CURING
CATALYSTS

1930.EEM      BELG  EEM        17JE2002   02 013 502.6      24AU2005   1270635      17JE2022   NIHC
SOLVENT-BASED PROCESS FOR MANUFACTURING LATENT CURING
CATALYSTS

1930.EEM      EPC   EEM        17JE2002   02 013 502.6      24AU2005   1270635      17JE2022   NIHC
SOLVENT-BASED PROCESS FOR MANUFACTURING LATENT CURING
CATALYSTS

1930.EEM      FRAN  EEM        17JE2002   02 013 502.6      24AU2005   1270635      17JE2022   NIHC
SOLVENT-BASED PROCESS FOR MANUFACTURING LATENT CURING
CATALYSTS

1930.EEM      GBRI  EEM        17JE2002   02 013 502.6      24AU2005   1270635      17JE2022   NIHC
SOLVENT-BASED PROCESS FOR MANUFACTURING LATENT CURING
CATALYSTS

1930.EEM      GERM  EEM        17JE2002   02 013 502.6      24AU2005   60205681.0   17JE2022   NIHC
```

SOLVENT-BASED PROCESS FOR MANUFACTURING LATENT CURING CATALYSTS								
1930.EEM	IREL	EEM	17JE2002	02 013 502.6	24AU2005	1270635	17JE2022	NIHC
SOLVENT-BASED PROCESS FOR MANUFACTURING LATENT CURING CATALYSTS								
1930.EEM	ITAL	EEM	17JE2002	02 013 502.6	24AU2005	1270635	17JE2022	NIHC
SOLVENT-BASED PROCESS FOR MANUFACTURING LATENT CURING CATALYSTS								
1930.EEM	JAPA	EEM	20JE2002	2002-180082	07SE2007	4,008,768	20JE2022	NIHC
SOLVENT-BASED PROCESS FOR MANUFACTURING LATENT CURING CATALYSTS								
1930.EEM	NETH	EEM	17JE2002	02 013 502.6	24AU2005	1270635	17JE2022	NIHC
SOLVENT-BASED PROCESS FOR MANUFACTURING LATENT CURING CATALYSTS								
1932.BDG	EPC	A	11JE2002	02 739 813.0				NIHC
REACTIVE HOT MELT ADHESIVE								
1933.BDM	EPC	A	11JE2002	02 734 763.2				NIHC
REACTIVE HOT MELT ADHESIVE								
1933.BDM	TAIW	A	14JE2002	91113108	21MR2005	229689	13JE2022	NIHC
REACTIVE HOT MELT ADHESIVE								
1935.PSA	ASTL	A	24JE2002	2002352190				NIHC
RADIATION CURABLE ADHESIVE								
1935.PSA	CANA	A	24JE2002	2,421,045				NIHC
RADIATION CURABLE ADHESIVE								
1935.PSA	EPC	A	24JE2002	02 780 954.0				NIHC
RADIATION CURABLE ADHESIVE								

1935.PSA	JAPA	A	24JE2002	2003-509049				NIHC
RADIATION CURABLE ADHESIVE								
1935.PSA	TAIW	A	25JE2002	91113970				NIHC
RADIATION CURABLE ADHESIVE								
1939.BDG	TAIW	A	06JL2002	91115500	21DE2005	245777	05JL2022	NIHC
REACTIVE HOT MELT ADHESIVE								
1940.BDG	TAIW	A	06JL2002	91115509				NIHC
REACTIVE HOT MELT ADHESIVE								
1941.PKG	ASTL	A	15AU2002	2002323199				NIHC
REACTIVATABLE ADHESIVES								
1941.PKG	EPC	A	15AU2002	02 757 164.5				NIHC
REACTIVATABLE ADHESIVES								
1941.PKG	JAPA	A	15AU2002	2003-521731				NIHC
REACTIVATABLE ADHESIVES								
1944.NVF	SPAI	A	28JE2002	200450010(7)				NIHC
FIRE RETARDANT FOAM AND GEL COMPOSITIONS								
1944D.NVF	USA	A	02SE2004	10/932,454	25AP2006	7,033,526	24AU2021	NIHC
FIRE RETARDANT FOAM AND GEL COMPOSITIONS								
1945.BDG	USA	A	27JL2001	09/916,779				NIHC
FOAMED ADHESIVE AND USE THEREOF								
1945.BDG	JAPA	A	23JL2002	2003-517174				NIHC
FOAMED ADHESIVE AND USE THEREOF								
1946.BDG	CANA	A	31MR2003	2,449,110				NIHC

```
FOAMABLE ADHESIVE AND USE THEREOF

1951.PSA       USA   A          28AU2001   09/941,162         19OC2004   6,805,954    28AU2021     NIHC
TACKIFIED ACRYLIC PRESSURE SENSITIVE ADHESIVE

1951.PSA       EPC   A          22AU2002   02 757 307.0                                            NIHC
TACKIFIED ACRYLICS FOR PRESSURE SENSITIVE APPLICATIONS

1960A.TDM      USA   A          19MR2002   10/100,260                                              NIHC
FILMS CONTAINING STARCH

1960A.TDM      CANA  A          15NO2002   2,411,889                                               NIHC
FILMS CONTAINING STARCH

1960A.TDM      CHIN  A          18NO2002   02151344.9                                              NIHC
FILMS CONTAINING STARCH

1960A.TDM      EPC   A          15NO2002   02 025 575.8                                            NIHC
FILMS CONTAINING STARCH

1960A.TDM      JAPA  A          15NO2002   2002-331954                                             NIHC
FILMS CONTAINING STARCH

1960A.TDM      MEXI  A          15NO2002   PA/a/2002/011337   10JA2008   253237       15NO2022     NIHC
FILMS CONTAINING STARCH

1962.EEM       USA   EEM        28SE2001   09/966,453         16AU2005   6,930,136    01JA2023     NIHC
ADHESION PROMOTERS CONTAINING BENZOTRIAZOLES

1963.EEM       USA   EEM        28SE2001   09/966,449         27AU2002   6,441,121    28SE2021     NIHC
EPOXY COMPOUNDS CONTAINING STYRENIC OR CINNAMYL
FUNCTIONALITY

1963.EEM       JAPA  EEM        01JL2002   2003-532484                                             NIHC
EPOXY COMPOUNDS CONTAINING STYRENIC OR CINNAMYL
FUNCTIONALITY
```

```
1963.EEM       KORS  EEM        01JL2002   2004-7004000                                                 NIHC
EPOXY COMPOUNDS CONTAINING STYRENIC OR CINNAMYL
FUNCTIONALITY


1963.EEM       TAIW  EEM        27SE2002   91122783                                                     NIHC
EPOXY COMPOUNDS CONTAINING STYRENIC OR CINNAMYL
FUNCTIONALITY


1964.EEM       USA   EEM        28SE2001   09/966,448         27MY2003   6,570,032    28SE2021      NIHC
COMPOUNDS CONTAINING VINYL SILANE AND ELECTRON DONOR OR
ACCEPTOR FUNCTIONALITY


1964.EEM       CHIN  EEM        27FE2003   03106642.9         16AU2006   ZL03106642.9 27FE2023      NIHC
COMPOUNDS CONTAINING VINYL SILANE AND ELECTRON DONOR OR
ACCEPTOR FUNCTIONALITY


1964.EEM       JAPA  EEM        13FE2003   2003-35049         03AU2007   3,993,518    13FE2023      NIHC
COMPOUNDS CONTAINING VINYL SILANE AND ELECTRON DONOR OR
ACCEPTOR FUNCTIONALITY


1964.EEM       KORS  EEM        29JA2003   2003-0005755                                                 NIHC
COMPOUNDS CONTAINING VINYL SILANE AND ELECTRON DONOR OR
ACCEPTOR FUNCTIONALITY


1965.EEM       USA   EEM        28SE2001   09/966,454         08JL2003   6,590,018    28SE2021      NIHC
VINYL SILANE COMPOUNDS CONTAINING EPOXY FUNCTIONALITY


1965.EEM       JAPA  EEM        01JL2002   2003-532503                                                  NIHC
VINYL SILANE COMPOUNDS CONTAINING EPOXY FUNCTIONALITY


1965.EEM       KORS  EEM        01JL2002   2004-7004001                                                 NIHC
VINYL SILANE COMPOUNDS CONTAINING EPOXY FUNCTIONALITY


1965.EEM       TAIW  EEM        27SE2002   91122782                                                     NIHC
VINYL SILANE COMPOUNDS CONTAINING EPOXY FUNCTIONALITY
```

1967.PKG	USA	A	03OC2001	09/969,893				NIHC
WATER-BASED BOTTLE LABELING ADHESIVE								
1967.PKG	EPC	A	02OC2002	02 768 939.7				NIHC
WATER-BASED BOTTLE LABELING ADHESIVE								
1970.BKB	USA	A	24OC2001	10/000,763				NIHC
BOOKBINDING PROCESS								
1970.BKB	CANA	A	21OC2002	2,464,680				NIHC
BOOKBINDING PROCESS								
1970.BKB	EPC	A	21OC2002	02 784 197.2				NIHC
BOOKBINDING PROCESS								
1970.BKB	JAPA	A	21OC2002	2003-537940				NIHC
BOOKBINDING PROCESS								
1971.EEM	USA	EEM	06NO2001	09/993,589	11JA2005	6,841,647	06NO2021	NIHC
FLUID RESISTANT SILICONE ENCAPSULANT								
1971.EEM	EPC	EEM	05NO2002	02 024 594.0				NIHC
FLUID RESISTANT SILICONE ENCAPSULANT								
1971.EEM	JAPA	EEM	01NO2002	2002-319501				NIHC
FLUID RESISTANT SILICONE ENCAPSULANT								
1971A.EEM	USA	EEM	08JA2004	10/753,293	03AP2007	7,199,206	03FE2023	NIHC
FLUID RESISTANT SILICONE ENCAPSULANT								
1971D.EEM	EPC	EEM	15FE2006	06 003 011.1				NIHC
FLUID RESISTANT SILICONE ENCAPSULANT								
1971D1.EEM	USA	EEM	29JL2004	10/901,713	10JL2007	7,241,852	06NO2021	NIHC
FLUID RESISTANT SILICONE ENCAPSULANT								

```
1971D2.EEM     USA   EEM         29JL2004   10/901,699         25SE2007   7,273,916    18DE2022     NIHC
FLUID RESISTANT SILICONE ENCAPSULANT

1972.EEM       USA   EEM         23OC2001   10/040,674         16SE2003   6,620,651    14DE2021     NIHC
ADHESIVE WAFERS FOR DIE ATTACH APPLICATION

1972.EEM       CHIN  EEM         02OC2002   02821011.5         07MR2007   ZL02821011.5 02OC2022     NIHC
ADHESIVE WAFERS FOR DIE ATTACH APPLICATION

1972.EEM       EPC   EEM         02OC2002   02 802 114.5                                            NIHC
ADHESIVE WAFERS FOR DIE ATTACH APPLICATION

1972.EEM       JAPA  EEM         02OC2002   2003-539100                                             NIHC
ADHESIVE WAFERS FOR DIE ATTACH APPLICATION


1972.EEM       KORS  EEM         02OC2002   2004-7005919                                            NIHC
ADHESIVE WAFERS FOR DIE ATTACH APPLICATION

1972.EEM       SING  EEM         02OC2002   200401773-7        29AP2005   103171       02OC2022     NIHC
ADHESIVE WAFERS FOR DIE ATTACH APPLICATION

1972.EEM       TAIW  EEM         18OC2002   91124154           11OC2004   204424       17OC2022     NIHC
ADHESIVE WAFERS FOR DIE ATTACH APPLICATION

1974.PKG       USA   A           09NO2001   10/053,497                                              NIHC
ADHESIVE FOR DIFFICULT TO BOND SUBSTRATES

1974.PKG       BELG  A           07NO2002   02 784 418.2       16JA2008   1442091      07NO2022     NIHC
ADHESIVE FOR DIFFICULT TO BOND SUBSTRATES

1974.PKG       EPC   A           07NO2002   02 784 418.2       16JA2008   1442091      07NO2022     NIHC
ADHESIVE FOR DIFFICULT TO BOND SUBSTRATES

1974.PKG       FINL  A           07NO2002   02 784 418.2       16JA2008   1442091      07NO2022     NIHC
```

```
ADHESIVE FOR DIFFICULT TO BOND SUBSTRATES

1974.PKG       FRAN  A          07NO2002   02 784 418.2       16JA2008   1442091      07NO2022     NIHC
ADHESIVE FOR DIFFICULT TO BOND SUBSTRATES

1974.PKG       GBRI  A          07NO2002   02 784 418.2       16JA2008   1442091      07NO2022     NIHC
ADHESIVE FOR DIFFICULT TO BOND SUBSTRATES

1974.PKG       GERM  A          07NO2002   02 784 418.2       16JA2008   60224697.0-0807NO2022     NIHC
ADHESIVE FOR DIFFICULT TO BOND SUBSTRATES

1974.PKG       ITAL  A          07NO2002   02 784 418.2       16JA2008   1442091      07NO2022     NIHC
ADHESIVE FOR DIFFICULT TO BOND SUBSTRATES

1974.PKG       NETH  A          07NO2002   02 784 418.2       16JA2008   1442091      07NO2022     NIHC
ADHESIVE FOR DIFFICULT TO BOND SUBSTRATES

1974.PKG       SPAI  A          07NO2002   02 784 418.2       16JA2008   1442091      07NO2022     NIHC
ADHESIVE FOR DIFFICULT TO BOND SUBSTRATES

1974.PKG       SWED  A          07NO2002   02 784 418.2       16JA2008   1442091      07NO2022     NIHC
ADHESIVE FOR DIFFICULT TO BOND SUBSTRATES

1974.PKG       TURK  A          07NO2002   02 784 418.2       16JA2008   1442091      07NO2022     NIHC
ADHESIVE FOR DIFFICULT TO BOND SUBSTRATES

1975.BDG       USA   A          15NO2001   10/002,459         15JE2004   6,749,705    29JE2022     NIHC
ADHESIVE AND USE THEREOF

1976.EEM       USA   EEM        29MR2002   10/113,059         12OC2004   6,803,406    29MR2022     NIHC
ELECTRON DONORS, ELECTRON ACCEPTORS AND ADHESION PROMOTERS
CONTAINING DISULFIDE

1976.EEM       EPC   EEM        03MR2003   03 746 036.7                                            NIHC
ELECTRON DONORS, ELECTRON ACCEPTORS AND ADHESION PROMOTERS
CONTAINING DISULFIDE
```

1977.EEM	USA	EEM	23FE2002	10/080,738	16SE2003	6,620,905	23FE2022	NIHC	CURABLE COMPOSITIONS CONTAINING BENZOXAZINE
1977.EEM	EPC	EEM	10JA2003	03 702 069.0				NIHC	CURABLE COMPOSITIONS CONTAINING BENZOXAZINE
1977.EEM	TAIW	EEM	21FE2003	92103743	21NO2005	243834	20FE2023	NIHC	CURABLE COMPOSITIONS CONTAINING BENZOXAZINE
1978.EEM	CHIN	EEM	19NO2002	02824886.4	24JA2007	ZL02824886.4	19NO2022	NIHC	DUAL CURE B-STAGEABLE ADHESIVE FOR DIE ATTACH
1978.EEM	EPC	EEM	19NO2002	02 793 971.9				NIHC	DUAL CURE B-STAGEABLE ADHESIVE FOR DIE ATTACH
1978.EEM	HONG	EEM	13JE2005	05104927.5	14SE2007	1072067	18NO2022	NIHC	DUAL CURE B-STAGEABLE ADHESIVE FOR DIE ATTACH
1978.EEM	JAPA	EEM	19NO2002	2003-552885				NIHC	DUAL CURE B-STAGEABLE ADHESIVE FOR DIE ATTACH
1978.EEM	KORS	EEM	19NO2002	2004-7008824				NIHC	DUAL CURE B-STAGEABLE ADHESIVE FOR DIE ATTACH
1978.EEM	SING	EEM	19NO2002	200402099-6	31AU2006	104402	19NO2022	NIHC	DUAL CURE B-STAGEABLE ADHESIVE FOR DIE ATTACH
1978.EEM	TAIW	EEM	13DE2002	91136235	21MR2005	229694	12DE2022	NIHC	DUAL CURE B-STAGEABLE ADHESIVE FOR DIE ATTACH
1978D.EEM	USA	EEM	27JE2005	11/168,037				NIHC	SEMICONDUCTOR ASSEMBLY USING DUAL-CURE DIE ATTACH ADHESIVE

```
1979.EEM       USA   EEM         14DE2001   10/020,638         21DE2004   6,833,629    14DE2021     NIHC
DUAL CURE B-STAGEABLE UNDERFILL FOR WAFER LEVEL


1979.EEM       BELG  EEM         19NO2002   02 805 072.2       09JA2008   1461829      19NO2022     NIHC
DUAL CURE B-STAGEABLE UNDERFILL FOR WAFER LEVEL


1979.EEM       CHIN  EEM         19NO2002   02824937.2         28MR2007   ZL02824937.2 19NO2022     NIHC
DUAL CURE B-STAGEABLE UNDERFILL FOR WAFER LEVEL


1979.EEM       DENM  EEM         19NO2002   02 805 072.2       09JA2008   1461829      19NO2022     NIHC
DUAL CURE B-STAGEABLE UNDERFILL FOR WAFER LEVEL


1979.EEM       EPC   EEM         19NO2002   02 805 072.2       09JA2008   1461829      19NO2022     NIHC
DUAL CURE B-STAGEABLE UNDERFILL FOR WAFER LEVEL


1979.EEM       FRAN  EEM         19NO2002   02 805 072.2       09JA2008   1461829      19NO2022     NIHC
DUAL CURE B-STAGEABLE UNDERFILL FOR WAFER LEVEL


1979.EEM       GBRI  EEM         19NO2002   02 805 072.2       09JA2008   1461829      19NO2022     NIHC
DUAL CURE B-STAGEABLE UNDERFILL FOR WAFER LEVEL


1979.EEM       GERM  EEM         19NO2002   02 805 072.2       09JA2008   60224581.8-0819NO2022     NIHC
DUAL CURE B-STAGEABLE UNDERFILL FOR WAFER LEVEL


1979.EEM       ITAL  EEM         19NO2002   02 805 072.2       09JA2008   1461829      19NO2022     NIHC
DUAL CURE B-STAGEABLE UNDERFILL FOR WAFER LEVEL


1979.EEM       JAPA  EEM         19NO2002   2003-553611                                             NIHC
DUAL CURE B-STAGEABLE UNDERFILL FOR WAFER LEVEL


1979.EEM       KORS  EEM         19NO2002   2004-7007746                                            NIHC
DUAL CURE B-STAGEABLE UNDERFILL FOR WAFER LEVEL


1979.EEM       NETH  EEM         19NO2002   02 805 072.2       09JA2008   1461829      19NO2022     NIHC
DUAL CURE B-STAGEABLE UNDERFILL FOR WAFER LEVEL
```

```
1979.EEM      SING  EEM      19NO2002  200402173-9        31JL2006  104058      19NO2022    NIHC
DUAL CURE B-STAGEABLE UNDERFILL FOR WAFER LEVEL

1979.EEM      TAIW  EEM      13DE2002  91136234           21AU2005  238476      12DE2022    NIHC
DUAL CURE B-STAGEABLE UNDERFILL FOR WAFER LEVEL


1985.EEM      USA   EEM      31JA2002  10/062,906         23SE2003  6,624,216   31JA2022    NIHC
NO-FLOW UNDERFILL ENCAPSULANT

1985.EEM      CHIN  EEM      21JA2003  03806610.6                                           NIHC
NO-FLOW UNDERFILL ENCAPSULANT

1985.EEM      EPC   EEM      21JA2003  03 734 968.5                                         NIHC
NO-FLOW UNDERFILL ENCAPSULANT

1985.EEM      JAPA  EEM      21JA2003  2003-564930                                          NIHC
NO-FLOW UNDERFILL ENCAPSULANT

1985.EEM      KORS  EEM      28JA2003  2004-7011759                                         NIHC
NO-FLOW UNDERFILL ENCAPSULANT

1986.EEM      BELG  EEM      21JA2003  03 734 967.7       27JE2007  1470176     21JA2023    NIHC
NO FLOW UNDERFILL COMPOSITION

1986.EEM      CHIN  EEM      21JA2003  03806754.4                                           NIHC
NO FLOW UNDERFILL COMPOSITION

1986.EEM      CZEC  EEM      21JA2003  03 734 967.7       27JE2007  1470176     21JA2023    NIHC
NO FLOW UNDERFILL COMPOSITION

1986.EEM      EPC   EEM      21JA2003  03 734 967.7       27JE2007  1470176     21JA2023    NIHC
NO FLOW UNDERFILL COMPOSITION

1986.EEM      FINL  EEM      21JA2003  03 734 967.7       27JE2007  1470176     21JA2023    NIHC
```

```
NO FLOW UNDERFILL COMPOSITION

1986.EEM       FRAN  EEM        21JA2003   03 734 967.7      27JE2007   1470176      21JA2023     NIHC
NO FLOW UNDERFILL COMPOSITION

1986.EEM       GBRI  EEM        21JA2003   03 734 967.7      27JE2007   1470176      21JA2023     NIHC
NO FLOW UNDERFILL COMPOSITION

1986.EEM       GERM  EEM        21JA2003   03 734 967.7      27JE2007   60314596.5-0821JA2023     NIHC
NO FLOW UNDERFILL COMPOSITION

1986.EEM       HUNG  EEM        21JA2003   03 734 967.7      27JE2007   E002161      21JA2023     NIHC
NO FLOW UNDERFILL COMPOSITION

1986.EEM       IREL  EEM        21JA2003   03 734 967.7      27JE2007   1470176      21JA2023     NIHC
NO FLOW UNDERFILL COMPOSITION

1986.EEM       JAPA  EEM        21JA2003   2003-564107                                            NIHC
NO FLOW UNDERFILL COMPOSITION

1986.EEM       KORS  EEM        29JA2003   2004-7011760                                           NIHC
NO FLOW UNDERFILL COMPOSITION

1986.EEM       TURK  EEM        21JA2003   03 734 967.7      27JE2007  TR 200706520T421JA2023     NIHC
NO FLOW UNDERFILL COMPOSITION

1987.EEM       CHIN  EEM        11FE2003   03804934.1        21NO2007   03804934.1   11FE2023     NIHC
B-STAGEABLE UNDERFILL ENCAPSULANT AND METHOD FOR ITS
APPLICATION

1987.EEM       EPC   EEM        11FE2003   03 743 672.2                                           NIHC
B-STAGEABLE UNDERFILL ENCAPSULANT AND METHOD FOR ITS
APPLICATION

1987.EEM       JAPA  EEM        11FE2003   2003-573695                                            NIHC
B-STAGEABLE UNDERFILL ENCAPSULANT AND METHOD FOR ITS
```

```
APPLICATION


1987.EEM       KORS  EEM         11FE2003   10-2004-7013603                                                 NIHC
B-STAGEABLE UNDERFILL ENCAPSULANT AND METHOD FOR ITS
APPLICATION


1987A.EEM      USA   EEM         21NO2005   11/284,219                                                      NIHC
B-STAGEABLE UNDERFILL ENCAPSULANT AND METHOD FOR ITS
APPLICATION


1988.EEM       USA   EEM         01MR2002   10/084,869         02MY2006   7,037,399    01MR2020     NIHC
UNDERFILL ENCAPSULANT FOR WAFER PACKAGING AND METHOD FOR ITS
APPLICATION


1988.EEM       CHIN  EEM         10FE2003   ZL03809916.0       10OC2007   03809916.0   10FE2023     NIHC
UNDERFILL ENCAPSULANT FOR WAFER PACKAGING AND METHOD FOR ITS
APPLICATION


1988.EEM       EPC   EEM         10FE2003   03 709 031.3                                                    NIHC
UNDERFILL ENCAPSULANT FOR WAFER PACKAGING AND METHOD FOR ITS
APPLICATION


1988.EEM       JAPA  EEM         10FE2003   2003-573694                                                     NIHC
UNDERFILL ENCAPSULANT FOR WAFER PACKAGING AND METHOD FOR ITS
APPLICATION


1988.EEM       KORS  EEM         10FE2003   10-2004-7013604                                                 NIHC
UNDERFILL ENCAPSULANT FOR WAFER PACKAGING AND METHOD FOR ITS
APPLICATION


1988A.EEM      USA   EEM         10FE2006   11/351,647                                                      NIHC
UNDERFILL ENCAPSULANT FOR WAFER PACKAGING AND METHOD FOR ITS
APPLICATION


1988A.EEM      CHIN  EEM         07FE2007   200710007038.1                                                  NIHC
UNDERFILL ENCAPSULANT FOR WAFER PACKAGING AND METHOD FOR ITS
APPLICATION
```

```
1988A.EEM      EPC   EEM         07FE2007   07 002 620.8                                                 NIHC
UNDERFILL ENCAPSULANT FOR WAFER PACKAGING AND METHOD FOR ITS
APPLICATION


1988A.EEM      INDI  EEM         07FE2007   271/CHE/2007                                                 NIHC
UNDERFILL ENCAPSULANT FOR WAFER PACKAGING AND METHOD FOR ITS
APPLICATION


1988A.EEM      JAPA  EEM         07FE2007   2007-27801                                                   NIHC
UNDERFILL ENCAPSULANT FOR WAFER PACKAGING AND METHOD FOR ITS
APPLICATION


1988A.EEM      KORS  EEM         08FE2007   10-2007-0013253                                              NIHC
UNDERFILL ENCAPSULANT FOR WAFER PACKAGING AND METHOD FOR ITS
APPLICATION


1988A.EEM      MAYS  EEM         08FE2007   PI 20070190                                                  NIHC
UNDERFILL ENCAPSULANT FOR WAFER PACKAGING AND METHOD FOR ITS
APPLICATION


1988A.EEM      PHIL  EEM         07FE2007   1-2007-000050                                                NIHC
UNDERFILL ENCAPSULANT FOR WAFER PACKAGING AND METHOD FOR ITS
APPLICATION


1988A.EEM      TAIW  EEM         09FE2007   96104682                                                     NIHC
UNDERFILL ENCAPSULANT FOR WAFER PACKAGING AND METHOD FOR ITS
APPLICATION


1996.EEM       USA   EEM         16JA2002   10/052,422        11NO2003   6,646,095    20AP2022     NIHC
PROCESS FOR THE MANUFACTURE OF COPOLYMERS OF FORMALDEHYDE
AND DIPHENYL OXIDE


1999.TDM       USA   A           31JA2002   10/061,622                                                   NIHC
BIOADHESIVE COMPOSITION


1999.TDM       CHIN  A           31JA2003   03807689.6                                                   NIHC
BIOADHESIVE COMPOSITION COMPRISING A POLYSACCHARIDE AND A
```

```
POLYCARBOXYLATED POLYMER


1999.TDM       EPC   A          31JA2003   03 735 098.0                                                NIHC
BIOADHESIVE COMPOSITION COMPRISING A POLYSACCHARIDE AND A
POLYCARBOXYLATED POLYMER


1999.TDM       JAPA  A          31JA2003   2003-563533                                                 NIHC
BIOADHESIVE COMPOSITION COMPRISING A POLYSACCHARIDE AND A
POLYCARBOXYLATED POLYMER


2010.BDG       USA   A          25JL2002   10/205,137        26JE2007   7,235,608    27AU2023     NIHC
REMOISTENABLE PRE-APPLIED ADHESIVE


2010.BDG       CANA  A          23JL2003   2,435,898                                                   NIHC
REMOISTENABLE PRE-APPLIED ADHESIVES


2010.BDG       EPC   A          24JL2003   03 016 568.2                                                NIHC
REMOISTENABLE PRE-APPLIED ADHESIVES


2019.EEM       USA   EEM        06NO2002   10/289,504        06JE2006   7,056,978    31JA2022     NIHC
TOUGHENED EPOXY-ANHYDRIDE NO-FLOW UNDERFILL ENCAPSULANT


2019.EEM       CHIN  EEM        31OC2003   200380107868.1                                              NIHC
TOUGHENED EPOXY-ANHYDRIDE NO-FLOW UNDERFILL ENCAPSULANT


2019.EEM       CZEC  EEM        31OC2003   03 781 663.4      20SE2006   1558678      31OC2023     NIHC
TOUGHENED EPOXY-ANHYDRIDE NO-FLOW UNDERFILL ENCAPSULANT


2019.EEM       DENM  EEM        31OC2003   03 781 663.4      20SE2006   1558678      31OC2023     NIHC
TOUGHENED EPOXY-ANHYDRIDE NO-FLOW UNDERFILL ENCAPSULANT


2019.EEM       EPC   EEM        31OC2003   03 781 663.4      20SE2006   1558678      31OC2023     NIHC
TOUGHENED EPOXY-ANHYDRIDE NO-FLOW UNDERFILL ENCAPSULANT


2019.EEM       FINL  EEM        31OC2003   03 781 663.4      20SE2006   1558678      31OC2023     NIHC
TOUGHENED EPOXY-ANHYDRIDE NO-FLOW UNDERFILL ENCAPSULANT
```

```
2019.EEM       FRAN  EEM        31OC2003   03 781 663.4       20SE2006   1558678      31OC2023     NIHC
TOUGHENED EPOXY-ANHYDRIDE NO-FLOW UNDERFILL ENCAPSULANT

2019.EEM       GERM  EEM        31OC2003   03 781 663.4       20SE2006   60308545.8-0831OC2023     NIHC
TOUGHENED EPOXY-ANHYDRIDE NO-FLOW UNDERFILL ENCAPSULANT

2019.EEM       HUNG  EEM        31OC2003   03 781 663.4       20SE2006   E000939      31OC2023     NIHC
TOUGHENED EPOXY-ANHYDRIDE NO-FLOW UNDERFILL ENCAPSULANT

2019.EEM       INDO  EEM        31OC2003   W-00200501173                                           NIHC
TOUGHENED EPOXY-ANHYDRIDE NO-FLOW UNDERFILL ENCAPSULANT

2019.EEM       ISRA  EEM        31OC2003   168354                                                  NIHC
TOUGHENED EPOXY-ANHYDRIDE NO-FLOW UNDERFILL ENCAPSULANT

2019.EEM       JAPA  EEM        31OC2003   2004-551651                                             NIHC
TOUGHENED EPOXY-ANHYDRIDE NO-FLOW UNDERFILL ENCAPSULANT

2019.EEM       KORS  EEM        31OC2003   10-2005-7007974                                         NIHC
TOUGHENED EPOXY-ANHYDRIDE NO-FLOW UNDERFILL ENCAPSULANT

2019.EEM       ROMA  EEM        31OC2003   03 781 663.4       20SE2006   1558678      31OC2023     NIHC
TOUGHENED EPOXY-ANHYDRIDE NO-FLOW UNDERFILL ENCAPSULANT

2019.EEM       SING  EEM        31OC2003   200502810-5        28SE2007   111795       31OC2023     NIHC
TOUGHENED EPOXY-ANHYDRIDE NO-FLOW UNDERFILL ENCAPSULANT

2019.EEM       SWED  EEM        31OC2003   03 781 663.4       20SE2006   1558678      31OC2023     NIHC
TOUGHENED EPOXY-ANHYDRIDE NO-FLOW UNDERFILL ENCAPSULANT

2023.PKG       USA   A          07MY2002   10/140,692         03AP2007   7,199,204    02FE2024     NIHC
HOT MELT ADHESIVE COMPOSITION

2025.TST       USA   A          10MY2002   10/143,332         04JA2005   6,838,187    10MY2022     NIHC
```

```
WATER BASED ADHESIVE COMPOSITION WITH RELEASE PROPERTIES


2025.TST       JAPA  A          09MY2003   2004-503577                                                 NIHC
WATER BASED ADHESIVE COMPOSITION WITH RELEASE PROPERTIES


2027.BDG       USA   A          15OC2002   10/271,677         02MY2006   7,037,402    16DE2022     NIHC
REACTIVE HOT MELT ADHESIVES WITH NON-POLYMERIC AROMATIC
DIFUNCTIONALS


2028A.BDG      USA   A          10MR2006   11/372,785                                                  NIHC
REACTIVE HOT MELT ADHESIVE WITH NON-POLYMERIC ALIPHATIC
DIFUNCTIONALS


2028A.BDG      BRAZ  A          08MR2007   PI 0700650-0                                                NIHC
REACTIVE HOT MELT ADHESIVE WITH NON-POLYMERIC ALIPHATIC
DIFUNCTIONALS


2028A.BDG      CHIN  A          07MR2007   200710086012.0                                              NIHC
REACTIVE HOT MELT ADHESIVE WITH NON-POLYMERIC ALIPHATIC
DIFUNCTIONALS


2028A.BDG      EPC   A          09MR2007   07 004 901.0                                                NIHC
REACTIVE HOT MELT ADHESIVE WITH NON-POLYMERIC ALIPHATIC
DIFUNCTIONALS


2028A.BDG      JAPA  A          06MR2007   2007-55169                                                  NIHC
REACTIVE HOT MELT ADHESIVE WITH NON-POLYMERIC ALIPHATIC
DIFUNCTIONALS


2031.EEM       EPC   EEM        12MY2003   03 009 803.2       15MR2006   1362901      12MY2023     NIHC
THERMOSET ADHESIVE FILMS


2031.EEM       FRAN  EEM        12MY2003   03 009 803.2       15MR2006   1362901      12MY2023     NIHC
THERMOSET ADHESIVE FILMS


2031.EEM       GERM  EEM        12MY2003   03 009 803.2       15MR2006   60303972.3-0813MY2023     NIHC
THERMOSET ADHESIVE FILMS
```

2031.EEM THERMOSET ADHESIVE FILMS	ITAL	EEM	12MY2003	03 009 803.2	15MR2006	1362901	12MY2023	NIHC
2031.EEM THERMOSET ADHESIVE FILMS	JAPA	EEM	12MY2003	2003-132918	19OC2007	4,028,431	12MY2023	NIHC
2031.EEM THERMOSET ADHESIVE FILMS	KORS	EEM	12MY2003	2003-0029801				NIHC
2031.EEM THERMOSET ADHESIVE FILMS	SING	EEM	09MY2003	200302719-0	31AU2005	108921	09MY2023	NIHC
2031.EEM THERMOSET ADHESIVE FILMS	TAIW	EEM	11MY2003	92113003				NIHC
2031A/D.EEM THERMOSET ADHESIVE FILMS	USA	EEM	12OC2005	11/248,490	05FE2008	7,326,754	22JA2023	NIHC
2035.PSA POLYMERIC PHOTOINITIATORS	USA	A	18JE2003	10/465,473	02JA2007	7,157,535	08JE2024	NIHC
2035.PSA POLYMERIC PHOTOINITIATORS	ASTL	A	19JE2003	2003253660				NIHC
2035.PSA POLYMERIC PHOTOINITIATORS	CHIN	A	19JE2003	03813893.X	12DE2007	ZL03813893.X	19JE2023	NIHC
2035.PSA POLYMERIC PHOTOINITIATORS	EPC	A	19JE2003	03 761 119.1				NIHC
2035.PSA POLYMERIC PHOTOINITIATORS	JAPA	A	19JE2003	2004-515919				NIHC
2035.PSA	KORS	A	19JE2003	10-2004-7020651				NIHC

POLYMERIC PHOTOINITIATORS								
2035.PSA	TAIW	A	24JE2003	92117229				NIHC
POLYMERIC PHOTOINITIATORS								
2035A.PSA	USA	A	30NO2006	11/606,686				NIHC
POLYMERIC PHOTOINITIATORS								
2035B.PSA	USA	A	30NO2006	11/606,685				NIHC
POLYMERIC PHOTOINITIATORS								
2039.EEM	USA	EEM	19JL2002	10/200,481	16MR2004	6,706,835	11AU2022	NIHC
CURABLE COMPOSITIONS CONTAINING THIAZOLE FUNCTIONALITY								
2039.EEM	CHIN	EEM	21JL2003	03154611.0	19SE2007	03154611.0	21JL2023	NIHC
CURABLE COMPOSITIONS CONTAINING THIAZOLE FUNCTIONALITY								
2039.EEM	EPC	EEM	21JL2003	03 016 503.9	04MY2005	1382600	21JL2023	NIHC
CURABLE COMPOSITIONS CONTAINING THIAZOLE FUNCTIONALITY								
2039.EEM	FRAN	EEM	21JL2003	03 016 503.9	04MY2005	1382600	21JL2023	NIHC
CURABLE COMPOSITIONS CONTAINING THIAZOLE FUNCTIONALITY								
2039.EEM	GERM	EEM	21JL2003	03 016 503.9	04MY2005	60300602.7	21JL2023	NIHC
CURABLE COMPOSITIONS CONTAINING THIAZOLE FUNCTIONALITY								
2039.EEM	ITAL	EEM	21JL2003	03 016 503.9	04MY2005	1382600	21JL2023	NIHC
CURABLE COMPOSITIONS CONTAINING THIAZOLE FUNCTIONALITY								
2039.EEM	JAPA	EEM	18JL2003	2003-199321	07AP2006	3,790,234	18JL2023	NIHC
CURABLE COMPOSITIONS CONTAINING THIAZOLE FUNCTIONALITY								
2039.EEM	KORS	EEM	18JL2003	2003-0049077				NIHC
CURABLE COMPOSITIONS CONTAINING THIAZOLE FUNCTIONALITY								

```
2039.EEM       MAYS  EEM         15JL2003   PI 20032626        31OC2006   MY-126671-A  15JL2023     NIHC
CURABLE COMPOSITIONS CONTAINING THIAZOLE FUNCTIONALITY


2039.EEM       SING  EEM         17JL2003   200304359-3        29OC2004   106153       17JL2023     NIHC
CURABLE COMPOSITIONS CONTAINING THIAZOLE FUNCTIONALITY


2039.EEM       TAIW  EEM         17JL2003   92119755           21NO2005   243818       16JL2023     NIHC
CURABLE COMPOSITIONS CONTAINING THIAZOLE FUNCTIONALITY


2039.EEM       THAI  EEM         10JL2003   083737             25DE2006   21132        10JL2023     NIHC
CURABLE COMPOSITIONS CONTAINING THIAZOLE FUNCTIONALITY


2040.EEM       USA   EEM         22JL2002   10/201,373         06AP2004   6,716,992    25SE2022     NIHC
CYCLOALIPHATIC EPOXY COMPOUNDS CONTAINING STYRENIC,
CINNAMYL, OR MALEIMIDE FUNCTIONALITY


2040.EEM       CHIN  EEM         22JL2003   03158021.1                                 22JL2023     NIHC
CYCLOALIPHATIC EPOXY COMPOUNDS CONTAINING STYRENIC,
CINNAMYL, OR MALEIMIDE FUNCTIONALITY


2040.EEM       EPC   EEM         22JL2003   03 016 521.1                                            NIHC
CYCLOALIPHATIC EPOXY COMPOUNDS CONTAINING STYRENIC,
CINNAMYL, OR MALEIMIDE FUNCTIONALITY


2040.EEM       HONG  EEM         16AU2004   04106118.0                                              NIHC
CYCLOALIPHATIC EPOXY COMPOUNDS CONTAINING STYRENIC,
CINNAMYL, OR MALEIMIDE FUNCTIONALITY


2040.EEM       JAPA  EEM         18JL2003   2003-199169                                             NIHC
CYCLOALIPHATIC EPOXY COMPOUNDS CONTAINING STYRENIC,
CINNAMYL, OR MALEIMIDE FUNCTIONALITY


2040.EEM       KORS  EEM         22JL2003   2003-0050139                                            NIHC
CYCLOALIPHATIC EPOXY COMPOUNDS CONTAINING STYRENIC,
CINNAMYL, OR MALEIMIDE FUNCTIONALITY


2040.EEM       SING  EEM         22JL2003   200304356-9        31JL2006   109521       22JL2023     NIHC
```

```
CYCLOALIPHATIC EPOXY COMPOUNDS CONTAINING STYRENIC,
CINNAMYL, OR MALEIMIDE FUNCTIONALITY


2040.EEM       TAIW  EEM        18JL2003   92119896           21MR2007   I-276633     17JL2023     NIHC
CYCLOALIPHATIC EPOXY COMPOUNDS CONTAINING STYRENIC,
CINNAMYL, OR MALEIMIDE FUNCTIONALITY


2040.EEM       THAI  EEM        16JL2003   083833                                                  NIHC
CYCLOALIPHATIC EPOXY COMPOUNDS CONTAINING STYRENIC,
CINNAMYL, OR MALEIMIDE FUNCTIONALITY


2040D.EEM      EPC   EEM        22JL2003   04 029 057.9                                            NIHC
CYCLOALIPHATIC EPOXY COMPOUNDS CONTAINING STYRENIC,
CINNAMYL, OR MALEIMIDE FUNCTIONALITY


2043.BDP       USA   A          06AU2002   10/213,883         11NO2003   6,645,341    06AU2022     NIHC
TWO PART EPOXIDE ADHESIVE WITH IMPROVED STRENGTH


2043.BDP       EPC   A          11DE2002   02 786 997.3                                            NIHC
TWO PART EPOXIDE ADHESIVE WITH IMPROVED STRENGTH


2043.BDP       TAIW  A          03AU2003   92121335           01DE2006   267541       02AU2023     NIHC
TWO PART EPOXIDE ADHESIVE WITH IMPROVED STRENGTH


2049.PKG       USA   A          06SE2002   10/236,270                                              NIHC
HOT MELT ADHESIVES AND USE THEREOF


2049.PKG       ASTL  A          04SE2003   2003263055                                              NIHC
HOT MELT ADHESIVES AND USE THEREOF


2049.PKG       CHIN  A          04SE2003   03820963.2         13DE2006   ZL03820963.2 04SE2023     NIHC
HOT MELT ADHESIVES AND USE THEREOF


2049.PKG       GBRI  A          04SE2003   0504985.3          25AP2007   2408742      04SE2023     NIHC
HOT MELT ADHESIVES AND USE THEREOF
```

```
2049.PKG       GERM  A           04SE2003   103 93 236.4-43                                             NIHC
HOT MELT ADHESIVES AND USE THEREOF


2049.PKG       JAPA  A           04SE2003   2004-534436                                                 NIHC
HOT MELT ADHESIVES AND USE THEREOF


2055.EEM       USA   EEM         18OC2002   10/274,664         06JE2006   7,057,264    18AU2023     NIHC
CURABLE COMPOUNDS CONTAINING REACTIVE GROUPS:
TRIAZINE/ISOCYANURATES, CYANATE ESTERS AND BLOCKED


2055.EEM       EPC   EEM         16OC2003   03 023 562.6                                                NIHC
CURABLE COMPOUNDS CONTAINING REACTIVE GROUPS:
TRIAZINE/ISOCYANURATES, CYANATE ESTERS AND BLOCKED


2055.EEM       JAPA  EEM         17OC2003   2003-357956                                                 NIHC
CURABLE COMPOUNDS CONTAINING REACTIVE GROUPS:
TRIAZINE/ISOCYANURATES, CYANATE ESTERS AND BLOCKED


2055.EEM       KORS  EEM         13OC2003   2003-0071140                                                NIHC
CURABLE COMPOUNDS CONTAINING REACTIVE GROUPS:
TRIAZINE/ISOCYANURATES, CYANATE ESTERS AND BLOCKED


2055.EEM       TAIW  EEM         13OC2003   92128285           11AP2007   278462       12OC2023     NIHC
CURABLE COMPOUNDS CONTAINING REACTIVE GROUPS:
TRIAZINE/ISOCYANURATES, CYANATE ESTERS AND BLOCKED


2056.BDG       USA   A           24OC2002   10/280,298         26SE2006   7,112,631    24OC2022     NIHC
MOISTURE CURED REACTIVE HOT MELT ADHESIVE WITH
MONOFUNCTIONAL REACTANTS AS GRAFTING AGENTS


2056A.BDG      USA   A           01SE2006   11/514,499                                                  NIHC
MOISTURE CURED REACTIVE HOT MELT ADHESIVE WITH
MONOFUNCTIONAL REACTANTS AS GRAFTING AGENTS


2058.ADH       EPC   A           22JE2004   04 737 116.6                                                NIHC
NON-METALIC SUBSTRATE HAVING AN ELECTROSTATICALLY APPLIED
ACTIVATABLE POWDER ADHESIVE
```

```
2059.NWN       USA   A          18OC2002   10/273,836                                         NIHC
LOW APPLICATION TEMPERATURE HOT MELT ADHESIVE


2059.NWN       ASTL  A          20OC2003   2003282966                                         NIHC
LOW APPLICATION TEMPERATURE HOT MELT ADHESIVE


2059.NWN       CHIN  A          20OC2003   200380106089.X                                     NIHC
LOW APPLICATION TEMPERATURE HOT MELT ADHESIVE


2059.NWN       EPC   A          20OC2003   03 774 898.5                                       NIHC
LOW APPLICATION TEMPERATURE HOT MELT ADHESIVE


2059.NWN       JAPA  A          20OC2003   2004-545572                                        NIHC
LOW APPLICATION TEMPERATURE HOT MELT ADHESIVE


2059D.NWN      USA   A          12MR2007   11/716,954                                         NIHC
LOW APPLICATION TEMPERATURE HOT MELT ADHESIVE


2060.ADH       USA   A          21OC2002   10/274,827                                         NIHC
MULTI-LAYER FILM FOR HOT MELT PACKAGING


2060.ADH       ASTL  A          20OC2003   2003279990                                         NIHC
MULTI-LAYER FILM FOR HOT MELT PACKAGING


2060.ADH       CHIN  A          20OC2003   200380107196.4                                     NIHC
MULTI-LAYER FILM FOR HOT MELT PACKAGING


2060.ADH       EPC   A          20OC2003   03 773 296.3                                       NIHC
MULTI-LAYER FILM FOR HOT MELT PACKAGING


2060.ADH       JAPA  A          20OC2003   2004-546944                                        NIHC
MULTI-LAYER FILM FOR HOT MELT PACKAGING


2060.ADH       KORS  A          20OC2003   10-2005-7006789                                    NIHC
MULTI-LAYER FILM FOR HOT MELT PACKAGING
```

```
2061.PSA       ASTL  A          18DE2003   2003270996                                                 NIHC
HOT MELT ADHESIVES BASED ON ACRYLIC BLOCK COPOLYMERS


2061.PSA       CANA  A          19DE2003   2,453,746                                                  NIHC
HOT MELT ADHESIVES BASED ON ACRYLIC BLOCK COPOLYMERS


2061.PSA       EPC   A          19DE2003   03 029 469.8                                               NIHC
HOT MELT ADHESIVES BASED ON ACRYLIC BLOCK COPOLYMERS


2061.PSA       JAPA  A          19DE2003   2003-422614                                                NIHC
HOT MELT ADHESIVES BASED ON ACRYLIC BLOCK COPOLYMERS


2061.PSA       KORS  A          19DE2003   2003-0093995                                               NIHC
HOT MELT ADHESIVES BASED ON ACRYLIC BLOCK COPOLYMERS


2061D.PSA      USA   A          26JA2005   11/043,474                                                 NIHC
TRANSDERMAL DRUG DELIVERY DEVICE COMPRISING AN ACRYLIC BLOCK
COPOLYMER-BASED ADHESIVE


2062.EEM       USA   EEM        20NO2002   10/301,924       31AU2004   6,784,025    02FE2023     NIHC
SEMICONDUCTOR PACKAGE WITH A DIE ATTACH ADHESIVE HAVING
SILANE FUNCTIONALITY


2062.EEM       EPC   EEM        20NO2003   03 026 695.1     04AP2007   1422279      20NO2023     NIHC
SEMICONDUCTOR PACKAGE WITH A DIE ATTACH ADHESIVE HAVING
SILANE FUNCTIONALITY


2062.EEM       FRAN  EEM        20NO2003   03 026 695.1     04AP2007   1422279      20NO2023     NIHC
SEMICONDUCTOR PACKAGE WITH A DIE ATTACH ADHESIVE HAVING
SILANE FUNCTIONALITY


2062.EEM       GERM  EEM        20NO2003   03 026 695.1     04AP2007   60312946.3   20NO2023     NIHC
SEMICONDUCTOR PACKAGE WITH A DIE ATTACH ADHESIVE HAVING
SILANE FUNCTIONALITY
```

```
2062.EEM       ITAL  EEM         20NO2003   03 026 695.1        04AP2007   1422279      20NO2023     NIHC
SEMICONDUCTOR PACKAGE WITH A DIE ATTACH ADHESIVE HAVING
SILANE FUNCTIONALITY

2062.EEM       JAPA  EEM         19NO2003   2003-389140                                              NIHC
SEMICONDUCTOR PACKAGE WITH A DIE ATTACH ADHESIVE HAVING
SILANE FUNCTIONALITY

2062.EEM       KORS  EEM         17NO2003   2003-0080995                                             NIHC
SEMICONDUCTOR PACKAGE WITH A DIE ATTACH ADHESIVE HAVING
SILANE FUNCTIONALITY

2062.EEM       MAYS  EEM         17NO2003   PI 20034393         29DE2006   MY-127794-A  17NO2023     NIHC
SEMICONDUCTOR PACKAGE WITH A DIE ATTACH ADHESIVE HAVING
SILANE FUNCTIONALITY

2062.EEM       TAIW  EEM         19NO2003   92132356            01AP2005   230422       18NO2023     NIHC
SEMICONDUCTOR PACKAGE WITH A DIE ATTACH ADHESIVE HAVING
SILANE FUNCTIONALITY

2063.EEM       USA   EEM         20NO2002   10/302,574          26OC2004   6,809,155    20NO2022     NIHC
UNSATURATED COMPOUNDS CONTAINING SILANE, ELECTRON DONOR AND
ELECTRON ACCEPTOR FUNCTIONALITY

2063.EEM       JAPA  EEM         19NO2003   2003-389186                                              NIHC
UNSATURATED COMPOUNDS CONTAINING SILANE, ELECTRON DONOR AND
ELECTRON ACCEPTOR FUNCTIONALITY

2063.EEM       KORS  EEM         17NO2003   2003-0080996                                             NIHC
UNSATURATED COMPOUNDS CONTAINING SILANE, ELECTRON DONOR AND
ELECTRON ACCEPTOR FUNCTIONALITY

2063.EEM       MAYS  EEM         17NO2003   PI 20034394                                              NIHC
UNSATURATED COMPOUNDS CONTAINING SILANE, ELECTRON DONOR AND
ELECTRON ACCEPTOR FUNCTIONALITY

2063.EEM       PHIL  EEM         17NO2003   1-2003-00532                                             NIHC
UNSATURATED COMPOUNDS CONTAINING SILANE, ELECTRON DONOR AND
```

```
ELECTRON ACCEPTOR FUNCTIONALITY


2063.EEM       TAIW  EEM         19NO2003   92132355          30JE2005   235162       18NO2023     NIHC
UNSATURATED COMPOUNDS CONTAINING SILANE, ELECTRON DONOR AND
ELECTRON ACCEPTOR FUNCTIONALITY


2063D.EEM      USA   EEM         07MY2004   10/841,059        21JE2005   6,908,969    23NO2022     NIHC
UNSATURATED COMPOUNDS CONTAINING SILANE, ELECTRON DONOR AND
ELECTRON ACCEPTOR FUNCTIONALITY


2069.EEM       USA   EEM         20DE2002   10/327,353        25AP2006   7,034,089    17AP2023     NIHC
EPOXY-FUNCTIONAL HYBRID COPOLYMERS


2069.EEM       CHIN  EEM         08DE2003   200380109778.6                                         NIHC
EPOXY-FUNCTIONAL HYBRID COPOLYMERS


2069.EEM       EPC   EEM         08DE2003   03 814 660.1                                           NIHC
EPOXY-FUNCTIONAL HYBRID COPOLYMERS


2069.EEM       JAPA  EEM         08DE2003   2005-565245                                            NIHC
EPOXY-FUNCTIONAL HYBRID COPOLYMERS


2069.EEM       KORS  EEM         08DE2003   10-2005-7011443                                        NIHC
EPOXY-FUNCTIONAL HYBRID COPOLYMERS


2070.EEM       USA   EEM         02JA2003   10/336,067        23NO2004   6,822,047    02JA2023     NIHC
ADHESIVE WITH CARBOXYL BENZOTRIAZOLE FOR IMPROVED ADHESION
TO METAL SUBSTRATES


2070.EEM       BELG  EEM         12DE2003   03 814 857.3      05SE2007   1578881      12DE2023     NIHC
ADHESIVE WITH CARBOXYL BENZOTRIAZOLE FOR IMPROVED ADHESION
TO METAL SUBSTRATES


2070.EEM       CHIN  EEM         12DE2003   200380100306.4    10JA2007  ZL0380100306.412DE2023     NIHC
ADHESIVE WITH CARBOXYL BENZOTRIAZOLE FOR IMPROVED ADHESION
TO METAL SUBSTRATES
```

```
2070.EEM       DENM  EEM        12DE2003   03 814 857.3       05SE2007   1578881      12DE2023     NIHC
ADHESIVE WITH CARBOXYL BENZOTRIAZOLE FOR IMPROVED ADHESION
TO METAL SUBSTRATES


2070.EEM       EPC   EEM        12DE2003   03 814 857.3       05SE2007   1578881      12DE2023     NIHC
ADHESIVE WITH CARBOXYL BENZOTRIAZOLE FOR IMPROVED ADHESION
TO METAL SUBSTRATES


2070.EEM       FINL  EEM        12DE2003   03 814 857.3       05SE2007   1578881      12DE2023     NIHC
ADHESIVE WITH CARBOXYL BENZOTRIAZOLE FOR IMPROVED ADHESION
TO METAL SUBSTRATES


2070.EEM       FRAN  EEM        12DE2003   03 814 857.3       05SE2007   1578881      12DE2023     NIHC
ADHESIVE WITH CARBOXYL BENZOTRIAZOLE FOR IMPROVED ADHESION
TO METAL SUBSTRATES


2070.EEM       GBRI  EEM        12DE2003   03 814 857.3       05SE2007   1578881      12DE2023     NIHC
ADHESIVE WITH CARBOXYL BENZOTRIAZOLE FOR IMPROVED ADHESION
TO METAL SUBSTRATES


2070.EEM       GERM  EEM        12DE2003   03 814 857.3       05SE2007   60316186.3-0812DE2023     NIHC
ADHESIVE WITH CARBOXYL BENZOTRIAZOLE FOR IMPROVED ADHESION
TO METAL SUBSTRATES


2070.EEM       HONG  EEM        06MR2006   06102879.6         31AU2007   1082956      12DE2023     NIHC
ADHESIVE WITH CARBOXYL BENZOTRIAZOLE FOR IMPROVED ADHESION
TO METAL SUBSTRATES


2070.EEM       ITAL  EEM        12DE2003   03 814 857.3       05SE2007   1578881      12DE2023     NIHC
ADHESIVE WITH CARBOXYL BENZOTRIAZOLE FOR IMPROVED ADHESION
TO METAL SUBSTRATES


2070.EEM       JAPA  EEM        12DE2003   2004-565554                                             NIHC
ADHESIVE WITH CARBOXYL BENZOTRIAZOLE FOR IMPROVED ADHESION
TO METAL SUBSTRATES


2070.EEM       KORS  EEM        12DE2003   10-2004-7013651                                         NIHC
```

```
ADHESIVE WITH CARBOXYL BENZOTRIAZOLE FOR IMPROVED ADHESION
TO METAL SUBSTRATES

2070.EEM       MAYS  EEM        08SE2004   PI 20043631        28FE2007   MY-128523-A  08SE2024     NIHC
ADHESIVE WITH CARBOXYL BENZOTRIAZOLE FOR IMPROVED ADHESION
TO METAL SUBSTRATES

2070.EEM       NETH  EEM        12DE2003   03 814 857.3       05SE2007   1578881      12DE2023     NIHC
ADHESIVE WITH CARBOXYL BENZOTRIAZOLE FOR IMPROVED ADHESION
TO METAL SUBSTRATES

2070.EEM       SING  EEM        12DE2003   200404961-5                                             NIHC
ADHESIVE WITH CARBOXYL BENZOTRIAZOLE FOR IMPROVED ADHESION
TO METAL SUBSTRATES

2070.EEM       SWED  EEM        12DE2003   03 814 857.3       05SE2007   1578881      12DE2023     NIHC
ADHESIVE WITH CARBOXYL BENZOTRIAZOLE FOR IMPROVED ADHESION
TO METAL SUBSTRATES

2070D.EEM      SING  EEM        12DE2003   200704907-5                                             NIHC
ADHESIVE WITH CARBOXYL BENZOTRIAZOLE FOR IMPROVED ADHESION
TO METAL SUBSTRATES

2073.BDP       USA   A          21JA2003   10/348,654         16DE2003   6,664,357    21JA2023     NIHC
METHOD FOR THE PREPARATION OF A STABLE ANAEROBIC/UV/VISIBLE
LIGHT CURABLE ADHESIVE

2074.EEM       EPC   EEM        02MR2004   04 716 407.4                                            NIHC
THERMAL INTERFACE MATERIAL

2074A.EEM      USA   EEM        08JL2005   11/178,138                                              NIHC
THERMAL INTERFACE MATERIAL

2079.PSG       USA   A          11FE2003   10/364,795         12OC2004   6,802,214    07MR2023     NIHC
ENVELOPE QUALITY CONTROL APPARATUS

2079.PSG       EPC   A          09FE2004   04 709 464.4                                            NIHC
```

ENVELOPE QUALITY CONTROL APPARATUS								
2080.PKG	USA	A	14FE2003	10/367,543	21SE2004	6,794,443	02MR2023	NIHC
HOT MELT ADHESIVE COMPOSITION								
2080.PKG	CHIN	A	13FE2004	200480006311.3				NIHC
HOT MELT ADHESIVE COMPOSITION								
2080.PKG	EPC	A	13FE2004	04 711 152.1				NIHC
HOT MELT ADHESIVE COMPOSITION								
2085.PKG	USA	A	24FE2003	10/372,691				NIHC
SUBSTRATE FOR CORE AND TUBEWINDING								
2085.PKG	EPC	A	20FE2004	04 713 394.7				NIHC
SUBSTRATE FOR CORE AND TUBEWINDING								
2086.PKG	EPC	A	20FE2004	04 713 488.7				NIHC
PACKAGING SYSTEM								
2090.PKG	EPC	A	20FE2004	04 713 425.9				NIHC
REACTIVATABLE ADHESIVES								
2091.PKG	EPC	A	20FE2004	04 713 409.3				NIHC
REACTIVATION OF PRE-APPLIED ADHESIVES BY ULTRASONIC WAVES								
2092.PKG	USA	A	25FE2004	10/786,185				NIHC
HOT MELT ADHESIVE COMPOSITION								
2092.PKG	ASTL	A	25FE2004	2004215348				NIHC
HOT MELT ADHESIVE COMPOSITION								
2092.PKG	EPC	A	25FE2004	04 714 601.4				NIHC
HOT MELT ADHESIVE COMPOSITION								

2092.PKG	JAPA	A	25FE2004	2006-503862				NIHC
HOT MELT ADHESIVE COMPOSITION								
2093.PKG	USA	A	25MY2004	10/853,750				NIHC
ADHESIVE FOR BAG SEALING APPLICATION								
2093.PKG	PCT	A	25MY2005	PCT/US05/18361				NIHC
ADHESIVE FOR BAG SEALING APPLICATION								
2097.EEM	USA	EEM	28FE2003	10/377,988	19SE2006	7,108,806	02SE2024	NIHC
CONDUCTIVE MATERIALS WITH ELECTRICAL STABILITY AND GOOD IMPACT RESISTANCE FOR USE IN ELECTRONIC DEVICES								
2097.EEM	CHIN	EEM	18FE2004	200480005233.5				NIHC
CONDUCTIVE MATERIALS WITH ELECTRICAL STABILITY AND GOOD IMPACT RESISTANCE FOR USE IN ELECTRONIC DEVICES								
2097.EEM	EPC	EEM	18FE2004	04 712 396.3				NIHC
CONDUCTIVE MATERIALS WITH ELECTRICAL STABILITY AND GOOD IMPACT RESISTANCE FOR USE IN ELECTRONIC DEVICES								
2097.EEM	JAPA	EEM	18FE2004	2006-508764				NIHC
CONDUCTIVE MATERIALS WITH ELECTRICAL STABILITY AND GOOD IMPACT RESISTANCE FOR USE IN ELECTRONIC DEVICES								
2097.EEM	KORS	EEM	18FE2004	10-2005-7016031				NIHC
CONDUCTIVE MATERIALS WITH ELECTRICAL STABILITY AND GOOD IMPACT RESISTANCE FOR USE IN ELECTRONIC DEVICES								
2097.EEM	PCT	EEM	18FE2004	PCT/US04/04844				NIHC
CONDUCTIVE MATERIALS WITH ELECTRICAL STABILITY AND GOOD IMPACT RESISTANCE FOR USE IN ELECTRONIC DEVICES								
2097.EEM	PHIL	EEM	18FE2004	1-2005-501418				NIHC
CONDUCTIVE MATERIALS WITH ELECTRICAL STABILITY AND GOOD IMPACT RESISTANCE FOR USE IN ELECTRONIC DEVICES								

```
3000.EEM       USA   EEM        06MY2003   10/430,089        25AP2006   7,034,064    26OC2023     NIHC
A METHOD OF ATTACHING A DIE TO A SUBSTRATE USING A HYBRID
OXETANE COMPOUND


3000.EEM       CHIN  EEM        21AP2004   200480012025.8    24OC2007  200480012025.821AP2024     NIHC
ADHESIVE COMPOSITIONS CONTAINING HYBRID OXETANE COMPOUNDS


3000.EEM       EPC   EEM        21AP2004   04 760 827.8                                           NIHC
ADHESIVE COMPOSITIONS CONTAINING HYBRID OXETANE COMPOUNDS


3000.EEM       HONG  EEM        01DE2006   06113265.5                                             NIHC
ADHESIVE COMPOSITIONS CONTAINING HYBRID OXETANE COMPOUNDS


3000.EEM       JAPA  EEM        21AP2004   2006-532451                                            NIHC
ADHESIVE COMPOSITIONS CONTAINING HYBRID OXETANE COMPOUNDS


3000.EEM       KORS  EEM        21AP2004   10-2005-7020879                                        NIHC
ADHESIVE COMPOSITIONS CONTAINING HYBRID OXETANE COMPOUNDS


3000.EEM       SING  EEM        21AP2004   200506861-4       31DE2007   116894       21AP2024     NIHC
ADHESIVE COMPOSITIONS CONTAINING HYBRID OXETANE COMPOUNDS


3000.EEM       TAIW  EEM        05MY2004   93112577                                               NIHC
ADHESIVE COMPOSITIONS CONTAINING HYBRID OXETANE COMPOUNDS


3001.EEM       USA   EEM        06MY2003   10/430,086        11OC2005   6,953,862    07SE2023     NIHC
OXETANE COMPOUNDS CONTAINING STYRENIC FUNCTIONALITY


3001.EEM       CHIN  EEM        21AP2004   200480000440.1                                         NIHC
OXETANE COMPOUNDS CONTAINING STYRENIC FUNCTIONALITY


3001.EEM       EPC   EEM        21AP2004   04 760 829.4                                           NIHC
OXETANE COMPOUNDS CONTAINING STYRENIC FUNCTIONALITY


3001.EEM       HONG  EEM        21AP2004   06102756.4                                             NIHC
```

```
OXETANE COMPOUNDS CONTAINING STYRENIC FUNCTIONALITY


3001.EEM       JAPA  EEM         21AP2004   2005-518201                                                   NIHC
OXETANE COMPOUNDS CONTAINING STYRENIC FUNCTIONALITY


3001.EEM       KORS  EEM         21AP2004   10-2005-7001438    10JL2006   0602057      21AP2024     NIHC
OXETANE COMPOUNDS CONTAINING STYRENIC FUNCTIONALITY


3001.EEM       SING  EEM         21AP2004   2005 01288-5                                                  NIHC
OXETANE COMPOUNDS CONTAINING STYRENIC FUNCTIONALITY


3001.EEM       TAIW  EEM         05MY2004   93112575                                                      NIHC
OXETANE COMPOUNDS CONTAINING STYRENIC FUNCTIONALITY


3001D.EEM      USA   EEM         03MY2005   11/120,585                                                    NIHC
POLYMER COMPOUNDS CONTAINING OXETANE AND STYRENIC
FUNCTIONALITY


3001D.EEM      CHIN  EEM         21AP2004   200610153771.X                                                NIHC
OXETANE COMPOUNDS CONTAINING STYRENIC FUNCTIONALITY


3001D.EEM      SING  EEM         21AP2004   200800919-3                                                   NIHC
OXETANE COMPOUNDS CONTAINING STYRENIC FUNCTIONALITY


3002.EEM       USA   EEM         06MY2003   10/430,114         22JE2004   6,753,434    09MY2023     NIHC
OXETANE COMPOUNDS CONTAINING CINNAMYL FUNCTIONALITY


3002.EEM       CHIN  EEM         21AP2004   200480012027.7                                                NIHC
OXETANE COMPOUNDS CONTAINING CINNAMYL FUNCTIONALITY


3002.EEM       EPC   EEM         21AP2004   04 760 830.2                                                  NIHC
OXETANE COMPOUNDS CONTAINING CINNAMYL FUNCTIONALITY


3002.EEM       HONG  EEM         15DE2006   06113832.9                                                    NIHC
OXETANE COMPOUNDS CONTAINING CINNAMYL FUNCTIONALITY
```

3002.EEM	JAPA	EEM	21AP2004	2006-532454				NIHC
OXETANE COMPOUNDS CONTAINING CINNAMYL FUNCTIONALITY								
3002.EEM	KORS	EEM	21AP2004	10-2005-7020880				NIHC
OXETANE COMPOUNDS CONTAINING CINNAMYL FUNCTIONALITY								
3002.EEM	SING	EEM	21AP2004	200506863-0	30JE2006	116896	21AP2024	NIHC
OXETANE COMPOUNDS CONTAINING CINNAMYL FUNCTIONALITY								
3002.EEM	TAIW	EEM	05MY2004	93112574				NIHC
OXETANE COMPOUNDS CONTAINING CINNAMYL FUNCTIONALITY								
3002D.EEM	USA	EEM	06JA2004	10/752,408	13SE2005	6,943,258	05JE2023	NIHC
POLYMER COMPOUNDS CONTAINING OXETANE AND CINNAMYL FUNCTIONALITY								
3003.EEM	USA	EEM	06MY2003	10/430,085	03JA2006	6,982,338	20OC2023	NIHC
OXETANE COMPOUNDS CONTAINING MALEIMIDE FUNCTIONALITY								
3003.EEM	CHIN	EEM	21AP2004	200480012026.2				NIHC
OXETANE COMPOUNDS CONTAINING MALEIMIDE FUNCTIONALITY								
3003.EEM	EPC	EEM	21AP2004	04 760 825.2				NIHC
OXETANE COMPOUNDS CONTAINING MALEIMIDE FUNCTIONALITY								
3003.EEM	HONG	EEM	13DE2006	06113689.3				NIHC
OXETANE COMPOUNDS CONTAINING MALEIMIDE FUNCTIONALITY								
3003.EEM	JAPA	EEM	21AP2004	2006-532450				NIHC
OXETANE COMPOUNDS CONTAINING MALEIMIDE FUNCTIONALITY								
3003.EEM	KORS	EEM	21AP2004	10-2005-7020881				NIHC
OXETANE COMPOUNDS CONTAINING MALEIMIDE FUNCTIONALITY								
3003.EEM	SING	EEM	21AP2004	200506860-6	31OC2007	116893	21AP2024	NIHC

OXETANE COMPOUNDS CONTAINING MALEIMIDE FUNCTIONALITY

3003.EEM	TAIW	EEM	05MY2004	93112573				NIHC	OXETANE COMPOUNDS CONTAINING MALEIMIDE FUNCTIONALITY
3003D.EEM	USA	EEM	04MY2005	11/121,430	15JA2008	7,319,132	08JE2024	NIHC	POLYMER COMPOUNDS CONTAINING OXETANE AND MALEIMIDE FUNCTIONALITY
3003D.EEM	EPC	EEM	21SE2006	06 019 766.2				NIHC	OXETANE COMPOUNDS CONTAINING MALEIMIDE FUNCTIONALITY
3006.EEM	USA	EEM	12MR2003	10/388,031	17AU2004	6,776,226	12MR2023	NIHC	ELECTRONIC DEVICE CONTAINING THERMAL INTERFACE MATERIAL
3006.EEM	EPC	EEM	02MR2004	04 716 410.8				NIHC	ELECTRONIC DEVICE CONTAINING THERMAL INTERFACE MATERIAL
3010.BDG	USA	A	04AP2003	10/408,141				NIHC	REACTIVE HOT MELT ADHESIVE WITH IMPROVED HYDROLYSIS RESISTANCE
3010.BDG	CHIN	A	19MR2004	200480014917.1				NIHC	REACTIVE HOT MELT ADHESIVE WITH IMPROVED HYDROLYSIS RESISTANCE
3010.BDG	EPC	A	19MR2004	04 759 686.1				NIHC	REACTIVE HOT MELT ADHESIVE WITH IMPROVED HYDROLYSIS RESISTANCE
3010.BDG	JAPA	A	19MR2004	2006-507371				NIHC	REACTIVE HOT MELT ADHESIVE WITH IMPROVED HYDROLYSIS RESISTANCE
3011.BDG	CHIN	A	19MR2004	200480014845.0				NIHC	EASY DE-GLAZING REACTIVE HOT MELT ADHESIVE

```
3011.BDG       JAPA  A           19MR2004   2006-507399                                              NIHC
EASY DE-GLAZING REACTIVE HOT MELT ADHESIVE


3013.PSA       USA   A           11AP2003   10/412,840                                               NIHC
PROCESS FOR MAKING PRESSURE SENSITIVE ADHESIVE TAPES FROM
CATIONIC CURE ADHESIVES


3013.PSA       BRAZ  A           08AP2004   0401045-0                                                NIHC
PROCESS FOR MAKING PRESSURE SENSITIVE ADHESIVE TAPES FROM
CATIONIC CURE ADHESIVES


3013.PSA       CHIN  A           08AP2004   200410038791.3                                           NIHC
PROCESS FOR MAKING PRESSURE SENSITIVE ADHESIVE TAPES FROM
CATIONIC CURE ADHESIVES


3013.PSA       GERM  A           08AP2004  10 2004 018 067.9-43                                      NIHC
PROCESS FOR MAKING PRESSURE SENSITIVE ADHESIVE TAPES FROM
CATIONIC CURE ADHESIVES


3013.PSA       KORS  A           09AP2004   2004-0024562                                             NIHC
PROCESS FOR MAKING PRESSURE SENSITIVE ADHESIVE TAPES FROM
CATIONIC CURE ADHESIVES


3013D.PSA      USA   A           30MY2006   11/443,381                                               NIHC
PROCESS FOR MAKING PRESSURE SENSITIVE ADHESIVE TAPES FROM
CATIONIC CURE ADHESIVES


3017A.EEM      USA   A           20FE2004   10/783,315         24JL2007   7,247,673    25SE2024     NIHC
WATERBASED HIGH ABRASION RESISTANT COATING


3017A.EEM      BRAZ  A           13AP2004   0409506-5                                                NIHC
WATERBASED HIGH ABRASION RESISTANT COATING


3017A.EEM      CANA  A           13AP2004   2,523,076                                                NIHC
WATERBASED HIGH ABRASION RESISTANT COATING
```

```
3017A.EEM      CHIN  A          13AP2004   200480010531.3     07NO2007  200480010531.313AP2024     NIHC
WATERBASED HIGH ABRASION RESISTANT COATING

3017A.EEM      CZEC  A          13AP2004   04 760 537.3       02AU2006   1618158      13AP2024     NIHC
WATERBASED HIGH ABRASION RESISTANT COATING

3017A.EEM      EPC   A          13AP2004   04 760 537.3       02AU2006   1618158      13AP2024     NIHC
WATERBASED HIGH ABRASION RESISTANT COATING

3017A.EEM      FRAN  A          13AP2004   04 760 537.3       02AU2006   1618158      13AP2024     NIHC
WATERBASED HIGH ABRASION RESISTANT COATING

3017A.EEM      GBRI  A          13AP2004   04 760 537.3       02AU2006   1618158      13AP2024     NIHC
WATERBASED HIGH ABRASION RESISTANT COATING

3017A.EEM      GERM  A          13AP2004   04 760 537.3       02AU2006  602004001778.713AP2024     NIHC
WATERBASED HIGH ABRASION RESISTANT COATING

3017A.EEM      HUNG  A          13AP2004   04 760 537.3       02AU2006   1618158      13AP2024     NIHC
WATERBASED HIGH ABRASION RESISTANT COATING

3017A.EEM      INDI  A          13AP2004   3061/CHENP/2005                                         NIHC
WATERBASED HIGH ABRASION RESISTANT COATING

3017A.EEM      ITAL  A          13AP2004   04 760 537.3       02AU2006   1618158      13AP2024     NIHC
WATERBASED HIGH ABRASION RESISTANT COATING

3017A.EEM      JAPA  A          13AP2004   2006-509961                                             NIHC
WATERBASED HIGH ABRASION RESISTANT COATING

3017A.EEM      KORS  A          13AP2004   10-2005-7019882                                         NIHC
WATERBASED HIGH ABRASION RESISTANT COATING

3017A.EEM      MEXI  A          13AP2004   PA/a/2005/011191                                        NIHC
WATERBASED HIGH ABRASION RESISTANT COATING
```

3017A.EEM	POLA	A	13AP2004	04 760 537.3	02AU2006	1618158	13AP2024	NIHC
WATERBASED HIGH ABRASION RESISTANT COATING								
3017A.EEM	ROMA	A	13AP2004	04 760 537.3	02AU2006	1618158	13AP2024	NIHC
WATERBASED HIGH ABRASION RESISTANT COATING								
3017A.EEM	SLVK	A	13AP2004	04 760 537.3	02AU2006	1618158	13AP2024	NIHC
WATERBASED HIGH ABRASION RESISTANT COATING								
3017A.EEM	SPAI	A	13AP2004	04 760 537.3	02AU2006	2267074	13AP2024	NIHC
WATERBASED HIGH ABRASION RESISTANT COATING								
3017A.EEM	SWED	A	13AP2004	04 760 537.3	02AU2006	1618158	13AP2024	NIHC
WATERBASED HIGH ABRASION RESISTANT COATING								
3017A.EEM	TURK	A	13AP2004	04 760 537.3	02AU2006	TR200604919T4	13AP2024	NIHC
WATERBASED HIGH ABRASION RESISTANT COATING								
3019.PKG	USA	A	02MY2003	10/428,890	19SE2006	7,109,263	02MY2023	NIHC
LABELING ADHESIVE								
3019.PKG	EPC	A	03MY2004	04 751 072.2				NIHC
LABELING ADHESIVE								
3019D.PKG	USA	A	13JE2006	11/451,725				NIHC
LABELING ADHESIVE								
3021.NWN	USA	A	06FE2004	10/773,547				NIHC
IONOMER-CONTAINING HOT MELT ADHESIVE								
3021.NWN	CANA	A	31JA2005	2,554,828				NIHC
IONOMER-CONTAINING HOT MELT ADHESIVE								
3021.NWN	CHIN	A	31JA2005	200580004100.0				NIHC
IONOMER-CONTAINING HOT MELT ADHESIVE								

```
3021.NWN       EPC   A          31JA2005   05 706 138.4                                        NIHC
IONOMER-CONTAINING HOT MELT ADHESIVE


3021.NWN       JAPA  A          31JA2005   2006-552167                                         NIHC
IONOMER-CONTAINING HOT MELT ADHESIVE


3023.PKG       USA   A          03JL2003   10/613,409                                          NIHC
HOT MELT ADHESIVE


3023.PKG       ASTL  A          01JL2004   2004202931                                          NIHC
HOT MELT ADHESIVE


3023.PKG       CHIN  A          01JL2004   200410055293.X                                      NIHC
HOT MELT ADHESIVE


3023.PKG       EPC   A          30JE2004   04 015 388.4                                        NIHC
HOT MELT ADHESIVE


3023.PKG       JAPA  A          01JL2004   2004-195850                                         NIHC
HOT MELT ADHESIVE


3023.PKG       KORS  A          01JL2004   2004-0051184                                        NIHC
HOT MELT ADHESIVE


3025.EEM       USA   EEM        23MY2003   10/444,285                                          NIHC
PRE-APPLIED THERMOPLASTIC REINFORCEMENT FOR ELECTRONIC
COMPONENTS


3025A.EEM      USA   EEM        30JA2004   10/768,910                                          NIHC
PRE-APPLIED THERMOPLASTIC REINFORCEMENT FOR ELECTRONIC
COMPONENTS


3025B.EEM      USA   EEM        30JA2004   10/768,868                                          NIHC
PRE-APPLIED THERMOPLASTIC REINFORCEMENT FOR ELECTRONIC
COMPONENTS
```

3026.EEM	USA	EEM	23MY2003	10/444,867	27DE2005	6,978,540	06FE2024	NIHC
METHOD FOR PRE-APPLIED THERMOPLASTIC REINFORCEMENT OF ELECTRONIC COMPONENTS								
3027.EEM	USA	EEM	23MY2003	10/444,604	28FE2006	7,004,375	18AU2023	NIHC
PRE-APPLIED FLUXING UNDERFILL COMPOSITION HAVING PRESSURE SENSITIVE ADHESIVE PROPERTIES								
3028.EEM	CHIN	EEM	18MY2004	200480013977.1	06FE2008	200480013977.1	18MY2024	NIHC
FOAMABLE UNDERFILL ENCAPSULANT								
3028.EEM	EPC	EEM	18MY2004	04 752 467.3				NIHC
FOAMABLE UNDERFILL ENCAPSULANT								
3028.EEM	JAPA	EEM	18MY2004	2006-533157				NIHC
FOAMABLE UNDERFILL ENCAPSULANT								
3028.EEM	KORS	EEM	18MY2004	10-2005-7022343				NIHC
FOAMABLE UNDERFILL ENCAPSULANT								
3028.EEM	PHIL	EEM	18MY2004	1-2005-501943				NIHC
FOAMABLE UNDERFILL ENCAPSULANT								
3028A.EEM	USA	EEM	18JA2006	11/333,940				NIHC
FOAMABLE UNDERFILL ENCAPSULANT								
3028A.EEM	CHIN	EEM	16JA2007	200710001997.2				NIHC
FOAMABLE UNDERFILL ENCAPSULANT								
3028A.EEM	EPC	EEM	17JA2007	07 000 896.6				NIHC
FOAMABLE UNDERFILL ENCAPSULANT								
3028A.EEM	INDI	EEM	16JA2007	87/CHE/2007				NIHC
FOAMABLE UNDERFILL ENCAPSULANT								

```
3028A.EEM      JAPA  EEM        17JA2007   2007-7967                                                NIHC
FOAMABLE UNDERFILL ENCAPSULANT

3028A.EEM      KORS  EEM        16JA2007   10-2007-0004674                                          NIHC
FOAMABLE UNDERFILL ENCAPSULANT

3028A.EEM      MAYS  EEM        16JA2007   PI 20070073                                              NIHC
FOAMABLE UNDERFILL ENCAPSULANT

3028A.EEM      PHIL  EEM        16JA2007   1-2007-000024                                            NIHC
FOAMABLE UNDERFILL ENCAPSULANT

3028A.EEM      SING  EEM        15JA2007   200700262-9                                              NIHC
FOAMABLE UNDERFILL ENCAPSULANT

3028A.EEM      TAIW  EEM        17JA2007   96101664                                                 NIHC
FOAMABLE UNDERFILL ENCAPSULANT

3029.EEM       USA   EEM        23MY2003   10/444,398         23MY2006   7,047,633    22AP2024     NIHC
METHOD OF USING PRE-APPLIED UNDERFILL ENCAPSULANT

3029.EEM       CHIN  EEM        18MY2004   200480014142.8                                           NIHC
METHOD OF USING PRE-APPLIED UNDERFILL ENCAPSULANT

3029.EEM       EPC   EEM        18MY2004   04 752 556.3                                             NIHC
METHOD OF USING PRE-APPLIED UNDERFILL ENCAPSULANT

3029.EEM       JAPA  EEM        18MY2004   2006-533192                                              NIHC
METHOD OF USING PRE-APPLIED UNDERFILL ENCAPSULANT

3029.EEM       KORS  EEM        18MY2004   10-2005-7022354                                          NIHC
METHOD OF USING PRE-APPLIED UNDERFILL ENCAPSULANT

3029.EEM       PHIL  EEM        18MY2004   1-2005-501944                                            NIHC
METHOD OF USING PRE-APPLIED UNDERFILL ENCAPSULANT
```

```
3029A.EEM      USA   EEM         20OC2004   10/969,588                                                 NIHC
METHOD OF USING PRE-APPLIED UNDERFILL ENCAPSULANT


3030.CRG       USA   A           16JE2003   10/462,183                                                 NIHC
FOAMED ADHESIVE AND APPLICATIONS THEREOF


3031.BDG       USA   A           09JE2003   10/457,260                                                 NIHC
NOVEL REACTIVE HOT MELT ADHESIVES


3031.BDG       ASTL  A           24MY2004   2004247630                                                 NIHC
NOVEL REACTIVE HOT MELT ADHESIVES


3031.BDG       BRAZ  A           24MY2004   0411104-4                                                  NIHC
NOVEL REACTIVE HOT MELT ADHESIVES


3031.BDG       CANA  A           24MY2004   2,528,456                                                  NIHC
NOVEL REACTIVE HOT MELT ADHESIVES


3031.BDG       CHIN  A           24MY2004   200480015898.4                                             NIHC
NOVEL REACTIVE HOT MELT ADHESIVES


3031.BDG       EPC   A           24MY2004   04 753 154.6                                               NIHC
NOVEL REACTIVE HOT MELT ADHESIVES


3031.BDG       JAPA  A           24MY2004   2006-533358                                                NIHC
NOVEL REACTIVE HOT MELT ADHESIVES


3031.BDG       KORS  A           24MY2004   10-2005-7023567                                            NIHC
NOVEL REACTIVE HOT MELT ADHESIVES


3031.BDG       MEXI  A           24MY2004   PA/a/2005/013286                                           NIHC
NOVEL REACTIVE HOT MELT ADHESIVES


3039.NWN       USA   A           06AU2003   10/635,139                                                 NIHC
```

HOT MELT ADHESIVE CONTAINING A NEUTRALIZING ADDITIVE								
3039.NWN	ASTL	A	04AU2004	2004203606				NIHC
HOT MELT ADHESIVE CONTAINING A NEUTRALIZING ADDITIVE								
3039.NWN	CHIN	A	04AU2004	200410079411.0				NIHC
HOT MELT ADHESIVE CONTAINING A NEUTRALIZING ADDITIVE								
3039.NWN	EPC	A	04AU2004	04 018 445.9				NIHC
HOT MELT ADHESIVE CONTAINING A NEUTRALIZING ADDITIVE								
3039.NWN	KORS	A	04AU2004	2004-0061456				NIHC
HOT MELT ADHESIVE CONTAINING A NEUTRALIZING ADDITIVE								
3039.NWN	NEWZ	A	04AU2004	534549	13JL2006	534549	04AU2024	NIHC
HOT MELT ADHESIVE CONTAINING A NEUTRALIZING ADDITIVE								
3039.NWN	TAIW	A	04AU2004	93123286				NIHC
HOT MELT ADHESIVE CONTAINING A NEUTRALIZING ADDITIVE								
3041.EEM	USA	EEM	31JL2003	10/632,330	05AP2005	6,874,573	31JL2023	NIHC
THERMAL INTERFACE MATERIAL								
3041.EEM	CHIN	EEM	30JL2004	200410076624.8				NIHC
THERMAL INTERFACE MATERIAL								
3041.EEM	EPC	EEM	26JL2004	04 017 644.8				NIHC
THERMAL INTERFACE MATERIAL								
3041.EEM	JAPA	EEM	29JL2004	2004-222010				NIHC
THERMAL INTERFACE MATERIAL								
3041.EEM	KORS	EEM	30JL2004	2004-0060296				NIHC
THERMAL INTERFACE MATERIAL								

```
3041.EEM       TAIW  EEM         30JL2004   93122801                                                  NIHC
THERMAL INTERFACE MATERIAL


3042.EEM       MAYS  EEM         26JL2004   PI 20042997                                               NIHC
METHOD FOR PRINTING ELECTROLUMINESCENT LAMPS


3042.EEM       TAIW  EEM         28JL2004   93122469                                                  NIHC
METHOD FOR PRINTING ELECTROLUMINESCENT LAMPS


3044.PKG       USA   A           22AU2003   10/646,417         24AP2007   7,208,541    22AU2023      NIHC
HOT MELT ADHESIVE


3044.PKG       ASTL  A           13FE2004   2004272489                                                NIHC
HOT MELT ADHESIVE


3044.PKG       CHIN  A           13FE2004   200480023259.2                                            NIHC
HOT MELT ADHESIVE


3044.PKG       EPC   A           13FE2004   04 711 154.7                                              NIHC
HOT MELT ADHESIVE


3044.PKG       JAPA  A           13FE2004   2006-523819                                               NIHC
HOT MELT ADHESIVE


3044.PKG       KORS  A           13FE2004   10-2006-7003546                                           NIHC
HOT MELT ADHESIVE


3054.BDG       EPC   A           01OC2004   04 023 386.8                                              NIHC
PRIMER COMPOSITION FOR BONDING POLYMER COMPOSITES WITH
URETHANE ADHESIVES AND SEALANTS


3055.EEM       USA   EEM         15OC2003   10/685,818         06MR2007   7,186,945    15JE2024      NIHC
SPRAYABLE ADHESIVE MATERIAL FOR LASER MARKING SEMICONDUCTOR
WAFERS AND DIES


3055.EEM       CHIN  EEM         15OC2004   200410095119.8                                            NIHC
```

```
SPRAYABLE ADHESIVE MATERIAL FOR LASER MARKING SEMICONDUCTOR
WAFERS, DIES AND DEVICES


3055.EEM       EPC   EEM        14OC2004   04 024 487.3                                             NIHC
SPRAYABLE ADHESIVE MATERIAL FOR LASER MARKING SEMICONDUCTOR
WAFERS, DIES AND DEVICES


3055.EEM       HONG  EEM        25OC2005   05109484.9                                               NIHC
SPRAYABLE ADHESIVE MATERIAL FOR LASER MARKING SEMICONDUCTOR
WAFERS, DIES AND DEVICES


3055.EEM       JAPA  EEM        15OC2004   2004-301706                                              NIHC
SPRAYABLE ADHESIVE MATERIAL FOR LASER MARKING SEMICONDUCTOR
WAFERS, DIES AND DEVICES


3055.EEM       KORS  EEM        14OC2004   10-2004-0082233                                          NIHC
SPRAYABLE ADHESIVE MATERIAL FOR LASER MARKING SEMICONDUCTOR
WAFERS, DIES AND DEVICES


3055.EEM       TAIW  EEM        14OC2004   93131069                                                 NIHC
SPRAYABLE ADHESIVE MATERIAL FOR LASER MARKING SEMICONDUCTOR
WAFERS, DIES AND DEVICES


3056.PKG       USA   A          07OC2003   10/680,276         23JA2007   7,166,662    29AU2024     NIHC
HOT MELT ADHESIVE COMPOSITION


3056.PKG       ASTL  A          05OC2004   2004218621                                               NIHC
HOT MELT ADHESIVE COMPOSITION


3056.PKG       CHIN  A          30SE2004   200410092134.7                                           NIHC
HOT MELT ADHESIVE COMPOSITION


3056.PKG       EPC   A          06OC2004   04 023 796.8       12DE2007   1522566      06OC2024     NIHC
HOT MELT ADHESIVE COMPOSITION


3056.PKG       FRAN  A          06OC2004   04 023 796.8       12DE2007   1522566      06OC2024     NIHC
HOT MELT ADHESIVE COMPOSITION
```

```
3056.PKG       GBRI  A          06OC2004   04 023 796.8       12DE2007   1522566      06OC2024     NIHC
HOT MELT ADHESIVE COMPOSITION

3056.PKG       GERM  A          06OC2004   04 023 796.8       12DE2007  602004010591.106OC2024     NIHC
HOT MELT ADHESIVE COMPOSITION

3056.PKG       ITAL  A          06OC2004   04 023 796.8       12DE2007   1522566      06OC2024     NIHC
HOT MELT ADHESIVE COMPOSITION

3056.PKG       JAPA  A          06OC2004   2004-293329                                             NIHC
HOT MELT ADHESIVE COMPOSITION

3056.PKG       KORS  A          04OC2004   10-2004-0078690                                         NIHC
HOT MELT ADHESIVE COMPOSITION

3056.PKG       NETH  A          06OC2004   04 023 796.8       12DE2007   1522566      06OC2024     NIHC
HOT MELT ADHESIVE COMPOSITION

3056.PKG       SPAI  A          06OC2004   04 023 796.8       12DE2007   1522566      06OC2024     NIHC
HOT MELT ADHESIVE COMPOSITION

3056.PKG       SWIT  A          06OC2004   04 023 796.8       12DE2007   1522566      06OC2024     NIHC
HOT MELT ADHESIVE COMPOSITION

3057.NWN       USA   A          26JL2006   10/587,374                                              NIHC
LOW APPLICATION TEMPERATURE ELASTIC ATTACHMENT ADHESIVE

3057.NWN       CANA  A          31JA2005   2,554,813                                               NIHC
LOW APPLICATION TEMPERATURE ELASTIC ATTACHMENT ADHESIVE

3057.NWN       CHIN  A          31JA2005   200580004098.7                                          NIHC
LOW APPLICATION TEMPERATURE ELASTIC ATTACHMENT ADHESIVE

3057.NWN       EPC   A          31JA2005   05 712 367.1                                            NIHC
```

```
LOW APPLICATION TEMPERATURE ELASTIC ATTACHMENT ADHESIVE


3057.NWN       JAPA  A           31JA2005   2006-552183                                                NIHC
LOW APPLICATION TEMPERATURE ELASTIC ATTACHMENT ADHESIVE


3058.PSA       USA   A           04NO2003   10/700,754         12JE2007   7,230,122    20FE2024     NIHC
SOLFONIUM SALT PHOTOINITIATORS AND USE THEREOF


3058A.PSA      USA   A           16AU2004   10/918,946                                                 NIHC
SOLUBLE SALT PHOTOINITIATORS AND USE THEREOF


3058A.PSA      CHIN  A           04NO2004   200410098187.X                                             NIHC
SOLUBLE SALT PHOTOINITIATORS AND USE THEREOF


3058A.PSA      EPC   A           04NO2004   04 026 159.6                                               NIHC
SOLUBLE SALT PHOTOINITIATORS AND USE THEREOF


3058A.PSA      JAPA  A           04NO2004   2004-320965                                                NIHC
SOLUBLE SALT PHOTOINITIATORS AND USE THEREOF


3058A.PSA      KORS  A           03NO2004   10-2004-0088840                                            NIHC
SOLUBLE SALT PHOTOINITIATORS AND USE THEREOF


3058A.PSA      TAIW  A           03NO2004   93133414                                                   NIHC
SOLUBLE SALT PHOTOINITIATORS AND USE THEREOF


3058D.PSA      USA   A           26AP2007   11/789,873                                                 NIHC
SOLFONIUM SALT PHOTOINITIATORS AND USE THEREOF


3064.EEM       USA   EEM         04DE2003   10/727,951                                                 NIHC
UV CURABLE PROTECTIVE ENCAPSULANT


3064.EEM       CHIN  EEM         03DE2004   200410104723.2                                             NIHC
UV CURABLE PROTECTIVE ENCAPSULANT
```

```
3064.EEM       JAPA  EEM        29NO2004   2004-344103                                    NIHC
UV CURABLE PROTECTIVE ENCAPSULANT


3064.EEM       KORS  EEM        02DE2004   10-2004-0100281                                NIHC
UV CURABLE PROTECTIVE ENCAPSULANT


3064.EEM       TAIW  EEM        03DE2004   93137262                                       NIHC
UV CURABLE PROTECTIVE ENCAPSULANT


3066.EEM       USA   EEM        02NO2005   10/555,291                                     NIHC
ASSEMBLY OF A SEMICONDUCTOR DIE ATTACHED TO SUBSTRATE WITH
OXAZOLINE DERIVATIVE BEARING AN ELECTRON DONOR OR ACCEPTOR


3066.EEM       CHIN  EEM        17FE2004   200480016947.6                                 NIHC
ASSEMBLY OF A SEMICONDUCTOR DIE ATTACHED TO SUBSTRATE WITH
OXAZOLINE DERIVATIVE BEARING AN ELECTRON DONOR OR ACCEPTOR


3066.EEM       HONG  EEM        09JA2007   07100295.5                                     NIHC
ASSEMBLY OF A SEMICONDUCTOR DIE ATTACHED TO SUBSTRATE WITH
OXAZOLINE DERIVATIVE BEARING AN ELECTRON DONOR OR ACCEPTOR


3066.EEM       ISRA  EEM        17FE2004   171334                                         NIHC
ASSEMBLY OF A SEMICONDUCTOR DIE ATTACHED TO SUBSTRATE WITH
OXAZOLINE DERIVATIVE BEARING AN ELECTRON DONOR OR ACCEPTOR


3066.EEM       JAPA  EEM        17FE2004   2006-553103                                    NIHC
ASSEMBLY OF A SEMICONDUCTOR DIE ATTACHED TO SUBSTRATE WITH
OXAZOLINE DERIVATIVE BEARING AN ELECTRON DONOR OR ACCEPTOR


3066.EEM       KORS  EEM        17FE2004   10-2005-7022833                                NIHC
ASSEMBLY OF A SEMICONDUCTOR DIE ATTACHED TO SUBSTRATE WITH
OXAZOLINE DERIVATIVE BEARING AN ELECTRON DONOR OR ACCEPTOR


3066.EEM       SING  EEM        17FE2004   200506529-7                                    NIHC
ASSEMBLY OF A SEMICONDUCTOR DIE ATTACHED TO SUBSTRATE WITH
OXAZOLINE DERIVATIVE BEARING AN ELECTRON DONOR OR ACCEPTOR
```

```
3066.EEM       TAIW  EEM         16FE2005   94104380                                                NIHC
ASSEMBLY OF A SEMICONDUCTOR DIE ATTACHED TO SUBSTRATE WITH
OXAZOLINE DERIVATIVE BEARING AN ELECTRON DONOR OR ACCEPTOR


3067.EEM       USA   EEM         10NO2005   10/556,193                                              NIHC
CURABLE LIQUID COMPOSITIONS CONTAINING BISOXAZOLINE


3067.EEM       EPC   EEM         17FE2004   04 711 916.9                                            NIHC
CURABLE LIQUID COMPOSITIONS CONTAINING BISOXAZOLINE


3067.EEM       SING  EEM         17FE2004   200506528-9        31JA2008   116203       17FE2024     NIHC
CURABLE LIQUID COMPOSITIONS CONTAINING BISOXAZOLINE


3067.EEM       TAIW  EEM         16FE2005   94104381                                                NIHC
CURABLE LIQUID COMPOSITIONS CONTAINING BISOXAZOLINE


3068.CRG       USA   A           30DE2003   10/748,908         07DE2004   6,827,784    30DE2023     NIHC
CORRUGATING METHOD AND MEANS


3068.CRG       CANA  A           29DE2004   2,491,201                                               NIHC
CORRUGATING METHOD AND MEANS


3070.EEM       USA   EEM         16SE2005   10/549,899                                              NIHC
MALEIMIDE RESIN WITH CYANURATE CORE


3070.EEM       CHIN  EEM         16JA2004   200480040077.6                                          NIHC
MALEIMIDE RESIN WITH CYANURATE CORE


3070.EEM       EPC   EEM         16JA2004   04 702 931.9                                            NIHC
MALEIMIDE RESIN WITH CYANURATE CORE


3070.EEM       HONG  EEM         16JL2007   07107605.5                                              NIHC
MALEIMIDE RESIN WITH CYANURATE CORE


3070.EEM       JAPA  EEM         16JA2004   2006-549217                                             NIHC
MALEIMIDE RESIN WITH CYANURATE CORE
```

```
3070.EEM       KORS  EEM        16JA2004   10-2005-7020070                                   NIHC
MALEIMIDE RESIN WITH CYANURATE CORE


3070.EEM       TAIW  EEM        14FE2005   94104211                                          NIHC
MALEIMIDE RESIN WITH CYANURATE CORE


3071.TDM       USA   A          20FE2004   10/783,080                                        NIHC
DISSOLVABLE FILM AND METHOD OF MANUFACTURE


3071.TDM       CHIN  A          18FE2005   200580005171.2                                    NIHC
DISSOLVABLE FILM AND METHOD OF MANUFACTURE


3071.TDM       EPC   A          18FE2005   05 723 811.5                                      NIHC
DISSOLVABLE FILM AND METHOD OF MANUFACTURE


3071.TDM       JAPA  A          18FE2005   2006-554335                                       NIHC
DISSOLVABLE FILM AND METHOD OF MANUFACTURE


3073.NWN       USA   A          13FE2004   10/779,420                                        NIHC
ADHESIVE CONTAINING RADIAL BLOCK COPOLYMER


3073.NWN       ASTL  A          10FE2005   2005200590                                        NIHC
ADHESIVE CONTAINING RADIAL BLOCK COPOLYMER


3073.NWN       CHIN  A          08FE2005   200510009470.5                                    NIHC
ADHESIVE CONTAINING RADIAL BLOCK COPOLYMER


3073.NWN       EPC   A          10FE2005   05 002 788.7                                      NIHC
ADHESIVE CONTAINING RADIAL BLOCK COPOLYMER


3073.NWN       JAPA  A          10FE2005   2005-34127                                        NIHC
ADHESIVE CONTAINING RADIAL BLOCK COPOLYMER


3073.NWN       KORS  A          11FE2005   10-2005-0011674                                   NIHC
```

```
ADHESIVE CONTAINING RADIAL BLOCK COPOLYMER


3074.NWN       USA   A           13FE2004   10/779,492                                            NIHC
ADHESIVE CONTAINING RADIAL BLOCK COPOLYMER


3074.NWN       ASTL  A           10FE2005   2005200588                                            NIHC
ADHESIVE CONTAINING RADIAL BLOCK COPOLYMER


3074.NWN       CHIN  A           08FE2005   200510051635.5                                        NIHC
ADHESIVE CONTAINING RADIAL BLOCK COPOLYMER


3074.NWN       EPC   A           10FE2005   05 002 787.9                                          NIHC
ADHESIVE CONTAINING RADIAL BLOCK COPOLYMER


3074.NWN       JAPA  A           10FE2005   2005-34760                                            NIHC
ADHESIVE CONTAINING RADIAL BLOCK COPOLYMER


3074.NWN       KORS  A           11FE2005   10-2005-0011670                                       NIHC
ADHESIVE CONTAINING RADIAL BLOCK COPOLYMER


3075.NWN       USA   A           13FE2004   10/779,505                                            NIHC
ELASTIC ATTACHMENT ADHESIVE CONTAINING RADIAL BLOCK
COPOLYMER


3075.NWN       ASTL  A           10FE2005   2005200594                                            NIHC
ELASTIC ATTACHMENT ADHESIVE CONTAINING RADIAL BLOCK
COPOLYMER


3075.NWN       CHIN  A           08FE2005   200510051870.2                                        NIHC
ELASTIC ATTACHMENT ADHESIVE CONTAINING RADIAL BLOCK
COPOLYMER


3075.NWN       EPC   A           10FE2005   05 002 789.5                                          NIHC
ELASTIC ATTACHMENT ADHESIVE CONTAINING RADIAL BLOCK
COPOLYMER
```

3075.NWN	JAPA	A	10FE2005	2005-34259				NIHC	ELASTIC ATTACHMENT ADHESIVE CONTAINING RADIAL BLOCK COPOLYMER
3075.NWN	KORS	A	11FE2005	10-2005-0011673				NIHC	ELASTIC ATTACHMENT ADHESIVE CONTAINING RADIAL BLOCK COPOLYMER
3080.BDG	USA	A	26MR2004	10/810,772				NIHC	NOVEL REACTIVE HOT MELT ADHESIVES
3080.BDG	ASTL	A	21MR2005	2005233529				NIHC	NOVEL REACTIVE HOT MELT ADHESIVES
3080.BDG	CANA	A	21MR2005	2,558,361				NIHC	NOVEL REACTIVE HOT MELT ADHESIVES
3080.BDG	CHIN	A	21MR2005	200580008273X				NIHC	NOVEL REACTIVE HOT MELT ADHESIVES
3080.BDG	EPC	A	21MR2005	05 729 696.4				NIHC	NOVEL REACTIVE HOT MELT ADHESIVES
3080.BDG	KORS	A	21MR2005	10-2006-7019883				NIHC	NOVEL REACTIVE HOT MELT ADHESIVES
3080.BDG	RUSS	A	21MR2005	2006137722				NIHC	NOVEL REACTIVE HOT MELT ADHESIVES
3082.EEM	USA	EEM	01AP2004	10/815,442	09JA2007	7,160,946	01AP2024	NIHC	METHOD TO IMPROVE HIGH TEMPERATURE COHESIVE STRENGTH WITH ADHESIVE HAVING MULTI-PHASE SYSTEM
3082.EEM	CHIN	EEM	01AP2005	200510065532.4				NIHC	METHOD TO IMPROVE HIGH TEMPERATURE COHESIVE STRENGTH WITH ADHESIVE HAVING MULTI-PHASE SYSTEM

```
3082.EEM       EPC   EEM         30MR2005   05 006 864.2       27DE2006   1582574      30MR2025    NIHC
METHOD TO IMPROVE HIGH TEMPERATURE COHESIVE STRENGTH WITH
ADHESIVE HAVING MULTI-PHASE SYSTEM


3082.EEM       FRAN  EEM         30MR2005   05 006 864.2       27DE2006   1582574      30MR2025    NIHC
METHOD TO IMPROVE HIGH TEMPERATURE COHESIVE STRENGTH WITH
ADHESIVE HAVING MULTI-PHASE SYSTEM


3082.EEM       GBRI  EEM         30MR2005   05 006 864.2       27DE2006   1582574      30MR2025    NIHC
METHOD TO IMPROVE HIGH TEMPERATURE COHESIVE STRENGTH WITH
ADHESIVE HAVING MULTI-PHASE SYSTEM


3082.EEM       GERM  EEM         30MR2005   05 006 864.2       27DE2006  602005000365.730MR2025    NIHC
METHOD TO IMPROVE HIGH TEMPERATURE COHESIVE STRENGTH WITH
ADHESIVE HAVING MULTI-PHASE SYSTEM


3082.EEM       HONG  EEM         16FE2006   06102020.4                                             NIHC
METHOD TO IMPROVE HIGH TEMPERATURE COHESIVE STRENGTH WITH
ADHESIVE HAVING MULTI-PHASE SYSTEM


3082.EEM       ITAL  EEM         30MR2005   05 006 864.2       27DE2006   1582574      30MR2025    NIHC
METHOD TO IMPROVE HIGH TEMPERATURE COHESIVE STRENGTH WITH
ADHESIVE HAVING MULTI-PHASE SYSTEM


3082.EEM       JAPA  EEM         31MR2005   2005-100639                                            NIHC
METHOD TO IMPROVE HIGH TEMPERATURE COHESIVE STRENGTH WITH
ADHESIVE HAVING MULTI-PHASE SYSTEM


3082.EEM       KORS  EEM         28MR2005   10-2005-0025635                                        NIHC
METHOD TO IMPROVE HIGH TEMPERATURE COHESIVE STRENGTH WITH
ADHESIVE HAVING MULTI-PHASE SYSTEM


3082.EEM       SING  EEM         29MR2005   200501886-6        31AU2007   115812       29MR2025    NIHC
METHOD TO IMPROVE HIGH TEMPERATURE COHESIVE STRENGTH WITH
ADHESIVE HAVING MULTI-PHASE SYSTEM


3082.EEM       TAIW  EEM         31MR2005   94110162                                               NIHC
```

```
METHOD TO IMPROVE HIGH TEMPERATURE COHESIVE STRENGTH WITH
ADHESIVE HAVING MULTI-PHASE SYSTEM

3083.EEM       USA   EEM        01AP2004   10/815,420                                        NIHC
DICING DIE BONDING FILM

3083.EEM       CHIN  EEM        01AP2005   200510069745.4                                    NIHC
DICING DIE BONDING FILM

3083.EEM       EPC   EEM        29MR2005   05 006 799.0                                      NIHC
DICING DIE BONDING FILM

3083.EEM       HONG  EEM        27FE2006   06102588.8                                        NIHC
DICING DIE BONDING FILM

3083.EEM       JAPA  EEM        31MR2005   2005-100699                                       NIHC
DICING DIE BONDING FILM

3083.EEM       KORS  EEM        01AP2005   10-2005-0027607                                   NIHC
DICING DIE BONDING FILM

3083.EEM       SING  EEM        29MR2005   200501883-3                                       NIHC
DICING DIE BONDING FILM

3083.EEM       TAIW  EEM        31MR2005   94110164                                          NIHC
DICING DIE BONDING FILM

3083A.EEM      USA   EEM        31AU2006   11/514,556                                        NIHC
DICING DIE BONDING FILM

3083A.EEM      CHIN  EEM        29AU2007   200710147777.0                                    NIHC
DICING DIE BONDING FILM

3083A.EEM      EPC   EEM        28AU2007   07 016 822.4                                      NIHC
DICING DIE BONDING FILM
```

```
3083A.EEM      JAPA  EEM         30AU2007   2007-223745                                         NIHC
DICING DIE BONDING FILM

3083A.EEM      KORS  EEM         30AU2007   10-2007-0087561                                     NIHC
DICING DIE BONDING FILM

3083A.EEM      SING  EEM         30AU2007   200706372-0                                         NIHC
DICING DIE BONDING FILM

3083A.EEM      TAIW  EEM         30AU2007   96132166                                            NIHC
DICING DIE BONDING FILM

3084.EEM       USA   EEM         01AP2004   10/816,093                                          NIHC
METHOD FOR REDUCING FREEZE-THAW VOIDS IN UNCURED ADHESIVES

3084.EEM       CHIN  EEM         01AP2005   200510069784.4                                      NIHC
METHOD FOR REDUCING FREEZE-THAW VOIDS IN UNCURED ADHESIVES

3084.EEM       EPC   EEM         29MR2005   05 006 798.2                                        NIHC
METHOD FOR REDUCING FREEZE-THAW VOIDS IN UNCURED ADHESIVES

3084.EEM       HONG  EEM         29JA2007   07101017.0                                          NIHC
METHOD FOR REDUCING FREEZE-THAW VOIDS IN UNCURED ADHESIVES

3084.EEM       JAPA  EEM         31MR2005   2005-100716                                         NIHC
METHOD FOR REDUCING FREEZE-THAW VOIDS IN UNCURED ADHESIVES

3084.EEM       KORS  EEM         28MR2005   10-2005-0025636                                     NIHC
METHOD FOR REDUCING FREEZE-THAW VOIDS IN UNCURED ADHESIVES

3084.EEM       SING  EEM         29MR2005   200501884-1                                         NIHC
METHOD FOR REDUCING FREEZE-THAW VOIDS IN UNCURED ADHESIVES

3084.EEM       TAIW  EEM         31MR2005   94110163                                            NIHC
METHOD FOR REDUCING FREEZE-THAW VOIDS IN UNCURED ADHESIVES
```

```
3084D.EEM      USA   EEM        30MY2006   11/402,170                                               NIHC
METHOD FOR REDUCING FREEZE-THAW VOIDS IN UNCURED ADHESIVES


3086.EEM       USA   A          29MR2004   10/812,134                                               NIHC
ULTRAVIOLET-CURABLE WATERBORNE COATING


3087.BDG       USA   A          06AP2004   10/818,673         21NO2006   7,138,466    04AP2023     NIHC
REACTIVE HOT MELT ADHESIVE WITH IMPROVED PROPERTIES


3088.CRG       USA   A          01DE2005   11/291,367                                               NIHC
METHOD FOR PREPARING FILTERS


3088.CRG       CANA  A          06DE2005   2,528,998                                                NIHC
METHOD FOR PREPARING FILTERS


3088.CRG       EPC   A          01DE2005   05 026 171.8                                             NIHC
METHOD FOR PREPARING FILTERS


3088.CRG       MEXI  A          05DE2005   PA/a/2005/013246                                         NIHC
METHOD FOR PREPARING FILTERS


3095.EEM       CHIN  EEM        30AP2005   200510078334.1                                           NIHC
TERMINATION COATING


3095.EEM       EPC   EEM        04MY2005   05 009 791.4                                             NIHC
TERMINATION COATING


3095.EEM       INDO  EEM        06MY2005   P-200500231                                              NIHC
TERMINATION COATING


3095.EEM       ISRA  EEM        03MY2005   168352                                                   NIHC
TERMINATION COATING


3095.EEM       JAPA  EEM        06MY2005   2005-134847                                              NIHC
```

```
TERMINATION COATING

3095.EEM       KORS  EEM         04MY2005   10-2005-0037615                                        NIHC
TERMINATION COATING

3095.EEM       MAYS  EEM         03MY2005   PI 20051963                                            NIHC
TERMINATION COATING

3095.EEM       SING  EEM         04MY2005   200502838-6                                            NIHC
TERMINATION COATING

3095.EEM       TAIW  EEM         05MY2005   94114472                                               NIHC
TERMINATION COATING

3096.EEM       CHIN  EEM         08MY2005   200510078335.6                                         NIHC
COMPOSITIONS FOR USE IN ELECTRONICS DEVICES

3096.EEM       EPC   EEM         04MY2005   05 009 792.2                                           NIHC
COMPOSITIONS FOR USE IN ELECTRONICS DEVICES

3096.EEM       INDO  EEM         06MY2005   W-200500230                                            NIHC
COMPOSITIONS FOR USE IN ELECTRONICS DEVICES

3096.EEM       ISRA  EEM         03MY2005   168353                                                 NIHC
COMPOSITIONS FOR USE IN ELECTRONICS DEVICES

3096.EEM       JAPA  EEM         06MY2005   2005-135069                                            NIHC
COMPOSITIONS FOR USE IN ELECTRONICS DEVICES

3096.EEM       KORS  EEM         04MY2005   10-2005-0037621                                        NIHC
COMPOSITIONS FOR USE IN ELECTRONICS DEVICES

3096.EEM       MAYS  EEM         04MY2005   PI 20051990                                            NIHC
COMPOSITIONS FOR USE IN ELECTRONICS DEVICES
```

```
3096.EEM      SING  EEM        04MY2005   200502839-4                                                NIHC
COMPOSITIONS FOR USE IN ELECTRONICS DEVICES


3096.EEM      TAIW  EEM        05MY2005   94114471                                                   NIHC
COMPOSITIONS FOR USE IN ELECTRONICS DEVICES


3096D.EEM     USA   EM         13AP2007   11/734,988                                                 NIHC
COMPOSITIONS FOR USE IN ELECTRONICS DEVICES


3098.PKG      USA   A          21MY2004   10/851,584       12DE2006   7,148,284    21MY2024      NIHC
HOT MELT ADHESIVE


3098.PKG      CANA  A          20MY2005   2,565,356                                                  NIHC
HOT MELT ADHESIVE


3098.PKG      CHIN  A          20MY2005   200580016132.2                                             NIHC
HOT MELT ADHESIVE


3098.PKG      EPC   A          20MY2005   05 779 985.0                                               NIHC
HOT MELT ADHESIVE


3098.PKG      JAPA  A          20MY2005   2007-527460                                                NIHC
HOT MELT ADHESIVE


3100.PKG      USA   A          14JE2005   11/152,430                                                 NIHC
SYSTEM FOR DISPENSING VISCOUS LIQUIDS


3100.PKG      EPC   A          15JE2005   05 786 255.9                                               NIHC
SYSTEM FOR DISPENSING VISCOUS LIQUIDS


3101.EEM      USA   EEM        29JL2004   10/901,631       12JE2007   7,230,055    02NO2025      NIHC
COMPOSITIONS CONTAINING OXETANE COMPOUNDS FOR USE IN
SEMICONDUCTOR PACKAGING


3101.EEM      CHIN  EEM        29JL2005   200510109831.3                                             NIHC
COMPOSITIONS CONTAINING OXETANE COMPOUNDS FOR USE IN
```

```
SEMICONDUCTOR PACKAGING


3101.EEM       EPC   EEM         27JL2005   05 016 295.7                                              NIHC
COMPOSITIONS CONTAINING OXETANE COMPOUNDS FOR USE IN
SEMICONDUCTOR PACKAGING


3101.EEM       HONG  EEM         05SE2006   06109856.8                                                NIHC
COMPOSITIONS CONTAINING OXETANE COMPOUNDS FOR USE IN
SEMICONDUCTOR PACKAGING


3101.EEM       JAPA  EEM         28JL2005   2005-219085                                               NIHC
COMPOSITIONS CONTAINING OXETANE COMPOUNDS FOR USE IN
SEMICONDUCTOR PACKAGING


3101.EEM       KORS  EEM         28JL2005   10-2005-0068962                                           NIHC
COMPOSITIONS CONTAINING OXETANE COMPOUNDS FOR USE IN
SEMICONDUCTOR PACKAGING


3101.EEM       TAIW  EEM         28JL2005   94125511                                                  NIHC
COMPOSITIONS CONTAINING OXETANE COMPOUNDS FOR USE IN
SEMICONDUCTOR PACKAGING


3102.EEM       USA   EEM         29JL2004   10/901,861         14NO2006   7,135,535    20JA2025     NIHC
SILOXANE RESINS WITH OXETANE FUNCTIONALITY


3102A.EEM      USA   EEM         16AU2006   11/505,083                                                NIHC
SILOXANE RESINS WITH OXETANE FUNCTIONALITY


3105.ADH       USA   A           22DE2006   11/630,853                                                NIHC
PROCESS TO GENERATE WATER BASED ADHESIVES AND THEIR USE


3105.ADH       EPC   A           23JE2004   04 014 710.0       02MY2007   1609834      23JE2024     NIHC
PROCESS TO GENERATE WATER BASED ADHESIVES AND THEIR USE


3105.ADH       GERM  A           23JE2004   04 014 710.0       02MY2007  602004006242.123JE2024     NIHC
PROCESS TO GENERATE WATER BASED ADHESIVES AND THEIR USE
```

```
3105.ADH       ITAL  A           23JE2004   04 014 710.0       02MY2007   1609834      23JE2024     NIHC
PROCESS TO GENERATE WATER BASED ADHESIVES AND THEIR USE


3105.ADH       SPAI  A           23JE2004   04 014 710.0       02MY2007   1609834      23JE2024     NIHC
PROCESS TO GENERATE WATER BASED ADHESIVES AND THEIR USE


3114.EEM       CHIN  EEM         06JL2005   200580021116.2                                          NIHC
MALEIMIDE-BASED RADIATION CURABLE COMPOSITIONS



3114.EEM       EPC   EEM         06JL2005   05 764 517.8                                            NIHC
MALEIMIDE-BASED RADIATION CURABLE COMPOSITIONS


3114.EEM       JAPA  EEM         06JL2005   2007-521500                                             NIHC
MALEIMIDE-BASED RADIATION CURABLE COMPOSITIONS


3114.EEM       KORS  EEM         06JL2005   10-2007-7000480                                         NIHC
MALEIMIDE-BASED RADIATION CURABLE COMPOSITIONS


3116.PKG       USA   A           14SE2004   10/940,520                                              NIHC
LABELING ADHESIVE AND USE THEREOF


3116.PKG       CHIN  A           13SE2005   200580030659.0                                          NIHC
LABELING ADHESIVE AND USE THEREOF


3116.PKG       EPC   A           13SE2005   05 798 641.6                                            NIHC
LABELING ADHESIVE AND USE THEREOF


3120.BDG       USA   A           19OC2004   10/968,658                                              NIHC
REACTIVE HOT MELT ADHESIVE WITH BLOCK ACRYLIC COPOLYMER


3120.BDG       CHIN  A           14OC2005   200510128352.6                                          NIHC
REACTIVE HOT MELT ADHESIVE WITH BLOCK ACRYLIC COPOLYMER


3120.BDG       EPC   A           10OC2005   05 022 031.8                                            NIHC
```

```
REACTIVE HOT MELT ADHESIVE WITH BLOCK ACRYLIC COPOLYMER


3120.BDG       JAPA  A          13OC2005   2005-298772                                     NIHC
REACTIVE HOT MELT ADHESIVE WITH BLOCK ACRYLIC COPOLYMER


3120.BDG       TAIW  A          14OC2005   94135791                                        NIHC
REACTIVE HOT MELT ADHESIVE WITH BLOCK ACRYLIC COPOLYMER


3122.PSA       USA   A          18NO2005   11/282,510                                      NIHC
HOT MELT ADHESIVES FOR MEDICAL APPLICATION


3122.PSA       EPC   A          21NO2005   05 025 345.9                                    NIHC
HOT MELT ADHESIVE FOR MEDICAL APPLICATIONS


3122.PSA       JAPA  A          18NO2005   2005-333507                                     NIHC
HOT MELT ADHESIVE FOR MEDICAL APPLICATIONS


3122.PSA       TAIW  A          21NO2005   94140739                                        NIHC
HOT MELT ADHESIVE FOR MEDICAL APPLICATIONS


3123.EM        USA   EM         24NO2004   10/997,350                                      NIHC
LOW TEMPERATURE SNAP CURE MATERIAL WITH SUITABLE WORKLIFE


3123.EM        CHIN  EM         21NO2005   200510124190.9                                  NIHC
LOW TEMPERATURE SNAP CURE MATERIAL WITH SUITABLE WORKLIFE


3123.EM        EPC   EM         21NO2005   05 025 344.2                                    NIHC
LOW TEMPERATURE SNAP CURE MATERIAL WITH SUITABLE WORKLIFE


3123.EM        JAPA  EM         18NO2005   2005-333652                                     NIHC
LOW TEMPERATURE SNAP CURE MATERIAL WITH SUITABLE WORKLIFE


3123.EM        KORS  EM         21NO2005   10-2005-0111293                                 NIHC
LOW TEMPERATURE SNAP CURE MATERIAL WITH SUITABLE WORKLIFE
```

```
3123.EM        MAYS  EM          18NO2005   PI 20055418                                          NIHC
LOW TEMPERATURE SNAP CURE MATERIAL WITH SUITABLE WORKLIFE


3123.EM        PHIL  EM          18NO2005   1-2005-000566                                        NIHC
LOW TEMPERATURE SNAP CURE MATERIAL WITH SUITABLE WORKLIFE


3123.EM        TAIW  EM          21NO2005   94140734                                             NIHC
LOW TEMPERATURE SNAP CURE MATERIAL WITH SUITABLE WORKLIFE


3123.EM        THAI  EM          18NO2005   106270                                               NIHC
LOW TEMPERATURE SNAP CURE MATERIAL WITH SUITABLE WORKLIFE


3124.TDM       USA   A           22SE2006   11/526,131                                           NIHC
ACRYLIC POLYMER-BASED ADHESIVES


3124.TDM       PCT   A           22SE2006   PCT/US06/37066                                       NIHC
ACRYLIC POLYMER-BASED ADHESIVES


3125.TDM       USA   A           01FE2005   11/047,924                                           NIHC
SOLUTION FOR PRESSURE SENSITIVE ADHESIVES BASED ON ACRYLIC
BLOCK COPOLYMERS


3125.TDM       CANA  A           26JA2006   2,534,023                                            NIHC
SOLUTION FOR PRESSURE SENSITIVE ADHESIVES BASED ON ACRYLIC
BLOCK COPOLYMERS


3125.TDM       CHIN  A           26JA2006   2006100029753                                        NIHC
SOLUTION FOR PRESSURE SENSITIVE ADHESIVES BASED ON ACRYLIC
BLOCK COPOLYMERS


3125.TDM       EPC   A           26JA2006   06 001 598.9                                         NIHC
SOLUTION FOR PRESSURE SENSITIVE ADHESIVES BASED ON ACRYLIC
BLOCK COPOLYMERS


3125.TDM       JAPA  A           27JA2006   2006-18508                                           NIHC
SOLUTION FOR PRESSURE SENSITIVE ADHESIVES BASED ON ACRYLIC
BLOCK COPOLYMERS
```

```
3125.TDM       KORS  A           27JA2006   10-2006-0009092                                   NIHC
SOLUTION FOR PRESSURE SENSITIVE ADHESIVES BASED ON ACRYLIC
BLOCK COPOLYMERS

3126.PSA       USA   A           29DE2004   11/024,570                                        NIHC
PHOTOINITIATORS AND UV-CROSSLINKABLE ACRYLIC POLYMERS FOR
PRESSURE SENSITIVE ADHESIVES

3126.PSA       ASTL  A           15DE2005   2005244547                                        NIHC
PHOTOINITIATORS AND UV-CROSSLINKABLE ACRYLIC POLYMERS FOR
PRESSURE SENSITIVE ADHESIVES

3126.PSA       CHIN  A           15DE2005   200510131892.X                                    NIHC
PHOTOINITIATORS AND UV-CROSSLINKABLE ACRYLIC POLYMERS FOR
PRESSURE SENSITIVE ADHESIVES

3126.PSA       EPC   A           20DE2005   05 027 956.1                                      NIHC
PHOTOINITIATORS AND UV-CROSSLINKABLE ACRYLIC POLYMERS FOR
PRESSURE SENSITIVE ADHESIVES

3126.PSA       JAPA  A           22DE2005   2005-369991                                       NIHC
PHOTOINITIATORS AND UV-CROSSLINKABLE ACRYLIC POLYMERS FOR
PRESSURE SENSITIVE ADHESIVES

3126.PSA       KORS  A           23DE2005   10-2005-0128956                                   NIHC
PHOTOINITIATORS AND UV-CROSSLINKABLE ACRYLIC POLYMERS FOR
PRESSURE SENSITIVE ADHESIVES
3126.PSA       TAIW  A           23DE2005   94145978                                          NIHC
PHOTOINITIATORS AND UV-CROSSLINKABLE ACRYLIC POLYMERS FOR
PRESSURE SENSITIVE ADHESIVES

3127.TOB       USA   A           27DE2004   11/023,052                                        NIHC
TRIACETIN RESISTANT HOT MELT ADHESIVE

3128.TDM       USA   A           22SE2006   11/526,135                                        NIHC
ACRYLIC POLYMER-BASED ADHESIVES
```

```
3128.TDM      PCT   A          22SE2006   PCT/US06/37067                                               NIHC
ACRYLIC POLYMER-BASED ADHESIVES


3133.EM       USA   EEM        09FE2005   11/054,164                                                   NIHC
PACKAGE OR PRE-APPLIED FOAMABLE UNDERFILL FOR LEAD-FREE
PROCESS


3133.EM       CANA  EEM        09FE2006   2,535,757                                                    NIHC
PACKAGE OR PRE-APPLIED FOAMABLE UNDERFILL FOR LEAD-FREE
PROCESS


3133.EM       CHIN  EEM        06FE2006   200610003264.8                                               NIHC
PACKAGE OR PRE-APPLIED FOAMABLE UNDERFILL FOR LEAD-FREE
PROCESS


3133.EM       EPC   EEM        02FE2006   06 002 131.8                                                 NIHC
PACKAGE OR PRE-APPLIED FOAMABLE UNDERFILL FOR LEAD-FREE
PROCESS


3133.EM       INDI  EEM        01FE2006   164/CHE/2006                                                 NIHC
PACKAGE OR PRE-APPLIED FOAMABLE UNDERFILL FOR LEAD-FREE
PROCESS


3133.EM       JAPA  EEM        06FE2006   2006-27831                                                   NIHC
PACKAGE OR PRE-APPLIED FOAMABLE UNDERFILL FOR LEAD-FREE
PROCESS


3133.EM       KORS  EEM        07FE2006   10-2006-0011674                                              NIHC
PACKAGE OR PRE-APPLIED FOAMABLE UNDERFILL FOR LEAD-FREE
PROCESS


3133.EM       TAIW  EEM        07FE2006   95103962                                                     NIHC
PACKAGE OR PRE-APPLIED FOAMABLE UNDERFILL FOR LEAD-FREE
PROCESS


3136.EM       USA   EM         07MR2005   11/073,778       05FE2008   7,326,369    22JE2025     NIHC
```

						LOW STRESS CONDUCTIVE ADHESIVE
3136.EM	CHIN	EM	03MR2006	200610058371.0	NIHC	LOW STRESS CONDUCTIVE ADHESIVE
3136.EM	EPC	EM	06MR2006	06 004 488.0	NIHC	LOW STRESS CONDUCTIVE ADHESIVE
3136.EM	JAPA	EM	03MR2006	2006-57140	NIHC	LOW STRESS CONDUCTIVE ADHESIVE
3136.EM	KORS	EM	06MR2006	10-2006-0020908	NIHC	LOW STRESS CONDUCTIVE ADHESIVE
3136.EM	TAIW	EM	06MR2006	95107344	NIHC	LOW STRESS CONDUCTIVE ADHESIVE
3137.BDG	USA	A	28FE2006	11/364,301	NIHC	PEELABLE HOT MELT ADHESIVE
3137.BDG	ASTL	A	06MR2006	2006200949	NIHC	PEELABLE HOT MELT ADHESIVE
3137.BDG	BRAZ	A	13MR2006	0600820-8	NIHC	PEELABLE HOT MELT ADHESIVE
3137.BDG	CHIN	A	08MR2006	200610057304.7	NIHC	PEELABLE HOT MELT ADHESIVE
3137.BDG	EPC	A	11MR2005	05 005 358.6	NIHC	PEELABLE HOT MELT ADHESIVE
3137.BDG	INDI	A	08MR2006	414/CHE/2006	NIHC	PEELABLE HOT MELT ADHESIVE

```
3137.BDG       JAPA  A          10MR2006   2006-64977                                        NIHC
PEELABLE HOT MELT ADHESIVE

3137.BDG       KORS  A          10MR2006   10-2006-0022483                                   NIHC
PEELABLE HOT MELT ADHESIVE

3137.BDG       MAYS  A          01MR2006   PI 20060876                                       NIHC
PEELABLE HOT MELT ADHESIVE

3137.BDG       MEXI  A          08MR2006   PA/a/2006/002685                                  NIHC
PEELABLE HOT MELT ADHESIVE

3137.BDG       TAIW  A          10MR2006   95108033                                          NIHC
PEELABLE HOT MELT ADHESIVE

3137.BDG       THAI  A          24FE2006   108978                                            NIHC
PEELABLE HOT MELT ADHESIVE

3139.EM        USA   EM         04AP2005   11/098,115                                        NIHC
RADIATION CURABLE CYCLOALIPHATIC BARRIER SEALANTS

3139.EM        CHIN  EM         03AP2006   200680010879.1                                    NIHC
RADIATION CURABLE CYCLOALIPHATIC BARRIER SEALANTS

3139.EM        EPC   EM         03AP2006   06 749 107.6                                      NIHC
RADIATION CURABLE CYCLOALIPHATIC BARRIER SEALANTS

3139.EM        JAPA  EM         03AP2006   2008-505403                                       NIHC
RADIATION CURABLE CYCLOALIPHATIC BARRIER SEALANTS


3139.EM        KORS  EM         03AP2006   10-2007-7024674                                   NIHC
RADIATION CURABLE CYCLOALIPHATIC BARRIER SEALANTS


3139.EM        TAIW  EM         03AP2006   95111705                                          NIHC
```

```
RADIATION CURABLE CYCLOALIPHATIC BARRIER SEALANTS


3139A.EM       USA   EM          26JE2006   11/474,772                                       NIHC
RADIATION CURABLE CYCLOALIPHATIC BARRIER SEALANTS


3140.EM        USA   EM          04AP2005   11/098,116                                       NIHC
RADIATION- OR THERMALLY-CURABLE OXETANE BARRIER SEALANTS


3140.EM        CHIN  EM          03AP2006   200680011296.0                                   NIHC
RADIATION- OR THERMALLY-CURABLE OXETANE BARRIER SEALANTS


3140.EM        EPC   EM          03AP2006   06 749 108.4                                     NIHC
RADIATION- OR THERMALLY-CURABLE OXETANE BARRIER SEALANTS


3140.EM        JAPA  EM          03AP2006   2008-505404                                      NIHC
RADIATION- OR THERMALLY-CURABLE OXETANE BARRIER SEALANTS


3140.EM        KORS  EM          03AP2006   10-2007-7025367                                  NIHC
RADIATION- OR THERMALLY-CURABLE OXETANE BARRIER SEALANTS


3140.EM        TAIW  EM          03AP2006   95111704                                         NIHC
RADIATION- OR THERMALLY-CURABLE OXETANE BARRIER SEALANTS


3140A.EM       USA   EM          10AU2006   11/502,707                                       NIHC
RADIATION- OR THERMALLY-CURABLE OXETANE BARRIER SEALANTS


3141.EM        USA   EM          04AP2005   11/098,117                                       NIHC
RADIATION-CURABLE DESICCANT-FILLED ADHESIVE/SEALANT


3141A.EM       USA   EM          30MR2006   11/393,496                                       NIHC
RADIATION-CURABLE DESICCANT-FILLED ADHESIVE/SEALANT


3141A.EM       CHIN  EM          30MR2006   200680010880.4                                   NIHC
RADIATION-CURABLE DESICCANT-FILLED ADHESIVE/SEALANT
```

```
3141A.EM       EPC   EM          30MR2006   06 740 192.7                                     NIHC
RADIATION-CURABLE DESICCANT-FILLED ADHESIVE/SEALANT


3141A.EM       JAPA  EM          30MR2006   2008-505385                                      NIHC
RADIATION-CURABLE DESICCANT-FILLED ADHESIVE/SEALANT


3141A.EM       KORS  EM          30MR2006   10-2007-7025368                                  NIHC
RADIATION-CURABLE DESICCANT-FILLED ADHESIVE/SEALANT


3141A.EM       TAIW  EM          03AP2006   95111703                                         NIHC
RADIATION-CURABLE DESICCANT-FILLED ADHESIVE/SEALANT


3142.TDM       USA   A           25AP2006   11/410,375                                       NIHC
USE OF DEBRANCHED STARCH IN EXTRUSION-SPHERONIZATION
PHARMACEUTICAL PELLETS


3142.TDM       ASTL  A           28AP2006   2006201779                                       NIHC
USE OF DEBRANCHED STARCH IN EXTRUSION-SPHERONIZATION
PHARMACEUTICAL PELLETS


3142.TDM       BRAZ  A           28AP2006   000                                              NIHC
USE OF DEBRANCHED STARCH IN EXTRUSION-SPHERONIZATION
PHARMACEUTICAL PELLETS


3142.TDM       CHIN  A           30AP2006   200610089886.7                                   NIHC
USE OF DEBRANCHED STARCH IN EXTRUSION-SPHERONIZATION
PHARMACEUTICAL PELLETS


3142.TDM       EPC   A           27AP2006   06 008 756.6                                     NIHC
USE OF DEBRANCHED STARCH IN EXTRUSION-SPHERONIZATION
PHARMACEUTICAL PELLETS


3142.TDM       INDO  A           28AP2006   200600261                                        NIHC
USE OF DEBRANCHED STARCH IN EXTRUSION-SPHERONIZATION
PHARMACEUTICAL PELLETS
```

```
3142.TDM       JAPA  A          01MY2006   2006-127831                                         NIHC
USE OF DEBRANCHED STARCH IN EXTRUSION-SPHERONIZATION
PHARMACEUTICAL PELLETS


3142.TDM       MAYS  A          28AP2006   PI 20061989                                         NIHC
USE OF DEBRANCHED STARCH IN EXTRUSION-SPHERONIZATION
PHARMACEUTICAL PELLETS


3142.TDM       MEXI  A          28AP2006   PA/a/2006/004838                                    NIHC
USE OF DEBRANCHED STARCH IN EXTRUSION-SPHERONIZATION
PHARMACEUTICAL PELLETS


3142.TDM       PHIL  A          27AP2006   1-2006-000237                                       NIHC
USE OF DEBRANCHED STARCH IN EXTRUSION-SPHERONIZATION
PHARMACEUTICAL PELLETS


3142.TDM       SAFR  A          28AP2006   2006/03392                                          NIHC
USE OF DEBRANCHED STARCH IN EXTRUSION-SPHERONIZATION
PHARMACEUTICAL PELLETS


3142.TDM       THAI  A          26AP2006   0601001903                                          NIHC
USE OF DEBRANCHED STARCH IN EXTRUSION-SPHERONIZATION
PHARMACEUTICAL PELLETS


3144.EM        CHIN  EM         14AP2006   200610072396.6                                      NIHC
DIE ATTACH ADHESIVES WITH IMPROVED STRESS PERFORMANCE


3144.EM        EPC   EM         13AP2006   06 007 866.4                                        NIHC
DIE ATTACH ADHESIVES WITH IMPROVED STRESS PERFORMANCE


3144.EM        JAPA  EM         17AP2006   2006-112988                                         NIHC
DIE ATTACH ADHESIVES WITH IMPROVED STRESS PERFORMANCE


3144.EM        KORS  EM         13AP2006   10-2006-0033556                                     NIHC
DIE ATTACH ADHESIVES WITH IMPROVED STRESS PERFORMANCE


3144.EM        SING  EM         13AP2006   200602515-9                                         NIHC
```

```
DIE ATTACH ADHESIVES WITH IMPROVED STRESS PERFORMANCE


3144.EM        TAIW  EM          17AP2006   95113570                                          NIHC
DIE ATTACH ADHESIVES WITH IMPROVED STRESS PERFORMANCE


3145.TDM       USA   A           04MY2006   11/418,289                                        NIHC
COMPOSITION USEFUL FOR DELIVERY OF ACTIVE AGENTS


3145.TDM       EPC   A           03MY2006   06 009 147.7                                      NIHC
COMPOSITION USEFUL FOR DELIVERY OF ACTIVE AGENTS


3145.TDM       INDI  A           01MY2006   000                                               NIHC
COMPOSITION USEFUL FOR DELIVERY OF ACTIVE AGENTS


3145.TDM       JAPA  A           01MY2006   2006-127593                                       NIHC
COMPOSITION USEFUL FOR DELIVERY OF ACTIVE AGENTS


3145.TDM       KORS  A           03MY2006   10-2006-0039961                                   NIHC
COMPOSITION USEFUL FOR DELIVERY OF ACTIVE AGENTS


3148.ACH       USA   A           05JE2005   11/146,267                                        NIHC
WEATHERSTRIP COATING


3148.ACH       EPC   A           01JE2006   06 011 377.6                                      NIHC
WEATHERSTRIP COATING


3148.ACH       JAPA  A           02JE2006   2006-155375                                       NIHC
WEATHERSTRIP COATING


3150.ADH       USA   A           14JL2005   11/181,381                                        NIHC
ACTIVATABLE COMPOSITIONS


3150.ADH       ASTL  A           12JL2006   2006202995                                        NIHC
ACTIVATABLE COMPOSITIONS
```

3150.ADH	CANA	A	12JL2006	2552270	NIHC
ACTIVATABLE COMPOSITIONS					
3150.ADH	CHIN	A	12JL2006	200610101894.9	NIHC
ACTIVATABLE COMPOSITIONS					
3150.ADH	EPC	A	13JL2006	06 014 570.3	NIHC
ACTIVATABLE COMPOSITIONS					
3150.ADH	JAPA	A	11JL2006	2006-190394	NIHC
ACTIVATABLE COMPOSITIONS					
3150.ADH	KORS	A	13JL2006	10-2006-0065964	NIHC
ACTIVATABLE COMPOSITIONS					
3150.ADH	TAIW	A	13JL2006	95125569	NIHC
ACTIVATABLE COMPOSITIONS					
3151.EM	CHIN	EM	29MY2006	200610084683.9	NIHC
FLUXING COMPOSITIONS					
3151.EM	EPC	EM	31MY2006	06 011 227.3	NIHC
FLUXING COMPOSITIONS					
3151.EM	HONG	EM	02FE2007	07101294.4	NIHC
FLUXING COMPOSITIONS					
3151.EM	JAPA	EM	02JE2006	2006-155372	NIHC
FLUXING COMPOSITIONS					
3151.EM	KORS	EM	02JE2006	10-2006-0049959	NIHC
FLUXING COMPOSITIONS					
3151.EM	SING	EM	29MY2006	200603572-9	NIHC
FLUXING COMPOSITIONS					

```
3151.EM        TAIW   EM          02JE2006   95119490                                     NIHC
FLUXING COMPOSITIONS

3151D.EM       USA    EM          31JL2007   11/831,379                                   NIHC
METHOD OF FLUXING USING A FLUXING COMPOSITION CONTAINING
COMPOUNDS WITH AN AROMATIC RING AND NO IMINO GROUP

3153.EM        USA    EM          22JL2005   11/168,236                                   NIHC
PROCESS FOR EXPOSING SOLDER BUMPS ON AN UNDERFILL COATED
SEMICONDUCTOR

3153.EM        CHIN   EM          19JL2006   200610106307.5                               NIHC
PROCESS FOR EXPOSING SOLDER BUMPS ON AN UNDERFILL COATED
SEMICONDUCTOR

3153.EM        EPC    EM          19JL2006   06 015 031.5                                 NIHC
PROCESS FOR EXPOSING SOLDER BUMPS ON AN UNDERFILL COATED
SEMICONDUCTOR

3153.EM        JAPA   EM          20JL2006   2006-197663                                  NIHC
PROCESS FOR EXPOSING SOLDER BUMPS ON AN UNDERFILL COATED
SEMICONDUCTOR

3153.EM        KORS   EM          20JL2006   10-2006-0067987                              NIHC
PROCESS FOR EXPOSING SOLDER BUMPS ON AN UNDERFILL COATED
SEMICONDUCTOR

3153.EM        SING   EM          18JL2006   200604839-1                                  NIHC
PROCESS FOR EXPOSING SOLDER BUMPS ON AN UNDERFILL COATED
SEMICONDUCTOR

3153.EM        TAIW   EM          20JL2006   95126458                                     NIHC
PROCESS FOR EXPOSING SOLDER BUMPS ON AN UNDERFILL COATED
SEMICONDUCTOR

3155.EM        USA    EM          21JE2005   11/157,611                                   NIHC
METAL SALTS OF MALEIMIDE COMPOUNDS AS CONDUCTIVITY
```

```
PROMOTERS

3156.EM        USA   EM         23JE2005   11/166,860                                     NIHC
METAL SALTS OF ORGANIC ACIDS AS CONDUCTIVITY PROMOTERS

3156.EM        CHIN  EM         21JE2006   200610093107.0                                 NIHC
METAL SALTS OF ORGANIC ACIDS AS CONDUCTIVITY PROMOTERS

3156.EM        EPC   EM         20JE2006   06 012 686.9                                   NIHC
METAL SALTS OF ORGANIC ACIDS AS CONDUCTIVITY PROMOTERS

3156.EM        JAPA  EM         22JE2006   2006-172676                                    NIHC
METAL SALTS OF ORGANIC ACIDS AS CONDUCTIVITY PROMOTERS

3156.EM        KORS  EM         21JE2006   10-2006-0056011                                NIHC
METAL SALTS OF ORGANIC ACIDS AS CONDUCTIVITY PROMOTERS

3156.EM        SING  EM         20JE2006   200604200-6                                    NIHC
METAL SALTS OF ORGANIC ACIDS AS CONDUCTIVITY PROMOTERS


3156.EM        TAIW  EM         22JE2006   95122376                                       NIHC
METAL SALTS OF ORGANIC ACIDS AS CONDUCTIVITY PROMOTERS

3156.EM        THAI  EM         19JE2006   0601002821                                     NIHC
METAL SALTS OF ORGANIC ACIDS AS CONDUCTIVITY PROMOTERS

3157.TDM       USA   A          29SE2005   11/238,277                                     NIHC
ACRYLIC PRESSURE SENSITIVE ADHESIVES

3157.TDM       CHIN  A          25SE2006   200610154265.2                                 NIHC
ACRYLIC PRESSURE SENSITIVE ADHESIVES

3157.TDM       EPC   A          25SE2006   06 019 982.5                                   NIHC
ACRYLIC PRESSURE SENSITIVE ADHESIVES
```

```
3157.TDM       JAPA  A          25SE2006   2006-258932                                      NIHC
ACRYLIC PRESSURE SENSITIVE ADHESIVES


3157.TDM       KORS  A          27SE2006   10-2006-0094206                                  NIHC
ACRYLIC PRESSURE SENSITIVE ADHESIVES


3159.ADH       USA   A          04AU2005   11/197,230                                       NIHC
LOW APPLICATION TEMPERATURE HOT MELT ADHESIVE AND USE
THEREOF IN PACKAGING APPLICATIONS


3161.PKG       USA   A          06OC2005   11/244,808                                       NIHC
INTEGRATED LOW APPLICATION TEMPERATURE HOT MELT ADHESIVE
PROCESSING SYSTEM


3161.PKG       CANA  A          28SE2006   2,561,597                                        NIHC
INTEGRATED LOW APPLICATION TEMPERATURE HOT MELT ADHESIVE
PROCESSING SYSTEM


3161.PKG       CHIN  A          29SE2006   200610159991.3                                   NIHC
INTEGRATED LOW APPLICATION TEMPERATURE HOT MELT ADHESIVE
PROCESSING SYSTEM


3161.PKG       EPC   A          27SE2006   06 020 252.0                                     NIHC
INTEGRATED LOW APPLICATION TEMPERATURE HOT MELT ADHESIVE
PROCESSING SYSTEM


3161.PKG       JAPA  A          03OC2006   2006-271683                                      NIHC
INTEGRATED LOW APPLICATION TEMPERATURE HOT MELT ADHESIVE
PROCESSING SYSTEM


3162.TDM       USA   A          26AU2005   11/212,437                                       NIHC
MUCOSAL DELIVERY TABLET


3162.TDM       CANA  A          25AU2006   2,557,377                                        NIHC
MUCOSAL DELIVERY TABLET
```

```
3162.TDM       CHIN  A           25AU2006   200610126518.5                                NIHC
MUCOSAL DELIVERY TABLET


3162.TDM       EPC   A           25AU2006   06 017 751.6                                  NIHC
MUCOSAL DELIVERY TABLET


3162.TDM       INDI  A           24AU2006   1509/CHE/2006                                 NIHC
MUCOSAL DELIVERY TABLET


3162.TDM       JAPA  A           25AU2006   2006-229039                                   NIHC
MUCOSAL DELIVERY TABLET


3162.TDM       KORS  A           25AU2006   10-2006-0081175                               NIHC
MUCOSAL DELIVERY TABLET


3165.EM        USA   EM          25AU2005   11/211,920                                    NIHC
QUINOLINOLS AND QUINOLINOL DERIVATIVES AS ADHESION PROMOTERS
IN DIE ATTACH ADHESIVES


3165.EM        CHIN  EM          22AU2006   200610126503.9                                NIHC
QUINOLINOLS AND QUINOLINOL DERIVATIVES AS ADHESION PROMOTERS
IN DIE ATTACH ADHESIVES


3165.EM        EPC   EM          23AU2006   06 017 529.6                                  NIHC
QUINOLINOLS AND QUINOLINOL DERIVATIVES AS ADHESION PROMOTERS
IN DIE ATTACH ADHESIVES


3165.EM        JAPA  EM          23AU2006   2006-226254                                   NIHC
QUINOLINOLS AND QUINOLINOL DERIVATIVES AS ADHESION PROMOTERS
IN DIE ATTACH ADHESIVES


3165.EM        KORS  EM          24AU2006   10-2006-0080520                               NIHC
QUINOLINOLS AND QUINOLINOL DERIVATIVES AS ADHESION PROMOTERS
IN DIE ATTACH ADHESIVES


3165.EM        SING  EM          22AU2006   200605716-0                                   NIHC
QUINOLINOLS AND QUINOLINOL DERIVATIVES AS ADHESION PROMOTERS
```

```
IN DIE ATTACH ADHESIVES

3165.EM        TAIW  EM          24AU2006   95131062                                      NIHC
QUINOLINOLS AND QUINOLINOL DERIVATIVES AS ADHESION PROMOTERS
IN DIE ATTACH ADHESIVES

3166.EM        USA   EM          25AU2005   11/211,406                                    NIHC
QUINOLINOLS AS FLUXING AND ACCELERATING AGENTS FOR UNDERFILL
COMPOSITIONS

3166.EM        CHIN  EM          22AU2006   200610126502.4                                NIHC
QUINOLINOLS AS FLUXING AND ACCELERATING AGENTS FOR UNDERFILL
COMPOSITIONS

3166.EM        EPC   EM          23AU2006   06 017 528.8                                  NIHC
QUINOLINOLS AS FLUXING AND ACCELERATING AGENTS FOR UNDERFILL
COMPOSITIONS

3166.EM        JAPA  EM          23AU2006   2006-226255                                   NIHC
QUINOLINOLS AS FLUXING AND ACCELERATING AGENTS FOR UNDERFILL
COMPOSITIONS

3166.EM        KORS  EM          24AU2006   10-2006-0080518                               NIHC
QUINOLINOLS AS FLUXING AND ACCELERATING AGENTS FOR UNDERFILL
COMPOSITIONS

3166.EM        SING  EM          22AU2006   200605715-2                                   NIHC
QUINOLINOLS AS FLUXING AND ACCELERATING AGENTS FOR UNDERFILL
COMPOSITIONS

3166.EM        TAIW  EM          24AU2006   95131063                                      NIHC
QUINOLINOLS AS FLUXING AND ACCELERATING AGENTS FOR UNDERFILL
COMPOSITIONS

3167.NWN       USA   A           21NO2005   11/284,102                                    NIHC
ADHESIVES CONTAINING BLOCK COPOLYMERS
```

```
3167.NWN       CANA  A           08NO2006   2,567,414                                                  NIHC
ADHESIVES CONTAINING BLOCK COPOLYMERS


3167.NWN       CHIN  A           16NO2006   200610160334.0                                             NIHC
ADHESIVES CONTAINING BLOCK COPOLYMERS


3167.NWN       EPC   A           08NO2006   06 023 233.7                                               NIHC
ADHESIVES CONTAINING BLOCK COPOLYMERS


3167.NWN       JAPA  A           15NO2006   2006-309539                                                NIHC
ADHESIVES CONTAINING BLOCK COPOLYMERS


3168.ADH       ATRA  A           14SE2005   05 020 034.4       11AP2007   E 359 315    14SE2025     NIHC
NOVEL WATER-BASED ADHESIVES FOR INDUSTRIAL APPLICATIONS


3168.ADH       BELG  A           14SE2005   05 020 034.4       11AP2007   1767566      14SE2025     NIHC
NOVEL WATER-BASED ADHESIVES FOR INDUSTRIAL APPLICATIONS


3168.ADH       BRAZ  A           05SE2006   000                                                        NIHC
NOVEL WATER-BASED ADHESIVES FOR INDUSTRIAL APPLICATIONS


3168.ADH       CANA  A           05SE2006   000                                                        NIHC
NOVEL WATER-BASED ADHESIVES FOR INDUSTRIAL APPLICATIONS

3168.ADH       CHIN  A           05SE2006   000                                                        NIHC
NOVEL WATER-BASED ADHESIVES FOR INDUSTRIAL APPLICATIONS


3168.ADH       EPC   A           14SE2005   05 020 034.4       11AP2007   1767566      14SE2025     NIHC
NOVEL WATER-BASED ADHESIVES FOR INDUSTRIAL APPLICATIONS


3168.ADH       EPC   A           05SE2006   000                                                        NIHC
NOVEL WATER-BASED ADHESIVES FOR INDUSTRIAL APPLICATIONS


3168.ADH       FRAN  A           14SE2005   05 020 034.4       11AP2007   1767566      14SE2025     NIHC
NOVEL WATER-BASED ADHESIVES FOR INDUSTRIAL APPLICATIONS
```

```
3168.ADH      GBRI  A         14SE2005   05 020 034.4      11AP2007   1767566      14SE2025     NIHC
NOVEL WATER-BASED ADHESIVES FOR INDUSTRIAL APPLICATIONS


3168.ADH      GERM  A         14SE2005   05 020 034.4      11AP2007  602005000882.914SE2025     NIHC
NOVEL WATER-BASED ADHESIVES FOR INDUSTRIAL APPLICATIONS


3168.ADH      INDI  A         05SE2006   000                                                  NIHC
NOVEL WATER-BASED ADHESIVES FOR INDUSTRIAL APPLICATIONS


3168.ADH      ITAL  A         14SE2005   05 020 034.4      11AP2007   1767566      14SE2025     NIHC
NOVEL WATER-BASED ADHESIVES FOR INDUSTRIAL APPLICATIONS


3168.ADH      JAPA  A         05SE2006   000                                                  NIHC
NOVEL WATER-BASED ADHESIVES FOR INDUSTRIAL APPLICATIONS


3168.ADH      MEXI  A         05SE2006   MX/a/2008/003301                                     NIHC
NOVEL WATER-BASED ADHESIVES FOR INDUSTRIAL APPLICATIONS


3168.ADH      NETH  A         14SE2005   05 020 034.4      11AP2007   1767566      14SE2025     NIHC
NOVEL WATER-BASED ADHESIVES FOR INDUSTRIAL APPLICATIONS


3168.ADH      POLA  A         14SE2005   05 020 034.4      11AP2007   1767566      14SE2025     NIHC
NOVEL WATER-BASED ADHESIVES FOR INDUSTRIAL APPLICATIONS


3168.ADH      RUSS  A         05SE2006   000                                                  NIHC
NOVEL WATER-BASED ADHESIVES FOR INDUSTRIAL APPLICATIONS


3168.ADH      SPAI  A         14SE2005   05 020 034.4      11AP2007   1767566      14SE2025     NIHC
NOVEL WATER-BASED ADHESIVES FOR INDUSTRIAL APPLICATIONS


3169.EM       USA   EM        26SE2005   11/235,991                                           NIHC
METAL SALTS OF QUINOLINOLS AND QUINOLINOL DERIVATIVES AS
ADHESION AND CONDUCTIVITY PROMOTERS IN DIE ATTACH ADEHSIVES


3169.EM       CHIN  EM        22SE2006   200610154355.1                                       NIHC
METAL SALTS OF QUINOLINOLS AND QUINOLINOL DERIVATIVES AS
```

```
ADHESION AND CONDUCTIVITY PROMOTERS IN DIE ATTACH ADEHSIVES


3169.EM        EPC   EM          25SE2006   06 019 981.7                                    NIHC
METAL SALTS OF QUINOLINOLS AND QUINOLINOL DERIVATIVES AS
ADHESION AND CONDUCTIVITY PROMOTERS IN DIE ATTACH ADEHSIVES


3169.EM        HONG  EM          05JL2007   07107171.9                                      NIHC
METAL SALTS OF QUINOLINOLS AND QUINOLINOL DERIVATIVES AS
ADHESION AND CONDUCTIVITY PROMOTERS IN DIE ATTACH ADEHSIVES


3169.EM        JAPA  EM          22SE2006   2006-256703                                     NIHC
METAL SALTS OF QUINOLINOLS AND QUINOLINOL DERIVATIVES AS
ADHESION AND CONDUCTIVITY PROMOTERS IN DIE ATTACH ADEHSIVES


3169.EM        KORS  EM          22SE2006   10-2006-0092336                                 NIHC
METAL SALTS OF QUINOLINOLS AND QUINOLINOL DERIVATIVES AS
ADHESION AND CONDUCTIVITY PROMOTERS IN DIE ATTACH ADEHSIVES


3169.EM        MAYS  EM          25SE2006   PI 20064202                                     NIHC
METAL SALTS OF QUINOLINOLS AND QUINOLINOL DERIVATIVES AS
ADHESION AND CONDUCTIVITY PROMOTERS IN DIE ATTACH ADEHSIVES


3169.EM        SING  EM          22SE2006   200606580-9                                     NIHC
METAL SALTS OF QUINOLINOLS AND QUINOLINOL DERIVATIVES AS
ADHESION AND CONDUCTIVITY PROMOTERS IN DIE ATTACH ADEHSIVES


3169.EM        TAIW  EM          25SE2006   95135295                                        NIHC
METAL SALTS OF QUINOLINOLS AND QUINOLINOL DERIVATIVES AS
ADHESION AND CONDUCTIVITY PROMOTERS IN DIE ATTACH ADEHSIVES


3169A.EM       USA   EM          10OC2006   11/545,238                                      NIHC
METAL SALTS OF QUINOLINOLS AND QUINOLINOL DERIVATIVES AS
ADHESION AND CONDUCTIVITY PROMOTERS IN DIE ATTACH ADEHSIVES


3170.BKB       USA   A           06OC2005   11/244,799                                      NIHC
FOAMED ADHESIVE FOR CASING-IN
```

```
3170.BKB       CANA  A          04OC2006   2,562,541                                              NIHC
FOAMED ADHESIVE FOR CASING-IN


3171.EM        USA   EEM        20OC2005   11/255,117                                             NIHC
RFID ANTENNA WITH PRE-APPLIED ADHESIVES


3171.EM        CHIN  EEM        17OC2006   200610135717.2                                         NIHC
RFID ANTENNA WITH PRE-APPLIED ADHESIVES


3171.EM        EPC   EEM        19OC2006   06 021 945.8                                           NIHC
RFID ANTENNA WITH PRE-APPLIED ADHESIVES


3171.EM        JAPA  EEM        16OC2006   2006-281364                                            NIHC
RFID ANTENNA WITH PRE-APPLIED ADHESIVES


3171.EM        KORS  EEM        19OC2006   10-2006-0101804                                        NIHC
RFID ANTENNA WITH PRE-APPLIED ADHESIVES


3171.EM        MAYS  EEM        17OC2006   PI 20064337                                            NIHC
RFID ANTENNA WITH PRE-APPLIED ADHESIVES


3171.EM        TAIW  EEM        19OC2006   95138494                                               NIHC
RFID ANTENNA WITH PRE-APPLIED ADHESIVES


3173.EM        JAPA  EM         30OC2006   2006-294312                                            NIHC
FLUXING COMPOSITIONS CONTAINING BENZOTRIAZOLES


3173.EM        KORS  EM         30OC2006   10-2006-0105739                                        NIHC
FLUXING COMPOSITIONS CONTAINING BENZOTRIAZOLES


3173.EM        TAIW  EM         01NO2006   95140340                                               NIHC
FLUXING COMPOSITIONS CONTAINING BENZOTRIAZOLES


3173D.EM       USA   EM         26JL2007   11/828,640                                             NIHC
METHOD OF FLUXING USING FLUXING COMPOSITIONS CONTAINING
BENZOTRIAZOLES
```

3180.BDM	USA	A	21NO2005	11/284,241	ADHESIVE COMPOSITION	NIHC
3180.BDM	CHIN	A	20NO2006	200610171810.9	ADHESIVE COMPOSITION	NIHC
3180.BDM	EPC	A	20NO2006	06 024 005.8	ADHESIVE COMPOSITION	NIHC
3180.BDM	JAPA	A	16NO2006	310137	ADHESIVE COMPOSITION	NIHC
3181.EM	PCT	EM	15DE2005	PCT/US05/46390	MULTI-LAYER ADHESIVE FILM DIE STACKING	NIHC
3182.BDG	USA	A	22NO2006	11/603,733	NOVEL MATERIAL FORMING SUPRAMOLECULAR STRUCTURES, PROCESS AND USES	NIHC
3182.BDG	CANA	A	27NO2006	2,569,291	NOVEL MATERIAL FORMING SUPRAMOLECULAR STRUCTURES, PROCESS AND USES	NIHC
3182.BDG	CHIN	A	28NO2006	610160512.X	NOVEL MATERIAL FORMING SUPRAMOLECULAR STRUCTURES, PROCESS AND USES	NIHC
3182.BDG	EPC	A	01DE2005	05 026 211.2	NOVEL MATERIAL FORMING SUPRAMOLECULAR STRUCTURES, PROCESS AND USES	NIHC
3182.BDG	JAPA	A	28NO2006	2006-320384	NOVEL MATERIAL FORMING SUPRAMOLECULAR STRUCTURES, PROCESS AND USES	NIHC

```
3183.ACH       USA   A          11JA2006   11/275,506                                          NIHC
BORON NITRIDE BASED LUBRICANT ADDITIVE


3183.ACH       BRAZ  A          10JA2007   PI 0700028-6                                        NIHC
BORON NITRIDE BASED LUBRICANT ADDITIVE


3183.ACH       CANA  A          08JA2007   2,573,039                                           NIHC
BORON NITRIDE BASED LUBRICANT ADDITIVE


3183.ACH       CHIN  A          09JA2007   200710001330.2                                      NIHC
BORON NITRIDE BASED LUBRICANT ADDITIVE


3183.ACH       JAPA  A          10JA2007   2007-2008                                           NIHC
BORON NITRIDE BASED LUBRICANT ADDITIVE


3183.ACH       KORS  A          09JA2007   10-2007-0002501                                     NIHC
BORON NITRIDE BASED LUBRICANT ADDITIVE


3183.ACH       MEXI  A          09JA2007   MX/a/2007/000365                                    NIHC
BORON NITRIDE BASED LUBRICANT ADDITIVE


3185.EM        USA   EM         30JA2006   11/275,786                                          NIHC
THERMAL INTERFACE MATERIAL


3185.EM        CHIN  EM         29JA2007   200710008291.9                                      NIHC
THERMAL INTERFACE MATERIAL


3185.EM        EPC   EM         29JA2007   07 001 862.7                                        NIHC
THERMAL INTERFACE MATERIAL


3185.EM        JAPA  EM         26JA2007   2007-15941                                          NIHC
THERMAL INTERFACE MATERIAL


3185.EM        KORS  EM         26JA2007   10-2007-0008544                                     NIHC
THERMAL INTERFACE MATERIAL
```

```
3185.EM        TAIW  EM          29JA2007   96103112                                            NIHC
THERMAL INTERFACE MATERIAL


3187.PSA       PCT   A           11MY2006   PCT/US06/18275                                      NIHC
ACRYLIC HOT MELT ADHESIVES


3188.EM        USA   EM          07MR2006   11/369,429                                          NIHC
CURABLE MATERIALS CONTAINING SILOXANE


3188.EM        CHIN  EM          06MR2007   200710086180.X                                      NIHC
CURABLE MATERIALS CONTAINING SILOXANE


3188.EM        EPC   EM          07MR2007   07 004 682.6                                        NIHC
CURABLE MATERIALS CONTAINING SILOXANE


3188.EM        JAPA  EM          06MR2007   2007-55139                                          NIHC
CURABLE MATERIALS CONTAINING SILOXANE


3188.EM        KORS  EM          06MR2007   10-2007-0022042                                     NIHC
CURABLE MATERIALS CONTAINING SILOXANE


3188.EM        SING  EM          06MR2007   200701711-4                                         NIHC
CURABLE MATERIALS CONTAINING SILOXANE


3188.EM        TAIW  EM          06MR2007   96107589                                            NIHC
CURABLE MATERIALS CONTAINING SILOXANE


3189.EM        USA   EM          10MR2006   11/373,437                                          NIHC
ADHESIVE COMPOSITION


3189.EM        CHIN  EM          07MR2007   200710086011.6                                      NIHC
ADHESIVE COMPOSITION


3189.EM        EPC   EM          09MR2007   07 004 903.6                                        NIHC
ADHESIVE COMPOSITION
```

3189.EM	JAPA	EM	08MR2007	2007-58097	NIHC	ADHESIVE COMPOSITION
3189.EM	KORS	EM	07MR2007	10-2007-0022505	NIHC	ADHESIVE COMPOSITION
3189.EM	PHIL	EM	06MR2007	1-2007-000074	NIHC	ADHESIVE COMPOSITION
3189.EM	TAIW	EM	09MR2007	96108097	NIHC	ADHESIVE COMPOSITION
3190.EM	USA	EM	10MR2006	11/373,484	NIHC	ANISOTROPIC CONDUCTIVE ADHESIVE
3190.EM	CHIN	EM	06MR2007	200710086181.4	NIHC	ANISOTROPIC CONDUCTIVE ADHESIVE
3190.EM	EPC	EM	09MR2007	07 004 902.8	NIHC	ANISOTROPIC CONDUCTIVE ADHESIVE
3190.EM	JAPA	EM	08MR2007	2007-58310	NIHC	ANISOTROPIC CONDUCTIVE ADHESIVE
3190.EM	KORS	EM	08MR2007	10-2007-0022785	NIHC	ANISOTROPIC CONDUCTIVE ADHESIVE
3190.EM	MAYS	EM	07MR2007	20070357	NIHC	ANISOTROPIC CONDUCTIVE ADHESIVE
3190.EM	TAIW	EM	09MR2007	96108098	NIHC	ANISOTROPIC CONDUCTIVE ADHESIVE
3190.EM	THAI	EM	07MR2007	0701001000	NIHC	

```
ANISOTROPIC CONDUCTIVE ADHESIVE


3191.EM        PCT   EM          29MR2006   PCT/US06/11441                                        NIHC
RADIATION- OR THERMALLY-CURABLE BARRIER SEALANTS


3191.EM        TAIW  EM          30JE2006   95123695                                              NIHC
RADIATION- OR THERMALLY-CURABLE BARRIER SEALANTS


3192.EM        PCT   EM          29MR2006   PCT/US06/11442                                        NIHC
RADIATION-CURABLE RUBBER ADHESIVE/SEALANT


3192.EM        TAIW  EM          30JE2006   95123697                                              NIHC
RADIATION-CURABLE RUBBER ADHESIVE/SEALANT


3193.EM        PCT   EM          30MR2006   PCT/US06/12657                                        NIHC
THERMALLY CURABLE EPOXY-AMINE BARRIER SEALANTS


3193.EM        TAIW  EM          29MR2007   96110912                                              NIHC
THERMALLY CURABLE EPOXY-AMINE BARRIER SEALANTS


3194.PKG       USA   A           14AP2006   11/404,916                                            NIHC
AQUEOUS BIOPOLYMER-CONTAINING LABELING ADHESIVE


3194.PKG       PCT   A           10AP2007   PCT/US07/08828                                        NIHC
AQUEOUS BIOPOLYMER-CONTAINING LABELING ADHESIVE


3195.BDM       USA   A           01MY2006   11/414,992                                            NIHC
SYSTEM FOR CONCEALING JOINTS


3196.NWN       USA   A           11MY2006   11/432,007                                            NIHC
ASBORBENT ARTICLES COMPRISING A RADIATION CURED HOT MELT
POSITIONING ADHESIVE


3196.NWN       CANA  A           10MY2007   2,588,444                                             NIHC
ASBORBENT ARTICLES COMPRISING A RADIATION CURED HOT MELT
POSITIONING ADHESIVE
```

3196.NWN	CHIN	A	11MY2007	200710107435.6	NIHC
ASBORBENT ARTICLES COMPRISING A RADIATION CURED HOT MELT POSITIONING ADHESIVE					
3196.NWN	EPC	A	10MY2007	07 009 435.4	NIHC
ASBORBENT ARTICLES COMPRISING A RADIATION CURED HOT MELT POSITIONING ADHESIVE					
3196.NWN	JAPA	A	10MY2007	2007-125201	NIHC
ASBORBENT ARTICLES COMPRISING A RADIATION CURED HOT MELT POSITIONING ADHESIVE					
3196.NWN	KORS	A	11MY2007	10-2007-0046008	NIHC
ASBORBENT ARTICLES COMPRISING A RADIATION CURED HOT MELT POSITIONING ADHESIVE					
3197.PKG	USA	A	21AP2006	11/409,136	NIHC
HOT MELT ADHESIVE FOR PACKAGING APPLICATIONS					
3197.PKG	CHIN	A	20AP2007	200710104404.5	NIHC
HOT MELT ADHESIVE FOR PACKAGING APPLICATIONS					
3197.PKG	EPC	A	19AP2007	07 007 995.9	NIHC
HOT MELT ADHESIVE FOR PACKAGING APPLICATIONS					
3197.PKG	JAPA	A	19AP2007	2007-110464	NIHC
HOT MELT ADHESIVE FOR PACKAGING APPLICATIONS					
3197.PKG	KORS	A	20AP2007	10-2007-0038879	NIHC
HOT MELT ADHESIVE FOR PACKAGING APPLICATIONS					
3199.BDG	USA	A	19MY2006	11/437,926	NIHC
TWO COMPONENT POLYURETHANE ADHESIVE					
3199.BDG	CHIN	A	17MY2007	200710103861.2	NIHC

```
TWO COMPONENT POLYURETHANE ADHESIVE

3199.BDG       EPC   A          18MY2007   07 009 958.5                                    NIHC
TWO COMPONENT POLYURETHANE ADHESIVE

3199.BDG       JAPA  A          18MY2007   2007-133249                                     NIHC
TWO COMPONENT POLYURETHANE ADHESIVE

3199.BDG       MEXI  A          18MY2007   MX/a/2007/006037                                NIHC
TWO COMPONENT POLYURETHANE ADHESIVE

3201.EM        CHIN  EM         08JE2006   000                                             NIHC
PRINTING PRESS CONTROL SYSTEM (XINK)

3201.EM        EPC   EM         08JE2006   06 775 038.0                                    NIHC
PRINTING PRESS CONTROL SYSTEM (XINK)

3201.EM        JAPA  EM         08JE2006   000                                             NIHC
PRINTING PRESS CONTROL SYSTEM (XINK)

3201.EM        KORS  EM         08JE2006   10-2008-7003708                                 NIHC
PRINTING PRESS CONTROL SYSTEM (XINK)

3201.EM        TAIW  EM         08JE2006   95120324                                        NIHC
PRINTING PRESS CONTROL SYSTEM

3202.EM        CANA  EM         08JE2006   000                                             NIHC
AQUEOUS PRINTABLE ELECTRICAL CONDUCTORS (XINK)

3202.EM        CHIN  EM         08JE2006   200680020379.6                                  NIHC
AQUEOUS PRINTABLE ELECTRICAL CONDUCTORS (XINK)

3202.EM        EPC   EM         08JE2006   06 752 776.2                                    NIHC
AQUEOUS PRINTABLE ELECTRICAL CONDUCTORS (XINK)
```

```
3202.EM        JAPA  EM          08JE2006   000                                                      NIHC
AQUEOUS PRINTABLE ELECTRICAL CONDUCTORS (XINK)


3202.EM        KORS  EM          08JE2006   10-2008-7000347                                          INNS
AQUEOUS PRINTABLE ELECTRICAL CONDUCTORS (XINK)


3202.EM        TAIW  EM          08JE2006   95120322                                                 NIHC
AQUEOUS PRINTABLE ELECTRICAL CONDUCTORS


3203.EM        USA   EM          09JE2006   11/450,486                                               NIHC
LOW VISCOSITY CURABLE COMPOSITIONS


3203.EM        CHIN  EM          07JE2007   200710108951.0                                           NIHC
LOW VISCOSITY CURABLE COMPOSITIONS


3203.EM        EPC   EM          06JE2007   07 011 138.0                                             NIHC
LOW VISCOSITY CURABLE COMPOSITIONS


3203.EM        JAPA  EM          08JE2007   2007-152528                                              NIHC
LOW VISCOSITY CURABLE COMPOSITIONS


3203.EM        KORS  EM          08JE2007   10-2007-0056086                                          NIHC
LOW VISCOSITY CURABLE COMPOSITIONS


3203.EM        TAIW  EM          08JE2007   96120618                                                 NIHC
LOW VISCOSITY CURABLE COMPOSITIONS


3204.ADH       USA   A           10JL2006   11/484,016                                               NIHC
LABELED TACKIFIERS


3204.ADH       EPC   A           06JL2007   07 013 269.1                                             NIHC
LABELED TACKIFIERS


3204.ADH       JAPA  A           09JL2007   2007-179917                                              NIHC
LABELED TACKIFIERS
```

```
3208.BDG       EPC   A          08DE2006   06 025 477.8                                      NIHC
REACTIVE COMPOSITION CONTAINING AN UNSATURATED BACKBONE


3208.BDG       PCT   A          10DE2007   PCT/EP07/10729                                    NIHC
REACTIVE COMPOSITION CONTAINING AN UNSATURATED BACKBONE


3209.EM        USA   EM         10AU2006   11/502,708                                        NIHC
THERMALLY CONDUCTIVE MATERIAL


3209.EM        CHIN  EM         08AU2007   000                                               NIHC
THERMALLY CONDUCTIVE MATERIAL


3209.EM        EPC   EM         07AU2007   07 015 590.8                                      NIHC
THERMALLY CONDUCTIVE MATERIAL


3209.EM        JAPA  EM         08AU2007   2007-206487                                       NIHC
THERMALLY CONDUCTIVE MATERIAL


3209.EM        KORS  EM         09AU2007   10-2007-0080040                                   NIHC
THERMALLY CONDUCTIVE MATERIAL


3209.EM        TAIW  EM         09AU2007   96129311                                          NIHC
THERMALLY CONDUCTIVE MATERIAL


3211.PSA       PCT   A          05NO2007   PCT/US07/23274                                    NIHC
ACRYLIC HOT MELT ADHESIVES


3212.EM        PCT   EM         06SE2007   PCT/US07/77734                                    NIHC
METHOD OF CHANGING RHEOLOGY IN FILLED RESIN SYSTEMS USING
CAVITATION


3215.ADH       EPC   A          11SE2006   06 018 969.3                                      NIHC
POWDER AND WATER-BASED ADHESIVE COMPOSITIONS


3215.ADH       PCT   A          07SE2007   PCT/EP07/07829                                    NIHC
```

```
POWDER AND WATER-BASED ADHESIVE COMPOSITIONS


3216.PSA       PCT   A          05NO2007   PCT/US07/23270                                          NIHC
ANTISTATIC PROTECTIVE HOT MELT ADHESIVES


3217.ACH       USA   A          11OC2006   11/545,883                                              NIHC
LUBRICANT FOR HOT FORGING APPLICATIONS


3217.ACH       PCT   A          11SE2007   PCT/US07/78113                                          NIHC
LUBRICANT FOR HOT FORGING APPLICATIONS


3217.ACH       TAIW  A          09OC2007   96137748                                                NIHC
LUBRICANT FOR HOT FORGING APPLICATIONS


3218.ACH       USA   A          12OC2006   11/546,890                                              NIHC
WATERBASED LOW NOISE GENERATING COATING

3218.ACH       ASTL  A          09OC2007   2007221892                                              NIHC
WATERBASED LOW NOISE GENERATING COATING


3218.ACH       BRAZ  A          10OC2007   000                                                     NIHC
WATERBASED LOW NOISE GENERATING COATING


3218.ACH       CANA  A          10OC2007   2,606,123                                               NIHC
WATERBASED LOW NOISE GENERATING COATING


3218.ACH       CHIN  A          09OC2007   200710162286.3                                          NIHC
WATERBASED LOW NOISE GENERATING COATING


3218.ACH       EPC   A          11OC2007   07 019 921.1                                            NIHC
WATERBASED LOW NOISE GENERATING COATING


3218.ACH       JAPA  A          11OC2007   2007-265403                                             NIHC
WATERBASED LOW NOISE GENERATING COATING


3218.ACH       KORS  A          11OC2007   10-2007-0102494                                         NIHC
```

WATERBASED LOW NOISE GENERATING COATING

3219.EM	PCT	EM	26JL2007	PCT/US07/74449	NIHC
1,3-DIPOLAR CYCLOADDITION OF AZIDES TO ALKYNES					
3219.EM	TAIW	EM	03AU2007	96128480	NIHC
1,3-DIPOLAR CYCLOADDITION OF AZIDES TO ALKYNES					
3220.EM	PCT	EM	01NO2007	PCT/US07/83319	NIHC
COMPOSITION WITH THERMALLY-TREATED SILICA FILLER FOR PERFORMANCE ENHANCEMENT					
3223.EM	PCT	EEM	16NO2006	PCT/US06/44465	NIHC
BOARD ON CHIP PACKAGE AND PROCESS FOR MAKING SAME					
3226.EM	PCT	EEM	08DE2006	PCT/US06/47067	NIHC
PROCESS FOR COATING A BUMPED SEMICONDUCTOR WAFER					
3227.CRG	PCT	A	22FE2008	PCT/US08/54660	NIHC
CORRUGATING ADHESIVE AND USE THEREOF					
3228.ADH	USA	A	18DE2006	11/640,734	NIHC
WATERBORNE ADHESIVE					
3229.EM	PCT	EM	02NO2007	PCT/US07/83445	NIHC
WATERBORNE CONDUCTIVE COMPOSITIONS					
3230.BDM	USA	A	09JA2007	11/651,435	NIHC
PRODUCT AND METHOD FOR CONCEALING JOINTS					
3230.BDM	PCT	A	08JA2008	PCT/US08/50460	NIHC
PRODUCT AND METHOD FOR CONCEALING JOINTS					
3231.EM	USA	EM	10JA2007	11/651,719	NIHC
HIGHLY CONDUCTIVE COMPOSITION FOR WAFER COATING					

3231.EM	CHIN	EM	09JA2008	000	HIGHLY CONDUCTIVE COMPOSITION FOR WAFER COATING	NIHC
3231.EM	EPC	EM	10JA2008	08 00 370.0	HIGHLY CONDUCTIVE COMPOSITION FOR WAFER COATING	NIHC
3231.EM	JAPA	EM	09JA2008	2008-2198	HIGHLY CONDUCTIVE COMPOSITION FOR WAFER COATING	NIHC
3231.EM	KORS	EM	08JA2008	10-2008-0001980	HIGHLY CONDUCTIVE COMPOSITION FOR WAFER COATING	NIHC
3231.EM	SING	EM	08JA2008	200800166-1	HIGHLY CONDUCTIVE COMPOSITION FOR WAFER COATING	NIHC
3231.EM	TAIW	EM	09JA2008	97100758	HIGHLY CONDUCTIVE COMPOSITION FOR WAFER COATING	NIHC
3231A.EM	USA	EM	16NO2007	11/941,498	HIGHLY CONDUCTIVE COMPOSITION FOR WAFER COATING	NIHC
3232.BDG	USA	A	25JA2007	11/657,859	REACTIVE HOT MELT ADHESIVE WITH BITUMINOUS ADDITIVE	NIHC
3232.BDG	PCT	A	24JA2008	PCT/US08/51882	REACTIVE HOT MELT ADHESIVE WITH BITUMINOUS ADDITIVE	NIHC
3233.EM	PCT	EM	31JA2007	PCT/US07/02740	SEMICONDUCTOR WAFER COATED WITH A FILLED, SPIN-COATABLE MATERIAL	NIHC
3235.PKG	USA	A	08FE2007	11/672,647	HOT MELT ADHESIVES	NIHC
3235.PKG	PCT	A	04FE2008	PCT/US08/52905		NIHC

```
HOT MELT ADHESIVES

3236.EM        PCT   EM          08FE2007   PCT/US07/03422                                        NIHC
MALEMIDE CONTAINING ESTER AND SULFIDE FUNCTIONALITIES

3238.EM        USA   EM          23FE2007   11/678,140                                            NIHC
CONDUCTIVE MATERIALS

3238.EM        CHIN  EM          19FE2008   200810080798.X                                        NIHC
CONDUCTIVE MATERIALS

3238.EM        EPC   EM          18FE2008   08 002 978.8                                          NIHC
CONDUCTIVE MATERIALS

3238.EM        INDI  EM          15FE2008   000                                                   NIHC
CONDUCTIVE MATERIALS

3238.EM        JAPA  EM          22FE2008   2008-041551                                           NIHC
CONDUCTIVE MATERIALS

3238.EM        KORS  EM          22FE2008   10-2008-0016103                                       NIHC
CONDUCTIVE MATERIALS

3238.EM        MEXI  EM          18FE2008   MX/a/2008/002344                                      NIHC
CONDUCTIVE MATERIALS

3238.EM        SING  EM          19FE2008   200801383-1                                           NIHC
CONDUCTIVE MATERIALS

3238.EM        TAIW  EM          22FE2008   97106162                                              NIHC
CONDUCTIVE MATERIALS

3239.PKG       USA   A           03AP2007   11/732,243                                            NIHC
HOT MELT ADHESIVE
```

3240.PKG	USA	A	03AP2007	11/732,242		NIHC	HOT MELT ADHESIVE
3241.EM	PCT	EM	14MR2007	PCT/US07/63970		NIHC	COMPOSITION CONTAINING PORPHYRIN TO IMPROVE ADHESION
3244.EM	USA	EM	10AP2007	11/733,279		NIHC	ELECTRICALLY CONDUCTIVE UV-CURABLE INK
3245.EM	USA	EM	17AP2007	60/912,223	17AP2008	NIHC	CORROSION-RESISTANT ANISOTROPIC CONDUCTIVE COMPOSITIONS
3246.EM	USA	EM	17AP2007	60/912,236	17AP2008	NIHC	THERMALLY-CONDUCTIVE COMPOSITIONS
3248.EM	PCT	EM	24JA2008	PCT/US08/51921		NIHC	ORGANIC ELECTRONIC DEVICES PROTECTED BY ELASTOMERIC LAMINATING ADHESIVE
3249.EM	USA	EM	23MY2007	11/752,591		NIHC	CORROSION-PREVENTIVE ADHESIVE COMPOSITIONS
3250.BDG	USA	A	26SE2007	11/861,486		NIHC	UV CURABLE COATING COMPOSITION
3251.BDG	USA	A	10AU2007	11/837,152		NIHC	REACTIVE HOT MELT ADHESIVE
3253.EM	PCT	EM	26JL2007	PCT/US07/74463		NIHC	ALCOHOLS CONTAINING IMIDE MOIETIES AND REACTIVE OLIGOMERS PREPARED THEREFROM
3253.EM	TAIW	EM	21JA2008	97102125		NIHC	ALCOHOLS CONTAINING IMIDE MOIETIES AND REACTIVE OLIGOMERS PREPARED THEREFROM

3254.NWN	USA	A	17AU2007	61/007,923	17AU2008	NIHC
HOT MELT ADHESIVES CONTAINING STYRENE BUTADIENE BLOCK COPOLYMER						
3256.BDG	PCT	A	10AU2007	PCT/JP07/65723		NIHC
REACTIVE WATER-BASED RESIN AND METHOD OF MANUFACTURING THE SAME						
3261.EM	PCT	EM	13SE2007	PCT/US07/78334		NIHC
ELECTRICALLY CONDUCTIVE COMPOSITION						
3262.EM	PCT	EM	14SE2007	PCT/US07/20018		NIHC
THERMALLY CONDUCTIVE COMPOSITION						
3265.EM	PCT	EM	19DE2007	PCT/US07/88130		NIHC
COMPOUNDS HAVING A DIPHENYL OXIDE BACKBONE AND MALEIMIDE FUNCTIONAL GROUP						
3270.EM	PCT	EM	20NO2007	PCT/US07/85258		NIHC
METHOD OF CONTAINING RESIN BLEED						
3271.EM	PCT	EM	20NO2007	PCT/US07/85272		NIHC
REDOX-INDUCED CATIONICALLY POLYMERIZABLE COMPOSITIONS WITH LOW CURE TEMPERATURE						
3272.EM	PCT	EM	20NO2007	PCT/US07/85278		NIHC
LOW-VOIDING DIE ATTACH FILM, SEMICONDUCTOR PACKAGE, AND PROCESSES FOR MAKING AND USING SAME						
3273.EM	PCT	EM	30NO2007	PCT/US07/86083		NIHC
CURABLE RESINS CONTAINING ACETAL, KETAL, ACETAL ESTER, OR KETAL ESTER LINKAGES						
3274.BDG	USA	A	20DE2007	11/961,345		NIHC
MOISTURE CURABLE HOT MELT ADHESIVE						
3275.BDG	USA	A	26DE2007	11/964,268		NIHC

```
INSULATION AND METHOD OF INSTALLING


3276.BDG       USA   A          21DE2007   11/962,872                                         NIHC
METHOD OF PREPARING A REACTIVE HOT MELT ADHESIVE


3281.EM        PCT   EM         26DE2007   000                                                NIHC
FUNCTION FLUORIDE ANTI-BLEED AGENTS WITH REACTIVE GROUPS AND
APPLICATION IN ORGANIC BASED CURABLE COMPOSITION


3283.EM        PCT   EM         05FE2008   PCT/US08/52983                                     NIHC
CURABLE COMPOSITIONS PREPARED FROM MULTIFUNCTIONAL AND
HYBRIDE N-VINYLFORMAMIDE COMPOUNDS


3284.ADH       USA   A          08FE2008   12/028,424                                         NIHC
HOT MELT ADHESIVE


3285.ADH       CHIN  A          28JA2008   200810003891.0                                     NIHC
ADHESIVES AND USES THEREOF


3286.ADH       CHIN  A          22NO2007   200710186831.2                                     NIHC
AN ADHESIVE, METHOD FOR PREPARING THE SAME AND APPLICATION
THEREOF


3287.ADH       CHIN  A          30JA2008   000                                                NIHC
MIXING SYSTEM AND ADHESIVE MIXER


3288.ADH       CHIN  A          03FE2008   000                                                NIHC
SPREADING ROLLER AND SPREADING MACHINE WITH IT


3290.EM        PCT   EM         25FE2008   000                                                NIHC
SELF-FILLETING DIE ATTACH PASTE


H-4614D        JAPA  EEM        15MR2006   2006-071105                                        NIHC
CURABLE AND CURED ORGANOSILICON COMPOSITIONS
```

Current owner key:

NIHC: National Starch & Chemical Investment Holding Corporation

SCHEDULE 2

TRADE MARKS

WORLDWIDE TRADEMARKS FILED ON OR AFTER July 10, 1999

Trademark	Ctry	Status	O.App.Dt	Curr Own Code
PURFECT GLAZE	USA	G	17JA2003	INNS
CERAMISHIELD	CTM	G	05DE2005	NIHC
ABLEBOND	CHIN	G	10JE2003	NIHC
ABLEBOND	PHIL	G	19MY2000	NIHC
ABLEFILM	CHIN	G	10JE2003	NIHC
ABLEFILM	PHIL	G	19MY2000	NIHC
ABLEFLEX	USA	G	07JE2000	INNS
ABLEFLEX	CHIN	G	27AP2004	NIHC
ABLELOC	USA	G	07JE2000	NIHC
ABLELOC	CHIN	G	27AP2004	NIHC
ABLELUX	USA	G	07JE2000	INNS
ABLELUX	CHIN	G	10JE2003	NIHC
ABLESTIK	INDI	F	21DE2005	NIHC
ABLETHERM	CHIN	G	10JE2003	NIHC
ABLETHERM	PHIL	G	19MY2000	NIHC
ACHESON	CHIN	G	27AP2002	NIHC
ACHESON	CHIN	F	27AP2002	NIHC
ACHESON	CHIN	G	27AP2002	NIHC
ACHESON	CHIN	G	14DE1999	NIHC
ACHESON	HONG	G	03JE2003	NIHC
ACHESON TEARDROP	CHIN	G	27AP2002	NIHC
ACHESON TEARDROP	CHIN	G	27AP2002	NIHC
ACHESON TEARDROP	CHIN	G	27AP2002	NIHC
ACHESON TEARDROP	HONG	G	03JE2003	NIHC
AERO-BOND	CTM	G	07SE1999	NIHC
AEROBOND	USA	G	28JE2000	INNS
AEROFRAME	USA	G	21JE2004	INNS
AEROFRAME	MEXI	G	21JE2004	INNS
BONDMASTER	INDO	G	05FE2003	NIHC

BONDMASTER	VIET	G	14FE2001	NIHC
CERAMISHIELD	USA	G	28NO2005	INNS
CERAMISHIELD	CTM	G	05DE2005	NIHC
CERAMISHIELD	TURK	G	05DE2005	NIHC
CIELOK	VIET	G	14FE2001	NIHC
CIEPAK	VIET	G	14FE2001	NIHC
CLEARJEL	JAPA	G	10MR2005	NIHC
COLD-CORR	USA	F	29AU2007	INNS
COLD-CORR	CANA	F	05SE2007	NIHC
CONTOUR	USA	G	07JE2000	INNS
COOL WRAP	USA	G	08JA2001	INNS
COOL-BIN	USA	G	09OC2003	INNS
COOL-BIND	JAPA	G	22JA2002	NIHC
COOL-CORR	USA	F	29AU2007	INNS
COOL-CORR	CANA	F	05SE2007	NIHC
COOL-LOK	SAFR	F	27MY2004	NIHC
COOL-MELT	COST	G	28SE1999	NIHC
COOL-MELT	SAFR	F	27MY2004	NIHC
COOL-MELT	VENE	G	02NO1999	NIHC
CORRALON	USA	G	11JA2002	INNS
DERMA-TAK	USA	G	19AU1999	INNS
DERMA-TAK	USA	F	24OC2007	INNS
DERMA-TAK	GREC	G	03SE1999	NIHC
DERMA-TAK	ITAL	G	23AU1999	NIHC
DERMA-TAK	KORE	G	06AU1999	NIHC
DUR-O-BOND	ITAL	G	23AU1999	NIHC
DURIBBON	JAPA	G	09AU2005	NIHC
DURO-LOK	VIET	G	14FE2001	NIHC
DURO-TAK	USA	G	27MR2001	INNS
EASY-PAC	USA	G	15JE2005	INNS
EASY-PAC	JAPA	F	01AU2007	NIHC
EASYFILL	USA	F	31OC2007	INNS
EASYFILL	CHIN	F	14NO2007	NIHC
EASYFILL	CTM	F	21DE2007	NIHC

EASYFILL	KORS	F	14NO2007	NIHC
EASYMELT	JAPA	G	29MR2000	NIHC
EASYTANK	USA	F	31OC2007	INNS
EASYTANK	CHIN	F	14NO2007	NIHC
EASYTANK	CTM	F	08NO2007	NIHC
EASYTANK	KORS	F	14NO2007	NIHC
ECCOSEAL	USA	G	14DE2004	NIHC
ECCOSEAL	CHIN	F	19AP2006	NIHC
ECO-CORR	USA	F	29AU2007	INNS
ECO-CORR	CANA	F	05SE2007	NIHC
ETIMELT	USA	G	29JE2006	INNS
FASTER QUALITY	USA	F	04SE2007	INNS
FILTER-LOK	USA	G	05NO2003	INNS
HY-PURE	USA	F	04AP2007	INNS
HY-PURE	CANA	F	05AP2007	INNS
INSTANT-PAK	USA	G	02AP2002	INNS
KOR LOK	TAIW	G	30SE2004	NIHC
KOR-LOK	VIET	G	14FE2001	NIHC
MULTI-LOK	USA	G	14JL2000	INNS
N-DURANCE	USA	G	22AU2006	INNS
N-DURANCE	CANA	F	23AU2006	INNS
NOVALON	USA	G	02OC2000	INNS
OPTAMYL	PHIL	G	03MR2000	NIHC
PG design	USA	G	18DE2002	INNS
PROLOC	USA	F	12NO2007	INNS
PROLOC	CANA	F	12NO2007	NIHC
PROLOC	CTM	F	16NO2007	NIHC
PROLOC	JAPA	F	13NO2007	NIHC
PROLOC	KORS	F	14NO2007	NIHC
PRONTO	USA	F	16JA2007	INNS
PRONTO	CHIN	F	25JA2007	NIHC
PRONTO	CHIN	F	25JA2007	NIHC
PUR-FECT BIND	USA	G	21JA2002	INNS
PUR-FECT LOK	USA	G	[illegible]	INNS

PUR-FECT PURGE	USA	G	17AP2002	INNS
PUR-FORMANCE	USA	F	03AP2007	INNS
PUR-FORMANCE	CANA	F	03AP2007	INNS
PURFECT	USA	G	16DE2002	INNS
PURFECT GLAZE	USA	G	17JA2003	INNS
RELY-IMIDE	USA	G	05DE2000	INNS
RIDI-CAL	USA	G	28AP2004	INNS
ROYAL DEX	USA	G	22JA2001	INNS
SELF-FILLETING	USA	G	03OC2005	NIHC
SERIES 767	USA	G	17JA2001	INNS
SHUR-LOK	USA	F	01AU2006	INNS
SOLUMAT FM	CTM	G	09FE2004	NIHC
STRAW-LOK	USA	G	12DE2003	INNS
STRAW-LOK	CTM	G	19DE2003	INNS
SUPER-LOK	CHIN	G	04NO2002	NIHC
SUPER-LOK	HONG	G	31OC2002	NIHC
SUPER-LOK	INDI	F	05NO2002	NIHC
SUPER-LOK	INDO	G	03DE2002	NIHC
SUPER-LOK	MAYS	G	08NO2002	NIHC
SUPER-LOK	SING	G	13NO2002	NIHC
SUPER-LOK	TAIW	G	01SE2003	NIHC
SUPER-LOK	VIET	G	14FE2001	NIHC
TAKAQUA	KORS	G	31OC2000	NIHC
UC	USA	F	05OC2006	INNS
UC	CANA	F	01NO2006	INNS
ULTRA-SET	USA	G	16JL2002	INNS
ULTRACASE	USA	G	24JA2001	INNS
VECTORPATCH	USA	G	24NO2003	INNS
VECTORSEAL	USA	G	13MR2006	INNS
VECTORSEAM	USA	G	24JE2002	INNS
VELOCITY	CANA	F	05DE2007	NIHC
VERSA-WELD	CANA	G	06AP2002	NIHC
XINK	USA	F	04JA2007	INNS
XINK	ARGE	F	14MY2007	INNS

XINK	ARGE	F	14MY2007	INNS
XINK	ARGE	F	05FE2008	INNS
XINK	BRAZ	F	13AP2007	INNS
XINK	BRAZ	F	13AP2007	INNS
XINK	CANA	F	29NO2005	INNS
XINK	CHIN	F	09JA2007	INNS
XINK	CHIN	F	09JA2007	INNS
XINK	CTM	F	10JA2007	INNS
XINK	JAPA	F	09JA2007	INNS
XINK	MEXI	G	08JA2007	INNS
XINK	MEXI	F	08JA2007	INNS

Current owner key:

INNS:	Indopco, Inc.
NIHC:	National Starch & Chemical Investment Holding Corporation

EXECUTION:

SIGNED by
Thomas Gerd Kuehn

Dr Boris Tasche
for and on behalf of HENKEL KGaA:

SIGNED by M.C. Dekker

duly authorised for and on behalf of
NATIONAL STARCH AND
CHEMICAL INVESTMENT
HOLDING CORPORATION:

SIGNED by S. HUYBEN

duly authorised for and on behalf of
INDOPCO, INC.: